

8-Bit

SAL-XC866

8-Bit Single-Chip Microcontroller

Data Sheet

V1.1 2012-12

Microcontrollers

Edition 2012-12

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8-Bit

SAL-XC866

8-Bit Single-Chip Microcontroller

Data Sheet

V1.1 2012-12

SAL-XC866 Data Sheet**Revision History: 2012-12**

V1.1

Previous Version: V1.0 2011-02

| Page | Subjects (major changes since last revision) |
|------|--|
| - | Removed the "preliminary" wording from the data sheet. |
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1 Summary of Features

- High-performance XC800 Core
 - compatible with standard 8051 processor
 - two clocks per machine cycle architecture (for memory access without wait state)
 - two data pointers
- On-chip memory
 - 8 Kbytes of Boot ROM
 - 256 bytes of RAM
 - 512 bytes of XRAM
 - 4/8/16 Kbytes of Flash
(includes memory protection strategy)
- I/O port supply at 3.3 V/5.0 V and core logic supply at 2.5 V (generated by embedded voltage regulator)

(further features are on next page)

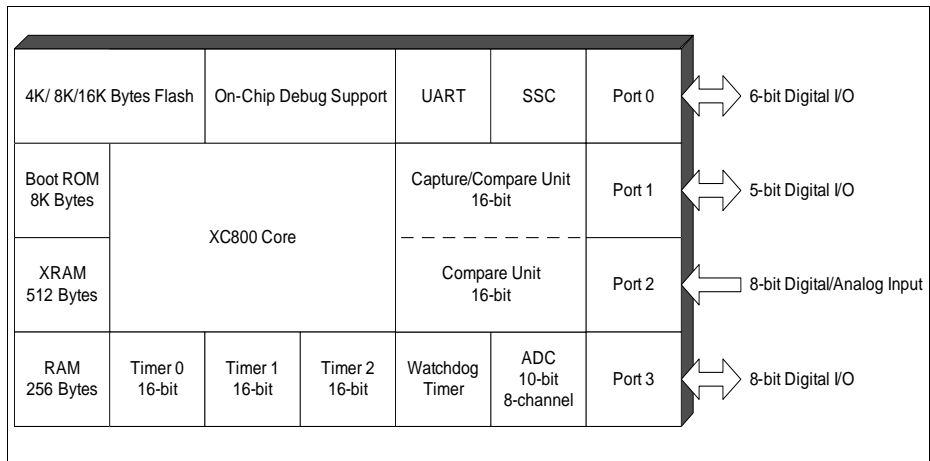


Figure 1 SAL-XC866 Functional Units

Summary of Features

Features (continued):

- Reset generation
 - Power-On reset
 - Hardware reset
 - Brownout reset for core logic supply
 - Watchdog timer reset
 - Power-Down Wake-up reset
- On-chip OSC and PLL for clock generation
 - PLL loss-of-lock detection
- Power saving modes
 - slow-down mode
 - idle mode
 - power-down mode with wake-up capability via RXD or EXINT0
 - clock gating control to each peripheral
- Programmable 16-bit Watchdog Timer (WDT)
- Four ports
 - 19 pins as digital I/O
 - 8 pins as digital/analog input
- 8-channel, 10-bit ADC
- Three 16-bit timers
 - Timer 0 and Timer 1 (T0 and T1)
 - Timer 2
- Capture/compare unit for PWM signal generation (CCU6)
- Full-duplex serial interface (UART)
- Synchronous serial channel (SSC)
- On-chip debug support
 - 1 Kbyte of monitor ROM (part of the 8-Kbyte Boot ROM)
 - 64 bytes of monitor RAM
- PG-TSSOP-38 pin package
- Temperature range T_A :
 - SAL (-40 to 150 °C)

Summary of Features
SAL-XC866 Variant Devices

The SAL-XC866 product family features devices with different configurations and program memory sizes, offering cost-effective solution for different application requirements.

The list of SAL-XC866 devices and their differences are summarized in [Table 1](#).

Table 1 Device Summary

| Device Type | Device Name | Power Supply (V) | P-Flash Size (Kbytes) | D-Flash Size (Kbytes) | LIN BSL Support |
|---------------------|-----------------|------------------|-----------------------|-----------------------|-----------------|
| Flash ¹⁾ | SAL-XC866L-4FRA | 5.0 | 12 | 4 | Yes |
| | SAL-XC866L-2FRA | 5.0 | 4 | 4 | Yes |
| | SAL-XC866L-4FRA | 3.3 | 12 | 4 | Yes |
| | SAL-XC866L-2FRA | 3.3 | 4 | 4 | Yes |

¹⁾ The flash memory (P-Flash and D-Flash) can be used for code or data.

Ordering Information

The ordering code for Infineon Technologies microcontrollers provides an exact reference to the required product. This ordering code identifies:

- The derivative itself, i.e. its function set, the temperature range, and the supply voltage
- the package and the type of delivery

For the available ordering codes for the SAL-XC866, please refer to your responsible sales representative or your local distributor.

As this document refers to all the derivatives, some descriptions may not apply to a specific product. For simplicity all versions are referred to by the term SAL-XC866 throughout this document.

2 General Device Information

2.1 Block Diagram

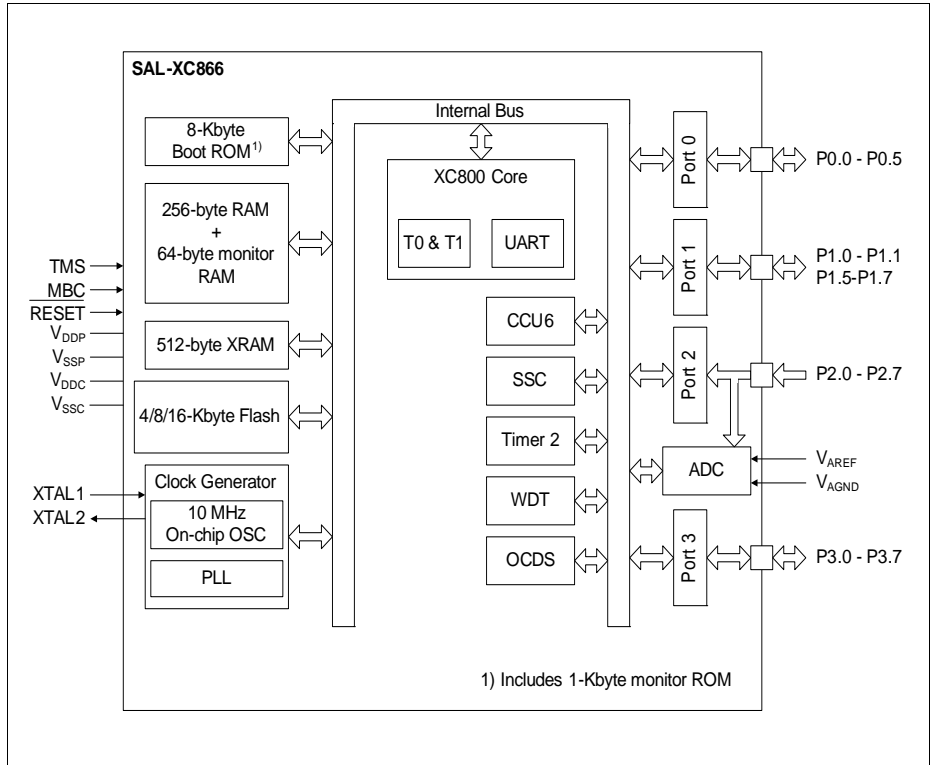


Figure 2 SAL-XC866 Block Diagram

2.2 Logic Symbol

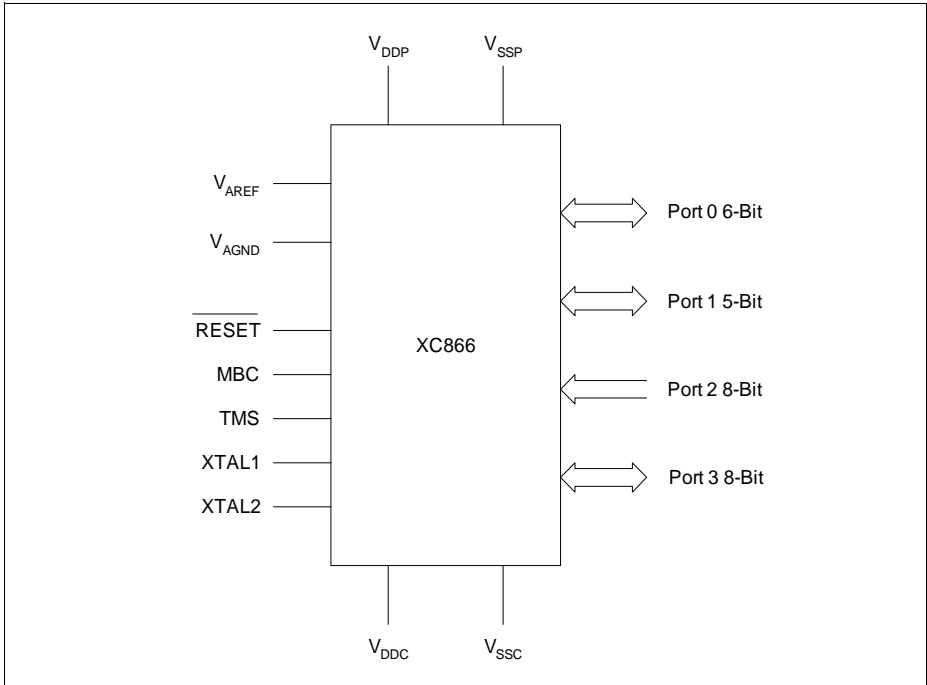


Figure 3 SAL-XC866 Logic Symbol

2.3 Pin Configuration

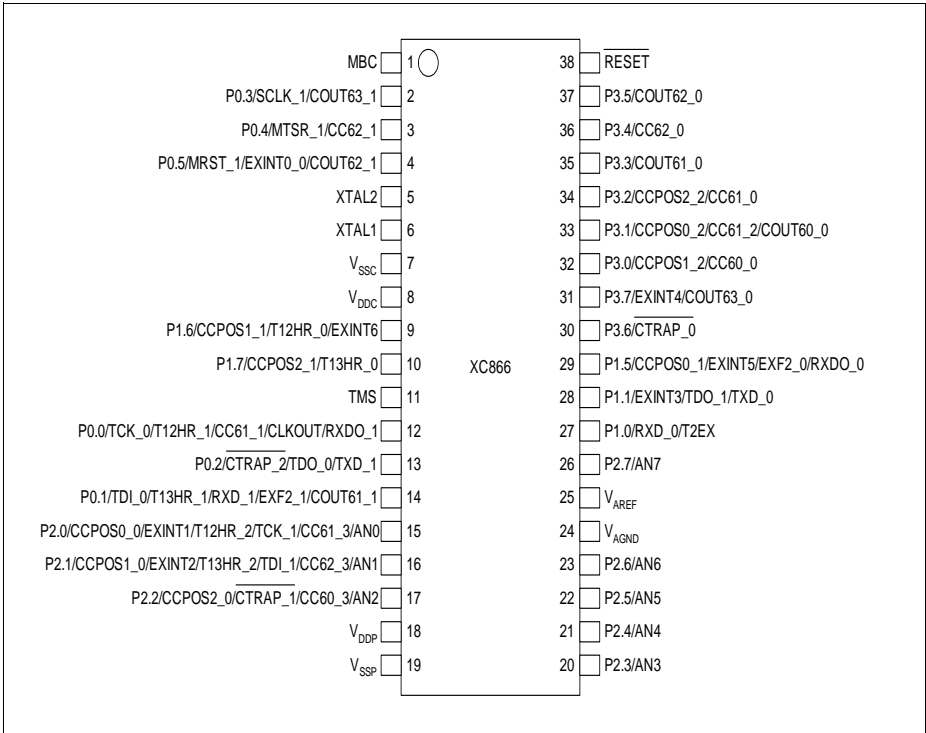


Figure 4 SAL-XC866 Pin Configuration, PG-TSSOP-38 Package (top view)

2.4 Pin Definitions and Functions

Table 2 Pin Definitions and Functions

| Symbol | Pin Number | Type | Reset State | Function |
|-----------|------------|------|-------------|--|
| P0 | | I/O | | Port 0 Port 0 is a 6-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, and the SSC. |
| P0.0 | 12 | | Hi-Z | TCK_0 JTAG Clock Input T12HR_1 CCU6 Timer 12 Hardware Run Input CC61_1 Input/Output of Capture/Compare channel 1 CLKOUT Clock Output RXDO_1 UART Transmit Data Output |
| P0.1 | 14 | | Hi-Z | TDI_0 JTAG Serial Data Input T13HR_1 CCU6 Timer 13 Hardware Run Input RXD_1 UART Receive Data Input COUT61_1 Output of Capture/Compare channel 1 EXF2_1 Timer 2 External Flag Output |
| P0.2 | 13 | | PU | CTRAP_2 CCU6 Trap Input TDO_0 JTAG Serial Data Output TXD_1 UART Transmit Data Output/ Clock Output |
| P0.3 | 2 | | Hi-Z | SCK_1 SSC Clock Input/Output COUT63_1 Output of Capture/Compare channel 3 |
| P0.4 | 3 | | Hi-Z | MTSR_1 SSC Master Transmit Output/ Slave Receive Input CC62_1 Input/Output of Capture/Compare channel 2 |
| P0.5 | 4 | | Hi-Z | MRST_1 SSC Master Receive Input/ Slave Transmit Output EXINT0_0 External Interrupt Input 0 COUT62_1 Output of Capture/Compare channel 2 |

General Device Information

Table 2 Pin Definitions and Functions (cont'd)

| Symbol | Pin Number | Type | Reset State | Function |
|-----------|------------|------|-------------|--|
| P1 | | I/O | | Port 1 Port 1 is a 5-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, and the SSC. |
| P1.0 | 27 | | PU | RXD_0 UART Receive Data Input T2EX Timer 2 External Trigger Input |
| P1.1 | 28 | | PU | EXINT3 External Interrupt Input 3 TDO_1 JTAG Serial Data Output TXD_0 UART Transmit Data Output/ Clock Output |
| P1.5 | 29 | | PU | CCPOS0_1 CCU6 Hall Input 0 EXINT5 External Interrupt Input 5 EXF2_0 Timer 2 External Flag Output RXDO_0 UART Transmit Data Output |
| P1.6 | 9 | | PU | CCPOS1_1 CCU6 Hall Input 1 T12HR_0 CCU6 Timer 12 Hardware Run Input EXINT6 External Interrupt Input 6 |
| P1.7 | 10 | | PU | CCPOS2_1 CCU6 Hall Input 2 T13HR_0 CCU6 Timer 13 Hardware Run Input P1.5 and P1.6 can be used as a software chip select output for the SSC. |

General Device Information

Table 2 Pin Definitions and Functions (cont'd)

| Symbol | Pin Number | Type | Reset State | Function |
|-----------|------------|------|-------------|--|
| P2 | | I | | Port 2 Port 2 is an 8-bit general purpose input-only port. It can be used as alternate functions for the digital inputs of the JTAG and CCU6. It is also used as the analog inputs for the ADC. |
| P2.0 | 15 | | Hi-Z | CCPOS0_0 CCU6 Hall Input 0 EXINT1 External Interrupt Input 1 T12HR_2 CCU6 Timer 12 Hardware Run Input TCK_1 JTAG Clock Input CC61_3 Input of Capture/Compare channel 1 AN0 Analog Input 0 |
| P2.1 | 16 | | Hi-Z | CCPOS1_0 CCU6 Hall Input 1 EXINT2 External Interrupt Input 2 T13HR_2 CCU6 Timer 13 Hardware Run Input TDI_1 JTAG Serial Data Input CC62_3 Input of Capture/Compare channel 2 AN1 Analog Input 1 |
| P2.2 | 17 | | Hi-Z | CCPOS2_0 CCU6 Hall Input 2 CTRAP_1 CCU6 Trap Input CC60_3 Input of Capture/Compare channel 0 AN2 Analog Input 2 |
| P2.3 | 20 | | Hi-Z | AN3 Analog Input 3 |
| P2.4 | 21 | | Hi-Z | AN4 Analog Input 4 |
| P2.5 | 22 | | Hi-Z | AN5 Analog Input 5 |
| P2.6 | 23 | | Hi-Z | AN6 Analog Input 6 |
| P2.7 | 26 | | Hi-Z | AN7 Analog Input 7 |

General Device Information

Table 2 Pin Definitions and Functions (cont'd)

| Symbol | Pin Number | Type | Reset State | Function |
|-----------|------------|------|-------------|--|
| P3 | | I | | Port 3 Port 3 is a bidirectional general purpose I/O port. It can be used as alternate functions for the CCU6. |
| P3.0 | 32 | | Hi-Z | CCPOS1_2 CCU6 Hall Input 1 CC60_0 Input/Output of Capture/Compare channel 0 |
| P3.1 | 33 | | Hi-Z | CCPOS0_2 CCU6 Hall Input 0 CC61_2 Input/Output of Capture/Compare channel 1 COUT60_0 Output of Capture/Compare channel 0 |
| P3.2 | 34 | | Hi-Z | CCPOS2_2 CCU6 Hall Input 2 CC61_0 Input/Output of Capture/Compare channel 1 |
| P3.3 | 35 | | Hi-Z | COUT61_0 Output of Capture/Compare channel 1 |
| P3.4 | 36 | | Hi-Z | CC62_0 Input/Output of Capture/Compare channel 2 |
| P3.5 | 37 | | Hi-Z | COUT62_0 Output of Capture/Compare channel 2 |
| P3.6 | 30 | | PD | <u>CTRAP_0</u> CCU6 Trap Input |
| P3.7 | 31 | | Hi-Z | EXINT4 External Interrupt Input 4 COUT63_0 Output of Capture/Compare channel 3 |

Table 2 Pin Definitions and Functions (cont'd)

| Symbol | Pin Number | Type | Reset State | Function |
|-------------------------|------------|------|-------------|---|
| V_{DDP} | 18 | – | – | I/O Port Supply (3.3 V/5.0 V) Also used by EVR and analog modules. |
| V_{SSP} | 19 | – | – | I/O Port Ground |
| V_{DDC} | 8 | – | – | Core Supply Monitor (2.5 V) |
| V_{SSC} | 7 | – | – | Core Supply Ground |
| V_{AREF} | 25 | – | – | ADC Reference Voltage |
| V_{AGND} | 24 | – | – | ADC Reference Ground |
| XTAL1 | 6 | I | Hi-Z | External Oscillator Input (NC if not needed) |
| XTAL2 | 5 | O | Hi-Z | External Oscillator Output (NC if not needed) |
| TMS | 11 | I | PD | Test Mode Select |
| RESET | 38 | I | PU | Reset Input |
| MBC¹⁾ | 1 | I | PU | Monitor & BootStrap Loader Control |

¹⁾ An external pull-up device in the range of 4.7 k Ω to 100 k Ω is required to enter user mode. Alternatively MBC can be tied to high if alternate functions (for debugging) of the pin are not utilized.

3 Functional Description

3.1 Processor Architecture

The SAL-XC866 is based on a high-performance 8-bit Central Processing Unit (CPU) that is compatible with the standard 8051 processor. While the standard 8051 processor is designed around a 12-clock machine cycle, the SAL-XC866 CPU uses a 2-clock machine cycle. This allows fast access to ROM or RAM memories without wait state. Access to the Flash memory, however, requires an additional wait state (one machine cycle). The instruction set consists of 45% one-byte, 41% two-byte and 14% three-byte instructions.

The SAL-XC866 CPU provides a range of debugging features, including basic stop/start, single-step execution, breakpoint support and read/write access to the data memory, program memory and SFRs. **Figure 5** shows the CPU functional blocks.

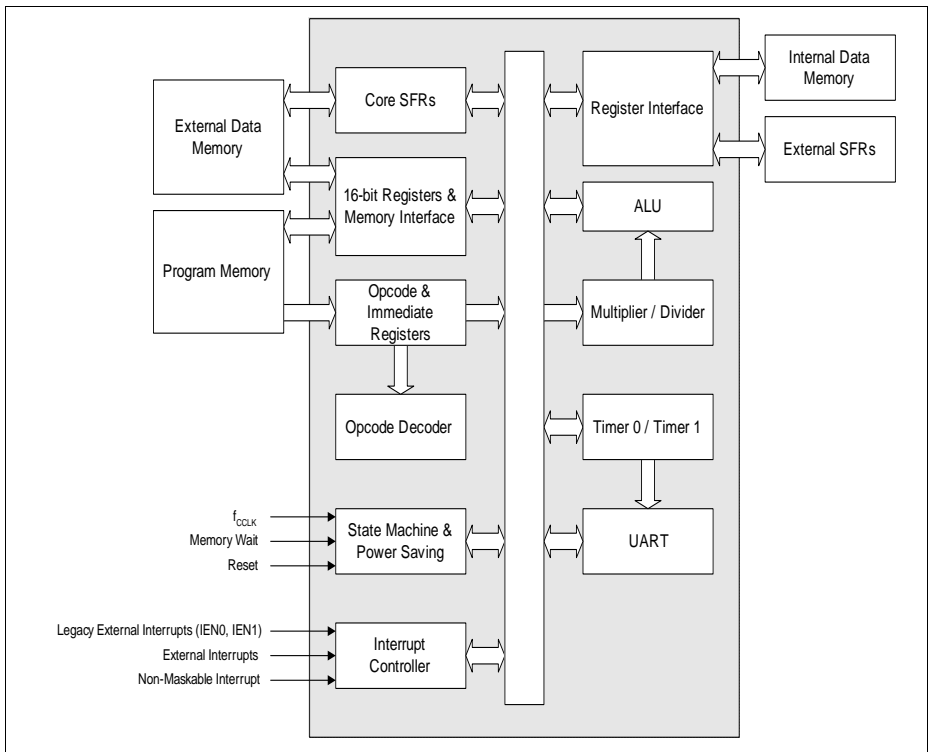


Figure 5 CPU Block Diagram

3.2 Memory Organization

The SAL-XC866 CPU operates in the following five address spaces:

- 8 Kbytes of Boot ROM program memory
- 256 bytes of internal RAM data memory
- 512 bytes of XRAM memory
- a 128-byte Special Function Register area
- 4/8/16 Kbytes of Flash program memory

Functional Description

Figure 6 illustrates the memory address spaces of the SAL-XC866-4FR devices.

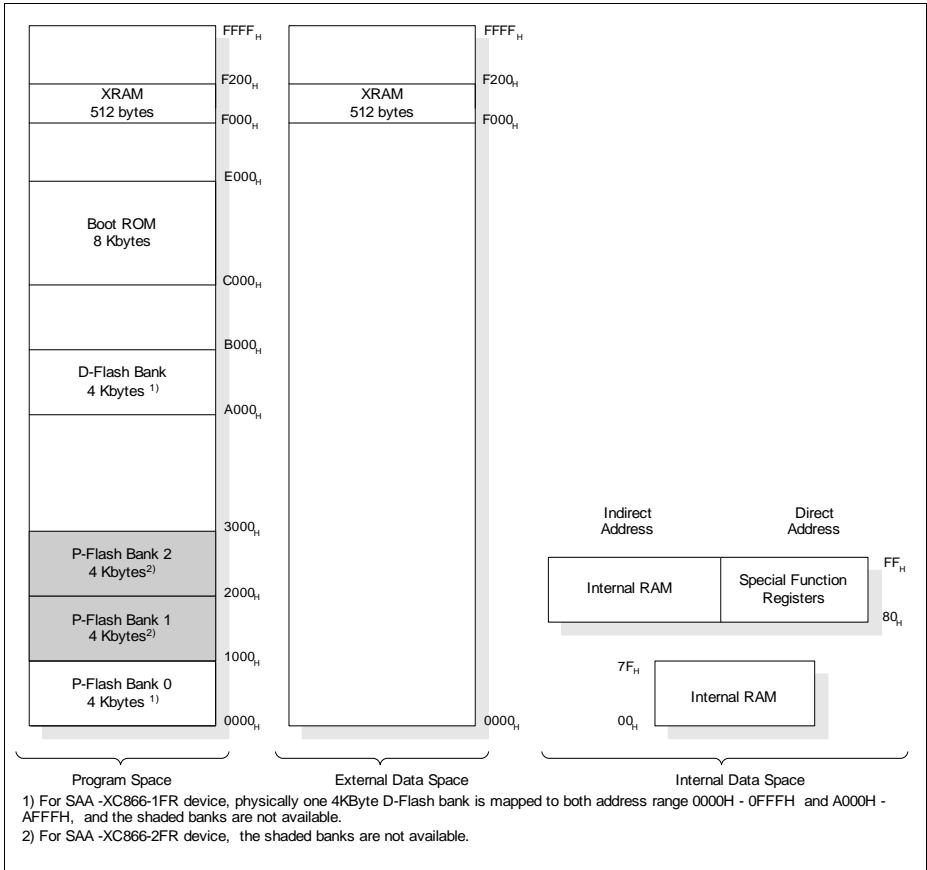


Figure 6 Memory Map of SAL-XC866 Flash Devices

3.2.1 Memory Protection Strategy

The SAL-XC866 memory protection strategy includes:

- Read-out protection: The Flash Memory can be enabled for read-out protection and ROM memory is always protected.
- Program and erase protection: The Flash memory in all devices can be enabled for program and erase protection.

Flash memory protection is available in two modes:

- Mode 0: Only the P-Flash is protected; the D-Flash is unprotected
- Mode 1: Both the P-Flash and D-Flash are protected

The selection of each protection mode and the restrictions imposed are summarized in [Table 3](#).

Table 3 Flash Protection Modes

| Mode | 0 | 1 |
|--|---|---|
| Activation | Program a valid password via BSL mode 6 | |
| Selection | MSB of password = 0 | MSB of password = 1 |
| P-Flash contents can be read by | Read instructions in the P-Flash | Read instructions in the P-Flash or D-Flash |
| P-Flash program and erase | Not possible | Not possible |
| D-Flash contents can be read by | Read instructions in any program memory | Read instructions in the P-Flash or D-Flash |
| D-Flash program | Possible | Not possible |
| D-Flash erase | Possible, on the condition that bit DFLASHEN in register MISC_CON is set to 1 prior to each erase operation | Not possible |

BSL mode 6, which is used for enabling Flash protection, can also be used for disabling Flash protection. Here, the programmed password must be provided by the user. A password match triggers an automatic erase of the read-protected Flash contents, see [Table 4](#), and the programmed password is erased. The Flash protection is then disabled upon the next reset.

For XC866-2FR and XC866-4FR devices:

The selection of protection type is summarized in [Table 4](#).

Table 4 Flash Protection Type for XC866-2FR and XC866-4FR devices

| PASSWORD | Type of Protection | Flash Banks to Erase when Unprotected |
|------------------------|---------------------------|--|
| 1XXXXXXXX _B | Flash Protection Mode 1 | All Banks |
| 0XXXXXXXX _B | Flash Protection Mode 0 | P-Flash Bank |

Although no protection scheme can be considered infallible, the SAL-XC866 memory protection strategy provides a very high level of protection for a general purpose microcontroller.

3.2.2 Special Function Register

The Special Function Registers (SFRs) occupy direct internal data memory space in the range 80_H to FF_H. All registers, except the program counter, reside in the SFR area. The SFRs include pointers and registers that provide an interface between the CPU and the on-chip peripherals. As the 128-SFR range is less than the total number of registers required, address extension mechanisms are required to increase the number of addressable SFRs. The address extension mechanisms include:

- Mapping
- Paging

3.2.2.1 Address Extension by Mapping

Address extension is performed at the system level by mapping. The SFR area is extended into two portions: the standard (non-mapped) SFR area and the mapped SFR area. Each portion supports the same address range 80_H to FF_H, bringing the number of addressable SFRs to 256. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit RMAP in the system control register SYSCON0 at address 8F_H. To access SFRs in the mapped area, bit RMAP in SFR SYSCON0 must be set. Alternatively, the SFRs in the standard area can be accessed by clearing bit RMAP. The SFR area can be selected as shown in [Figure 7](#).

SYSCON0

System Control Register 0

Reset Value: 00_H

| | | | | | | | |
|---|---|---|---|---|----|---|------|
| 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| 0 | | | | | 1 | 0 | RMAP |
| r | | | | | rw | r | rw |

| Field | Bits | Type | Description |
|-------|---------|------|--|
| RMAP | 0 | rw | Special Function Register Map Control 0 The access to the standard SFR area is enabled. 1 The access to the mapped SFR area is enabled. |
| 1 | 2 | rw | Reserved Returns the last value if read; should be written with 1. |
| 0 | 1,[7:3] | r | Reserved Returns 0 if read; should be written with 0. |

Functional Description

Note: The RMAP bit must be cleared/set by ANL or ORL instructions. The rest bits of SYSCON0 should not be modified.

As long as bit RMAP is set, the mapped SFR area can be accessed. This bit is not cleared automatically by hardware. Thus, before standard/mapped registers are accessed, bit RMAP must be cleared/set, respectively, by software.

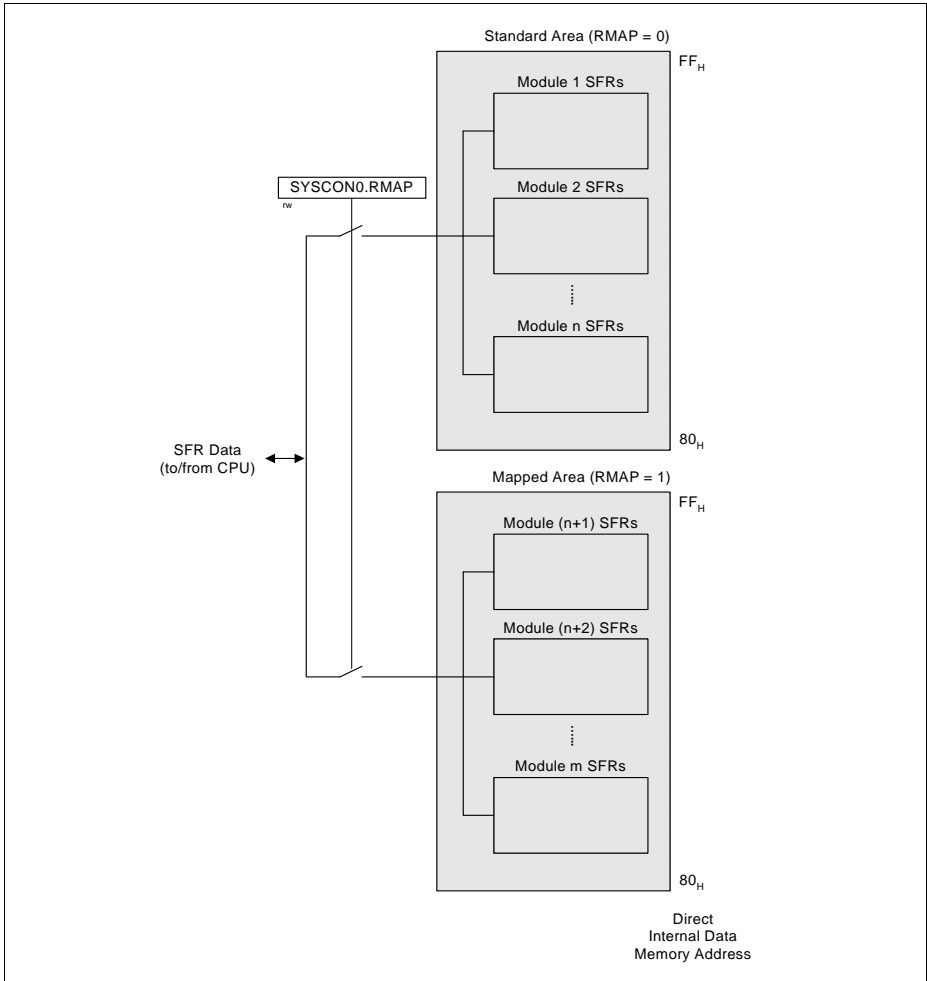


Figure 7 Address Extension by Mapping

3.2.2.2 Address Extension by Paging

Address extension is further performed at the module level by paging. With the address extension by mapping, the SAL-XC866 has a 256-SFR address range. However, this is still less than the total number of SFRs needed by the on-chip peripherals. To meet this requirement, some peripherals have a built-in local address extension mechanism for increasing the number of addressable SFRs. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit field PAGE in the module page register MOD_PAGE. Hence, the bit field PAGE must be programmed before accessing the SFR of the target module. Each module may contain a different number of pages and a different number of SFRs per page, depending on the specific requirement. Besides setting the correct RMAP bit value to select the SFR area, the user must also ensure that a valid PAGE is selected to target the desired SFR. A page inside the extended address range can be selected as shown in **Figure 8**.

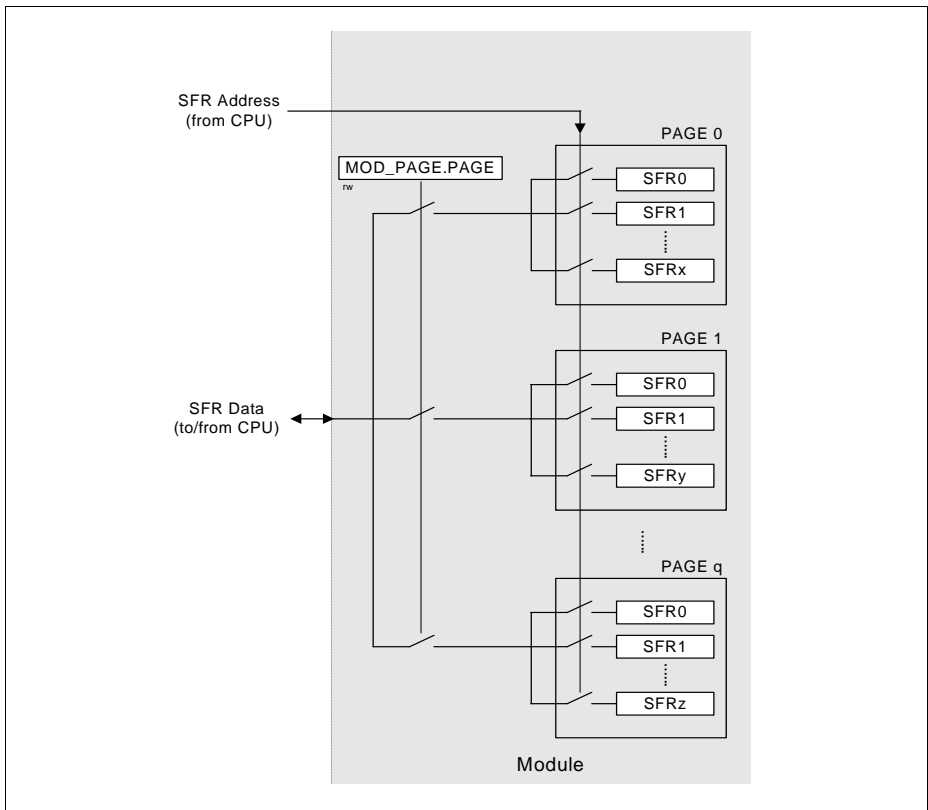


Figure 8 Address Extension by Paging

Functional Description

In order to access a register located in a page different from the actual one, the current page must be left. This is done by reprogramming the bit field PAGE in the page register. Only then can the desired access be performed.

If an interrupt routine is initiated between the page register access and the module register access, and the interrupt needs to access a register located in another page, the current page setting can be saved, the new one programmed and finally, the old page setting restored. This is possible with the storage fields MOD_STx (x = 0 - 3) for the save and restore action of the current page setting. By indicating which storage bit field should be used in parallel with the new page value, a single write operation can:

- Save the contents of PAGE in MOD_STx before overwriting with the new value (this is done in the beginning of the interrupt routine to save the current page setting and program the new page number); or
- Overwrite the contents of PAGE with the contents of MOD_STx, ignoring the value written to the bit positions of PAGE (this is done at the end of the interrupt routine to restore the previous page setting before the interrupt occurred)

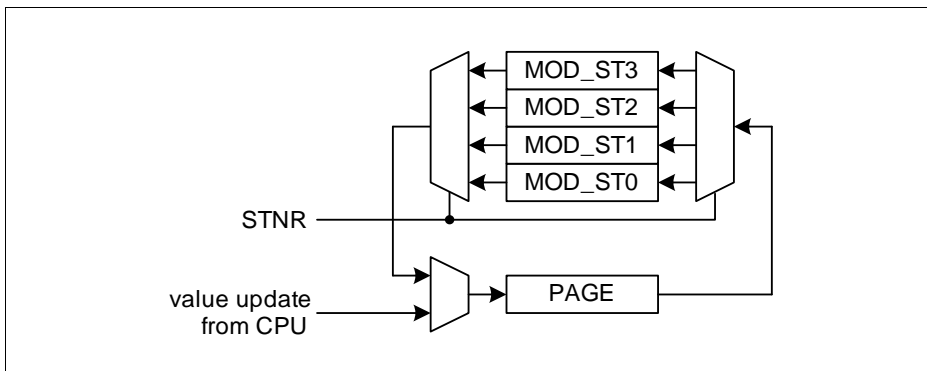


Figure 9 Storage Elements for Paging

With this mechanism, a certain number of interrupt routines (or other routines) can perform page changes without reading and storing the previously used page information. The use of only write operations makes the system simpler and faster. Consequently, this mechanism significantly improves the performance of short interrupt routines.

The SAL-XC866 supports local address extension for:

- Parallel Ports
- Analog-to-Digital Converter (ADC)
- Capture/Compare Unit 6 (CCU6)
- System Control Registers

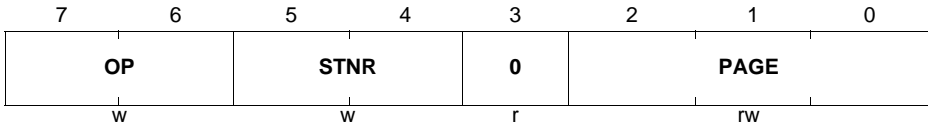
Functional Description

The page register has the following definition:

MOD_PAGE

Page Register for module MOD

Reset Value: 00_H



| Field | Bits | Type | Description |
|-------------|-------|------|---|
| PAGE | [2:0] | rw | <p>Page Bits</p> <p>When written, the value indicates the new page. When read, the value indicates the currently active page.</p> |
| STNR | [5:4] | w | <p>Storage Number</p> <p>This number indicates which storage bit field is the target of the operation defined by bit field OP. If OP = 10_B, the contents of PAGE are saved in MOD_STx before being overwritten with the new value. If OP = 11_B, the contents of PAGE are overwritten by the contents of MOD_STx. The value written to the bit positions of PAGE is ignored.</p> <p>00 MOD_ST0 is selected. 01 MOD_ST1 is selected. 10 MOD_ST2 is selected. 11 MOD_ST3 is selected.</p> |

Functional Description

| Field | Bits | Type | Description |
|-----------|-------|------|---|
| OP | [7:6] | w | <p>Operation</p> <p>0X Manual page mode. The value of STNR is ignored and PAGE is directly written.</p> <p>10 New page programming with automatic page saving. The value written to the bit positions of PAGE is stored. In parallel, the previous contents of PAGE are saved in the storage bit field MOD_STx indicated by STNR.</p> <p>11 Automatic restore page action. The value written to the bit positions PAGE is ignored and instead, PAGE is overwritten by the contents of the storage bit field MOD_STx indicated by STNR.</p> |
| 0 | 3 | r | <p>Reserved</p> <p>Returns 0 if read; should be written with 0.</p> |

Functional Description

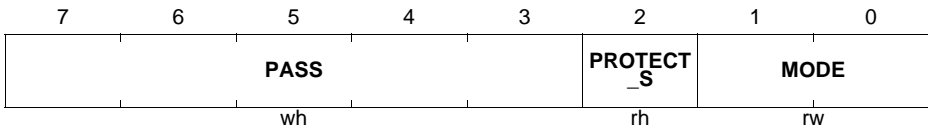
3.2.3 Bit Protection Scheme

The bit protection scheme prevents direct software writing of selected bits (i.e., protected bits) using the PASSWD register. When the bit field MODE is 11_B, writing 10011_B to the bit field PASS opens access to writing of all protected bits, and writing 10101_B to the bit field PASS closes access to writing of all protected bits. Note that access is opened for maximum 32 CCLKs if the “close access” password is not written. If “open access” password is written again before the end of 32 CCLK cycles, there will be a recount of 32 CCLK cycles. The protected bits include NDIV, WDTEN, PD, and SD.

PASSWD

Password Register

Reset Value: 07_H



| Field | Bits | Type | Description |
|------------------|-------|------|--|
| MODE | [1:0] | rw | <p>Bit Protection Scheme Control bits</p> <p>00 Scheme Disabled 11 Scheme Enabled (default) Others: Scheme Enabled</p> <p>These two bits cannot be written directly. To change the value between 11_B and 00_B, the bit field PASS must be written with 11000_B; only then, will the MODE[1:0] be registered.</p> |
| PROTECT_S | 2 | rh | <p>Bit Protection Signal Status bit</p> <p>This bit shows the status of the protection.</p> <p>0 Software is able to write to all protected bits. 1 Software is unable to write to any protected bits.</p> |
| PASS | [7:3] | wh | <p>Password bits</p> <p>The Bit Protection Scheme only recognizes three patterns.</p> <p>11000_B Enables writing of the bit field MODE. 10011_B Opens access to writing of all protected bits. 10101_B Closes access to writing of all protected bits.</p> |

3.2.4 SAL-XC866 Register Overview

The SFRs of the SAL-XC866 are organized into groups according to their functional units. The contents (bits) of the SFRs are summarized in **Table 5** to **Table 13**, with the addresses of the bitaddressable SFRs appearing in bold typeface.

The CPU SFRs can be accessed in both the standard and mapped memory areas (RMAP = 0 or 1).

Table 5 CPU Register Overview

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|--|------------------------|-----------|-------|-------|-------|-------|------|------|-------|
| RMAP = 0 or 1 | | | | | | | | | | |
| 81 _H | SP Stack Pointer Register | Reset: 07 _H | Bit Field | | SP | | | | | |
| | | | Type | | rw | | | | | |
| 82 _H | DPL Data Pointer Register Low | Reset: 00 _H | DPL7 | DPL6 | DPL5 | DPL4 | DPL3 | DPL2 | DPL1 | DPL0 |
| | | | rw | rw | rw | rw | rw | rw | rw | rw |
| 83 _H | DPH Data Pointer Register High | Reset: 00 _H | DPH7 | DPH6 | DPH5 | DPH4 | DPH3 | DPH2 | DPH1 | DPH0 |
| | | | rw | rw | rw | rw | rw | rw | rw | rw |
| 87 _H | PCON Power Control Register | Reset: 00 _H | SMOD | 0 | | | GF1 | GF0 | 0 | IDLE |
| | | | rw | r | | | rw | rw | r | rw |
| 88 _H | TCON Timer Control Register | Reset: 00 _H | TF1 | TR1 | TF0 | TR0 | IE1 | IT1 | IE0 | IT0 |
| | | | rwh | rw | rwh | rw | rw | rw | rwh | rw |
| 89 _H | TMOD Timer Mode Register | Reset: 00 _H | GATE1 | 0 | T1M | | GATE0 | 0 | T0M | |
| | | | rw | r | rw | | rw | r | rw | |
| 8A _H | TL0 Timer 0 Register Low | Reset: 00 _H | Bit Field | | VAL | | | | | |
| | | | Type | | rwh | | | | | |
| 8B _H | TL1 Timer 1 Register Low | Reset: 00 _H | Bit Field | | VAL | | | | | |
| | | | Type | | rwh | | | | | |
| 8C _H | TH0 Timer 0 Register High | Reset: 00 _H | Bit Field | | VAL | | | | | |
| | | | Type | | rwh | | | | | |
| 8D _H | TH1 Timer 1 Register High | Reset: 00 _H | Bit Field | | VAL | | | | | |
| | | | Type | | rwh | | | | | |
| 98 _H | SCON Serial Channel Control Register | Reset: 00 _H | SM0 | SM1 | SM2 | REN | TB8 | RB8 | TI | RI |
| | | | rw | rw | rw | rw | rw | rwh | rwh | rwh |
| 99 _H | SBUF Serial Data Buffer Register | Reset: 00 _H | Bit Field | | VAL | | | | | |
| | | | Type | | rwh | | | | | |
| A2 _H | EO Extended Operation Register | Reset: 00 _H | 0 | | | TRAP_ | 0 | | | DPSEL |
| | | | r | | | rw | r | | | rw |
| A8 _H | IEN0 Interrupt Enable Register 0 | Reset: 00 _H | EA | 0 | ET2 | ES | ET1 | EX1 | ET0 | EX0 |
| | | | rw | r | rw | rw | rw | rw | rw | rw |
| B8 _H | IP Interrupt Priority Register | Reset: 00 _H | 0 | | PT2 | PS | PT1 | PX1 | PT0 | PX0 |
| | | | r | | rw | rw | rw | rw | rw | rw |
| B9 _H | IPH Interrupt Priority Register High | Reset: 00 _H | 0 | | PT2H | PSH | PT1H | PX1H | PT0H | PX0H |
| | | | r | | rw | rw | rw | rw | rw | rw |
| D0 _H | PSW Program Status Word Register | Reset: 00 _H | CY | AC | F0 | RS1 | RS0 | OV | F1 | P |
| | | | rw | rwh | rwh | rw | rw | rwh | rwh | rh |
| E0 _H | ACC Accumulator Register | Reset: 00 _H | ACC7 | ACC6 | ACC5 | ACC4 | ACC3 | ACC2 | ACC1 | ACC0 |
| | | | rw | rw | rw | rw | rw | rw | rw | rw |
| E8 _H | IEN1 Interrupt Enable Register 1 | Reset: 00 _H | ECCIP | ECCIP | ECCIP | ECCIP | EXM | EX2 | ESSC | EADC |
| | | | 3 | 2 | 1 | 0 | rw | rw | rw | rw |
| | | | rw | rw | rw | rw | rw | rw | rw | rw |

Functional Description
Table 5 CPU Register Overview (cont'd)

| Addr | Register Name | Reset: | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|---|------------------------|-----------|-------------|-------------|-------------|-------------|------|------|-------|-----------|
| F0 _H | B B Register | Reset: 00 _H | Bit Field | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |
| F8 _H | IP1 Interrupt Priority Register 1 | Reset: 00 _H | Bit Field | PCCIP 3 | PCCIP 2 | PCCIP 1 | PCCIP 0 | PXM | PX2 | PSSC | PADC |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |
| F9 _H | IPH1 Interrupt Priority Register 1 High | Reset: 00 _H | Bit Field | PCCIP 3H | PCCIP 2H | PCCIP 1H | PCCIP 0H | PXMH | PX2H | PSSCH | PADC H |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |

The system control SFRs can be accessed in the standard memory area (RMAP = 0).

Table 6 System Control Register Overview

| Addr | Register Name | Reset: | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|------------------|---|------------------------|-----------|----------|-------------|--------------|--------------|--------------|---------------|--------------|-------------|
| RMAP = 0 or 1 | | | | | | | | | | | |
| 8F _H | SYSCON0 System Control Register 0 | Reset: 00 _H | Bit Field | 0 | | | | | | | RMAP |
| | | | Type | r | | | | | | | rw |
| RMAP = 0 | | | | | | | | | | | |
| BF _H | SCU_PAGE Page Register for System Control | Reset: 00 _H | Bit Field | OP | | STNR | | 0 | PAGE | | |
| | | | Type | w | | w | | r | rwh | | |
| RMAP = 0, Page 0 | | | | | | | | | | | |
| B3 _H | MODISEL Peripheral Input Select Register | Reset: 00 _H | Bit Field | 0 | | JTAG TDIS | JTAG TCKS | 0 | | EXINT 0IS | URRIS |
| | | | Type | r | | rw | rw | r | | rw | rw |
| B4 _H | IRCON0 Interrupt Request Register 0 | Reset: 00 _H | Bit Field | 0 | EXINT 6 | EXINT 5 | EXINT 4 | EXINT 3 | EXINT 2 | EXINT 1 | EXINT 0 |
| | | | Type | r | rwh | rwh | rwh | rwh | rwh | rwh | rwh |
| B5 _H | IRCON1 Interrupt Request Register 1 | Reset: 00 _H | Bit Field | 0 | | | ADCS RC1 | ADCS RC0 | RIR | TIR | EIR |
| | | | Type | r | | | rwh | rwh | rwh | rwh | rwh |
| B7 _H | EXICON0 External Interrupt Control Register 0 | Reset: 00 _H | Bit Field | EXINT3 | | EXINT2 | | EXINT1 | | EXINT0 | |
| | | | Type | rw | | rw | | rw | | rw | |
| BA _H | EXICON1 External Interrupt Control Register 1 | Reset: 00 _H | Bit Field | 0 | | EXINT6 | | EXINT5 | | EXINT4 | |
| | | | Type | r | | rw | | rw | | rw | |
| BB _H | NMICON NMI Control Register | Reset: 00 _H | Bit Field | 0 | NMI ECC | NMI VDDP | NMI VDD | NMI OCDS | NMI FLASH | NMI PLL | NMI WDT |
| | | | Type | r | rw | rw | rw | rw | rw | rw | rw |
| BC _H | NMISR NMI Status Register | Reset: 00 _H | Bit Field | 0 | FNMI ECC | FNMI VDDP | FNMI VDD | FNMI OCDS | FNMI FLASH | FNMI PLL | FNMI WDT |
| | | | Type | r | rwh | rwh | rwh | rwh | rwh | rwh | rwh |
| BD _H | BCON Baud Rate Control Register | Reset: 00 _H | Bit Field | BGSEL | | 0 | BREN | BRPRE | | | R |
| | | | Type | rw | | r | rw | rw | | | rw |
| BE _H | BG Baud Rate Timer/Reload Register | Reset: 00 _H | Bit Field | BR_VALUE | | | | | | | |
| | | | Type | rw | | | | | | | |
| E9 _H | FDCON Fractional Divider Control Register | Reset: 00 _H | Bit Field | BGS | SYNEN | ERRSY N | EOFSY N | BRK | NDOV | FDM | FDEN |
| | | | Type | rw | rw | rwh | rwh | rw | rw | rw | rw |
| EA _H | FDSTEP Fractional Divider Reload Register | Reset: 00 _H | Bit Field | STEP | | | | | | | |
| | | | Type | rw | | | | | | | |
| EB _H | FDRES Fractional Divider Result Register | Reset: 00 _H | Bit Field | RESULT | | | | | | | |
| | | | Type | rh | | | | | | | |
| RMAP = 0, Page 1 | | | | | | | | | | | |

Functional Description
Table 6 System Control Register Overview (cont'd)

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 | |
|------------------|--|-----------|------------------|------------|----------|-----------|------------|---------------|-------------|-------------|--------------|
| B3 _H | ID Identity Register Reset: 01 _H | Bit Field | PRODID | | | | | VERID | | | |
| | | Type | r | | | | | r | | | |
| B4 _H | PMCON0 Power Mode Control Register 0 Reset: 00 _H | Bit Field | 0 | WDT RST | WKRS | WK SEL | SD | PD | WS | | |
| | | Type | r | rwh | rwh | rw | rw | rwh | rw | | |
| B5 _H | PMCON1 Power Mode Control Register 1 Reset: 00 _H | Bit Field | 0 | | | | T2_DIS | CCU _DIS | SSC _DIS | ADC _DIS | |
| | | Type | r | | | | rw | rw | rw | rw | |
| B6 _H | OSC_CON OSC Control Register Reset: 08 _H | Bit Field | 0 | | | OSC PD | XPD | OSC SS | ORD RES | OSCR | |
| | | Type | r | | | rw | rw | rw | rwh | rh | |
| B7 _H | PLL_CON PLL Control Register Reset: 20 _H | Bit Field | NDIV | | | | VCO BYP | OSC DISC | RESLD | LOCK | |
| | | Type | rw | | | | rw | rw | rwh | rh | |
| BA _H | CMCON Clock Control Register Reset: 00 _H | Bit Field | VCO SEL | 0 | | | CLKREL | | | | |
| | | Type | rw | r | | | rw | | | | |
| BB _H | PASSWD Password Register Reset: 07 _H | Bit Field | PASS | | | | | PROTE CT_S | MODE | | |
| | | Type | w | | | | | rh | rw | | |
| BC _H | FEAL Flash Error Address Register Low Reset: 00 _H | Bit Field | ECCERRADDR[7:0] | | | | | | | | |
| | | Type | rh | | | | | | | | |
| BD _H | FEAH Flash Error Address Register High Reset: 00 _H | Bit Field | ECCERRADDR[15:8] | | | | | | | | |
| | | Type | rh | | | | | | | | |
| BE _H | COCON Clock Output Control Register Reset: 00 _H | Bit Field | 0 | TLEN | COU S | COREL | | | | | |
| | | Type | r | rw | rw | rw | | | | | |
| E9 _H | MISC_CON Miscellaneous Control Register Reset: 00 _H | Bit Field | 0 | | | | | | | | DFLAS HEN |
| | | Type | r | | | | | | | | rwh |
| RMAP = 0, Page 3 | | | | | | | | | | | |
| B3 _H | XADDRH On-Chip XRAM Address Higher Order Reset: F0 _H | Bit Field | ADDRH | | | | | | | | |
| | | Type | rw | | | | | | | | |

The WDT SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 7 WDT Register Overview

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|--|-----------|-----------|------------|-----------|---|-----------|-----------|-----------|---|
| RMAP = 1 | | | | | | | | | | |
| BB _H | WDTCON Watchdog Timer Control Register Reset: 00 _H | Bit Field | 0 | WINB EN | WDT PR | 0 | WDT EN | WDT RS | WDT IN | |
| | | Type | r | rw | rh | r | rw | rwh | rw | |
| BC _H | WDTREL Watchdog Timer Reload Register Reset: 00 _H | Bit Field | WDTREL | | | | | | | |
| | | Type | rw | | | | | | | |
| BD _H | WDTWINB Watchdog Window-Boundary Count Register Reset: 00 _H | Bit Field | WDTWINB | | | | | | | |
| | | Type | rw | | | | | | | |
| BE _H | WDTL Watchdog Timer Register Low Reset: 00 _H | Bit Field | WDT[7:0] | | | | | | | |
| | | Type | rh | | | | | | | |
| BF _H | WDTH Watchdog Timer Register High Reset: 00 _H | Bit Field | WDT[15:8] | | | | | | | |
| | | Type | rh | | | | | | | |

Functional Description

The Port SFRs can be accessed in the standard memory area (RMAP = 0).

Table 8 Port Register Overview

| Addr | Register Name | Reset | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|------------------|--|------------------------------|-----------|-----|-----|------|-----|-----|------|-----|-----|
| RMAP = 0 | | | | | | | | | | | |
| B2 _H | PORT_PAGE Page Register for PORT | Reset: 00_H | Bit Field | OP | | STNR | | 0 | PAGE | | |
| | | | Type | w | | w | | r | rwh | | |
| RMAP = 0, Page 0 | | | | | | | | | | | |
| 80 _H | P0_DATA P0 Data Register | Reset: 00_H | Bit Field | 0 | P5 | P4 | P3 | P2 | P1 | P0 | |
| | | | Type | r | rwh | rwh | rwh | rwh | rwh | rwh | rwh |
| 86 _H | P0_DIR P0 Direction Register | Reset: 00_H | Bit Field | 0 | P5 | P4 | P3 | P2 | P1 | P0 | |
| | | | Type | r | rw | rw | rw | rw | rw | rw | rw |
| 90 _H | P1_DATA P1 Data Register | Reset: 00_H | Bit Field | P7 | P6 | P5 | 0 | | P1 | P0 | |
| | | | Type | rwh | rwh | rwh | r | | rwh | rwh | rwh |
| 91 _H | P1_DIR P1 Direction Register | Reset: 00_H | Bit Field | P7 | P6 | P5 | 0 | | P1 | P0 | |
| | | | Type | rw | rw | rw | r | | rw | rw | rw |
| A0 _H | P2_DATA P2 Data Register | Reset: 00_H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | rwh | rwh | rwh | rwh | rwh | rwh | rwh | rwh |
| A1 _H | P2_DIR P2 Direction Register | Reset: 00_H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |
| B0 _H | P3_DATA P3 Data Register | Reset: 00_H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | rwh | rwh | rwh | rwh | rwh | rwh | rwh | rwh |
| B1 _H | P3_DIR P3 Direction Register | Reset: 00_H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |
| RMAP = 0, Page 1 | | | | | | | | | | | |
| 80 _H | P0_PUDSEL P0 Pull-Up/Pull-Down Select Register | Reset: FF_H | Bit Field | 0 | P5 | P4 | P3 | P2 | P1 | P0 | |
| | | | Type | r | rw | rw | rw | rw | rw | rw | rw |
| 86 _H | P0_PUDEN P0 Pull-Up/Pull-Down Enable Register | Reset: C4_H | Bit Field | 0 | P5 | P4 | P3 | P2 | P1 | P0 | |
| | | | Type | r | rw | rw | rw | rw | rw | rw | rw |
| 90 _H | P1_PUDSEL P1 Pull-Up/Pull-Down Select Register | Reset: FF_H | Bit Field | P7 | P6 | P5 | 0 | | P1 | P0 | |
| | | | Type | rw | rw | rw | r | | rw | rw | rw |
| 91 _H | P1_PUDEN P1 Pull-Up/Pull-Down Enable Register | Reset: FF_H | Bit Field | P7 | P6 | P5 | 0 | | P1 | P0 | |
| | | | Type | rw | rw | rw | r | | rw | rw | rw |
| A0 _H | P2_PUDSEL P2 Pull-Up/Pull-Down Select Register | Reset: FF_H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |
| A1 _H | P2_PUDEN P2 Pull-Up/Pull-Down Enable Register | Reset: 00_H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |
| B0 _H | P3_PUDSEL P3 Pull-Up/Pull-Down Select Register | Reset: BF_H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |
| B1 _H | P3_PUDEN P3 Pull-Up/Pull-Down Enable Register | Reset: 40_H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |
| RMAP = 0, Page 2 | | | | | | | | | | | |
| 80 _H | P0_ALTSEL0 P0 Alternate Select 0 Register | Reset: 00_H | Bit Field | 0 | P5 | P4 | P3 | P2 | P1 | P0 | |
| | | | Type | r | rw | rw | rw | rw | rw | rw | rw |
| 86 _H | P0_ALTSEL1 P0 Alternate Select 1 Register | Reset: 00_H | Bit Field | 0 | P5 | P4 | P3 | P2 | P1 | P0 | |
| | | | Type | r | rw | rw | rw | rw | rw | rw | rw |
| 90 _H | P1_ALTSEL0 P1 Alternate Select 0 Register | Reset: 00_H | Bit Field | P7 | P6 | P5 | 0 | | P1 | P0 | |
| | | | Type | rw | rw | rw | r | | rw | rw | rw |
| 91 _H | P1_ALTSEL1 P1 Alternate Select 1 Register | Reset: 00_H | Bit Field | P7 | P6 | P5 | 0 | | P1 | P0 | |
| | | | Type | rw | rw | rw | r | | rw | rw | rw |
| B0 _H | P3_ALTSEL0 P3 Alternate Select 0 Register | Reset: 00_H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |

Functional Description
Table 8 Port Register Overview (cont'd)

| Addr | Register Name | Reset: | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|------------------|---|-----------------------|-----------|----|----|----|----|----|----|----|----|
| B1 _H | P3_ALTSEL1 P3 Alternate Select 1 Register | 00_H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |
| RMAP = 0, Page 3 | | | | | | | | | | | |
| 80 _H | P0_OD P0 Open Drain Control Register | 00_H | Bit Field | 0 | | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | r | | rw | rw | rw | rw | rw | rw |
| 90 _H | P1_OD P1 Open Drain Control Register | 00_H | Bit Field | P7 | P6 | P5 | 0 | | | P1 | P0 |
| | | | Type | rw | rw | rw | r | | | rw | rw |
| B0 _H | P3_OD P3 Open Drain Control Register | 00_H | Bit Field | P7 | P6 | P5 | P4 | P3 | P2 | P1 | P0 |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |

The ADC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 9 ADC Register Overview

| Addr | Register Name | Reset: | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|------------------|---|-----------------------|-----------|------------|------------|---------|------|--------|---------|------------|-------|
| RMAP = 0 | | | | | | | | | | | |
| D1 _H | ADC_PAGE Page Register for ADC | 00_H | Bit Field | OP | | STNR | | 0 | PAGE | | |
| | | | Type | w | | w | | r | rwh | | |
| RMAP = 0, Page 0 | | | | | | | | | | | |
| CA _H | ADC_GLOBCTR Global Control Register | 30_H | Bit Field | ANON | DW | CTC | | 0 | | | |
| | | | Type | rw | rw | rw | | r | | | |
| CB _H | ADC_GLOBSTR Global Status Register | 00_H | Bit Field | 0 | | CHNR | | | 0 | SAM PLE | BUSY |
| | | | Type | r | | rh | | | r | rh | rh |
| CC _H | ADC_PRAR Priority and Arbitration Register | 00_H | Bit Field | ASEN1 | ASEN0 | 0 | ARBM | CSM1 | PRI01 | CSM0 | PRI00 |
| | | | Type | rw | rw | r | rw | rw | rw | rw | rw |
| CD _H | ADC_LCBR Limit Check Boundary Register | B7_H | Bit Field | BOUND1 | | | | BOUND0 | | | |
| | | | Type | rw | | | | rw | | | |
| CE _H | ADC_INPCR0 Input Class Register 0 | 00_H | Bit Field | STC | | | | | | | |
| | | | Type | rw | | | | | | | |
| CF _H | ADC_ETRCR External Trigger Control Register | 00_H | Bit Field | SYNEN 1 | SYNEN 0 | ETRSEL1 | | | ETRSEL0 | | |
| | | | Type | rw | rw | rw | | | rw | | |
| RMAP = 0, Page 1 | | | | | | | | | | | |
| CA _H | ADC_CHCTR0 Channel Control Register 0 | 00_H | Bit Field | 0 | LCC | | | 0 | RESRSEL | | |
| | | | Type | r | rw | | | r | rw | | |
| CB _H | ADC_CHCTR1 Channel Control Register 1 | 00_H | Bit Field | 0 | LCC | | | 0 | RESRSEL | | |
| | | | Type | r | rw | | | r | rw | | |
| CC _H | ADC_CHCTR2 Channel Control Register 2 | 00_H | Bit Field | 0 | LCC | | | 0 | RESRSEL | | |
| | | | Type | r | rw | | | r | rw | | |
| CD _H | ADC_CHCTR3 Channel Control Register 3 | 00_H | Bit Field | 0 | LCC | | | 0 | RESRSEL | | |
| | | | Type | r | rw | | | r | rw | | |
| CE _H | ADC_CHCTR4 Channel Control Register 4 | 00_H | Bit Field | 0 | LCC | | | 0 | RESRSEL | | |
| | | | Type | r | rw | | | r | rw | | |
| CF _H | ADC_CHCTR5 Channel Control Register 5 | 00_H | Bit Field | 0 | LCC | | | 0 | RESRSEL | | |
| | | | Type | r | rw | | | r | rw | | |
| D2 _H | ADC_CHCTR6 Channel Control Register 6 | 00_H | Bit Field | 0 | LCC | | | 0 | RESRSEL | | |
| | | | Type | r | rw | | | r | rw | | |
| D3 _H | ADC_CHCTR7 Channel Control Register 7 | 00_H | Bit Field | 0 | LCC | | | 0 | RESRSEL | | |
| | | | Type | r | rw | | | r | rw | | |
| RMAP = 0, Page 2 | | | | | | | | | | | |

Functional Description
Table 9 ADC Register Overview (cont'd)

| Addr | Register Name | Reset | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 | |
|------------------|--|------------------------|-----------|--------------|-----|----|-----|------|------|--------|------|--|
| CA _H | ADC_RESR0L Result Register 0 Low | Reset: 00 _H | Bit Field | RESULT[1:0] | 0 | VF | DRC | CHNR | | | | |
| | | | Type | rh | r | rh | rh | rh | | | | |
| CB _H | ADC_RESR0H Result Register 0 High | Reset: 00 _H | Bit Field | RESULT[9:2] | | | | | | | | |
| | | | Type | rh | | | | | | | | |
| CC _H | ADC_RESR1L Result Register 1 Low | Reset: 00 _H | Bit Field | RESULT[1:0] | 0 | VF | DRC | CHNR | | | | |
| | | | Type | rh | r | rh | rh | rh | | | | |
| CD _H | ADC_RESR1H Result Register 1 High | Reset: 00 _H | Bit Field | RESULT[9:2] | | | | | | | | |
| | | | Type | rh | | | | | | | | |
| CE _H | ADC_RESR2L Result Register 2 Low | Reset: 00 _H | Bit Field | RESULT[1:0] | 0 | VF | DRC | CHNR | | | | |
| | | | Type | rh | r | rh | rh | rh | | | | |
| CF _H | ADC_RESR2H Result Register 2 High | Reset: 00 _H | Bit Field | RESULT[9:2] | | | | | | | | |
| | | | Type | rh | | | | | | | | |
| D2 _H | ADC_RESR3L Result Register 3 Low | Reset: 00 _H | Bit Field | RESULT[1:0] | 0 | VF | DRC | CHNR | | | | |
| | | | Type | rh | r | rh | rh | rh | | | | |
| D3 _H | ADC_RESR3H Result Register 3 High | Reset: 00 _H | Bit Field | RESULT[9:2] | | | | | | | | |
| | | | Type | rh | | | | | | | | |
| RMAP = 0, Page 3 | | | | | | | | | | | | |
| CA _H | ADC_RESRA0L Result Register 0, View A Low | Reset: 00 _H | Bit Field | RESULT[2:0] | | VF | DRC | CHNR | | | | |
| | | | Type | rh | | rh | rh | rh | | | | |
| CB _H | ADC_RESRA0H Result Register 0, View A High | Reset: 00 _H | Bit Field | RESULT[10:3] | | | | | | | | |
| | | | Type | rh | | | | | | | | |
| CC _H | ADC_RESRA1L Result Register 1, View A Low | Reset: 00 _H | Bit Field | RESULT[2:0] | | VF | DRC | CHNR | | | | |
| | | | Type | rh | | rh | rh | rh | | | | |
| CD _H | ADC_RESRA1H Result Register 1, View A High | Reset: 00 _H | Bit Field | RESULT[10:3] | | | | | | | | |
| | | | Type | rh | | | | | | | | |
| CE _H | ADC_RESRA2L Result Register 2, View A Low | Reset: 00 _H | Bit Field | RESULT[2:0] | | VF | DRC | CHNR | | | | |
| | | | Type | rh | | rh | rh | rh | | | | |
| CF _H | ADC_RESRA2H Result Register 2, View A High | Reset: 00 _H | Bit Field | RESULT[10:3] | | | | | | | | |
| | | | Type | rh | | | | | | | | |
| D2 _H | ADC_RESRA3L Result Register 3, View A Low | Reset: 00 _H | Bit Field | RESULT[2:0] | | VF | DRC | CHNR | | | | |
| | | | Type | rh | | rh | rh | rh | | | | |
| D3 _H | ADC_RESRA3H Result Register 3, View A High | Reset: 00 _H | Bit Field | RESULT[10:3] | | | | | | | | |
| | | | Type | rh | | | | | | | | |
| RMAP = 0, Page 4 | | | | | | | | | | | | |
| CA _H | ADC_RCR0 Result Control Register 0 | Reset: 00 _H | Bit Field | VFCTR | WFR | 0 | IEN | 0 | | DRCT R | | |
| | | | Type | rw | rw | r | rw | r | | rw | | |
| CB _H | ADC_RCR1 Result Control Register 1 | Reset: 00 _H | Bit Field | VFCTR | WFR | 0 | IEN | 0 | | DRCT R | | |
| | | | Type | rw | rw | r | rw | r | | rw | | |
| CC _H | ADC_RCR2 Result Control Register 2 | Reset: 00 _H | Bit Field | VFCTR | WFR | 0 | IEN | 0 | | DRCT R | | |
| | | | Type | rw | rw | r | rw | r | | rw | | |
| CD _H | ADC_RCR3 Result Control Register 3 | Reset: 00 _H | Bit Field | VFCTR | WFR | 0 | IEN | 0 | | DRCT R | | |
| | | | Type | rw | rw | r | rw | r | | rw | | |
| CE _H | ADC_VFCR Valid Flag Clear Register | Reset: 00 _H | Bit Field | 0 | | | | VFC3 | VFC2 | VFC1 | VFC0 | |
| | | | Type | r | | | | w | w | w | w | |
| RMAP = 0, Page 5 | | | | | | | | | | | | |

Functional Description
Table 9 ADC Register Overview (cont'd)

| Addr | Register Name | Reset: | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|------------------|--|------------------------|-----------|------------|------------|------------|------------|------------|------------|------------|------------|
| CA _H | ADC_CHINFR Channel Interrupt Flag Register | Reset: 00 _H | Bit Field | CHINF 7 | CHINF 6 | CHINF 5 | CHINF 4 | CHINF 3 | CHINF 2 | CHINF 1 | CHINF 0 |
| | | | Type | rh | rh | rh | rh | rh | rh | rh | rh |
| CB _H | ADC_CHINCR Channel Interrupt Clear Register | Reset: 00 _H | Bit Field | CHINC 7 | CHINC 6 | CHINC 5 | CHINC 4 | CHINC 3 | CHINC 2 | CHINC 1 | CHINC 0 |
| | | | Type | w | w | w | w | w | w | w | w |
| CC _H | ADC_CHINSR Channel Interrupt Set Register | Reset: 00 _H | Bit Field | CHINS 7 | CHINS 6 | CHINS 5 | CHINS 4 | CHINS 3 | CHINS 2 | CHINS 1 | CHINS 0 |
| | | | Type | w | w | w | w | w | w | w | w |
| CD _H | ADC_CHINPR Channel Interrupt Node Pointer Register | Reset: 00 _H | Bit Field | CHINP 7 | CHINP 6 | CHINP 5 | CHINP 4 | CHINP 3 | CHINP 2 | CHINP 1 | CHINP 0 |
| | | | Type | rw | rw | rw | rw | rw | rw | rw | rw |
| CE _H | ADC_EVINFR Event Interrupt Flag Register | Reset: 00 _H | Bit Field | EVINF 7 | EVINF 6 | EVINF 5 | EVINF 4 | 0 | | EVINF 1 | EVINF 0 |
| | | | Type | rh | rh | rh | rh | r | | rh | rh |
| CF _H | ADC_EVINCR Event Interrupt Clear Flag Register | Reset: 00 _H | Bit Field | EVINC 7 | EVINC 6 | EVINC 5 | EVINC 4 | 0 | | EVINC 1 | EVINC 0 |
| | | | Type | w | w | w | w | r | | w | w |
| D2 _H | ADC_EVINSR Event Interrupt Set Flag Register | Reset: 00 _H | Bit Field | EVINS 7 | EVINS 6 | EVINS 5 | EVINS 4 | 0 | | EVINS 1 | EVINS 0 |
| | | | Type | w | w | w | w | r | | w | w |
| D3 _H | ADC_EVINPR Event Interrupt Node Pointer Register | Reset: 00 _H | Bit Field | EVINP 7 | EVINP 6 | EVINP 5 | EVINP 4 | 0 | | EVINP 1 | EVINP 0 |
| | | | Type | rw | rw | rw | rw | r | | rw | rw |
| RMAP = 0, Page 6 | | | | | | | | | | | |
| CA _H | ADC_CRCR1 Conversion Request Control Register 1 | Reset: 00 _H | Bit Field | CH7 | CH6 | CH5 | CH4 | 0 | | | |
| | | | Type | rwh | rwh | rwh | rwh | r | | | |
| CB _H | ADC_CRPR1 Conversion Request Pending Register 1 | Reset: 00 _H | Bit Field | CHP7 | CHP6 | CHP5 | CHP4 | 0 | | | |
| | | | Type | rwh | rwh | rwh | rwh | r | | | |
| CC _H | ADC_CRMR1 Conversion Request Mode Register 1 | Reset: 00 _H | Bit Field | Rsv | LDEV | CLR PND | SCAN | ENSI | ENTR | ENGT | |
| | | | Type | r | w | w | rw | rw | rw | rw | |
| CD _H | ADC_QMR0 Queue Mode Register 0 | Reset: 00 _H | Bit Field | CEV | TREV | FLUSH | CLRV | TRMD | ENTR | ENGT | |
| | | | Type | w | w | w | w | rw | rw | rw | |
| CE _H | ADC_QSR0 Queue Status Register 0 | Reset: 20 _H | Bit Field | Rsv | 0 | EMPTY | EV | 0 | | | |
| | | | Type | r | r | rh | rh | r | | | |
| CF _H | ADC_Q0R0 Queue 0 Register 0 | Reset: 00 _H | Bit Field | EXTR | ENSI | RF | V | 0 | REQCHNR | | |
| | | | Type | rh | rh | rh | rh | r | rh | | |
| D2 _H | ADC_QBUR0 Queue Backup Register 0 | Reset: 00 _H | Bit Field | EXTR | ENSI | RF | V | 0 | REQCHNR | | |
| | | | Type | rh | rh | rh | rh | r | rh | | |
| D2 _H | ADC_QINR0 Queue Input Register 0 | Reset: 00 _H | Bit Field | EXTR | ENSI | RF | 0 | | REQCHNR | | |
| | | | Type | w | w | w | r | | w | | |

The Timer 2 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 10 Timer 2 Register Overview

| Addr | Register Name | Reset: | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|-----------------|---|------------------------|-----------|-----|------|---|---|-------|-----|---|------------|
| C0 _H | T2_T2CON Timer 2 Control Register | Reset: 00 _H | Bit Field | TF2 | EXF2 | 0 | | EXEN2 | TR2 | 0 | CP/ RL2 |
| | | | Type | rwh | rwh | r | | rw | rwh | r | rw |

Functional Description
Table 10 Timer 2 Register Overview (cont'd)

| C1 _H | T2_T2MOD Timer 2 Mode Register | Reset: 00 _H | Bit Field | T2 REGS | T2 RHEN | EDGE SEL | PREN | T2PRE | DCEN |
|-----------------|--|------------------------|-----------|------------|------------|-------------|------|-------|------|
| | | | Type | rw | rw | rw | rw | rw | rw |
| C2 _H | T2_RC2L Timer 2 Reload/Capture Register Low | Reset: 00 _H | Bit Field | RC2[7:0] | | | | | |
| | | | Type | rwh | | | | | |
| C3 _H | T2_RC2H Timer 2 Reload/Capture Register High | Reset: 00 _H | Bit Field | RC2[15:8] | | | | | |
| | | | Type | rwh | | | | | |
| C4 _H | T2_T2L Timer 2 Register Low | Reset: 00 _H | Bit Field | THL2[7:0] | | | | | |
| | | | Type | rwh | | | | | |
| C5 _H | T2_T2H Timer 2 Register High | Reset: 00 _H | Bit Field | THL2[15:8] | | | | | |
| | | | Type | rwh | | | | | |

The CCU6 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 11 CCU6 Register Overview

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 | |
|------------------|--|------------------------|-----------|------------|------------|------------|------------|------------|------------|------------|------------|
| RMAP = 0 | | | | | | | | | | | |
| A3 _H | CCU6_PAGE Page Register for CCU6 | Reset: 00 _H | Bit Field | OP | | STNR | | 0 | PAGE | | |
| | | | Type | w | | w | | r | rwh | | |
| RMAP = 0, Page 0 | | | | | | | | | | | |
| 9A _H | CCU6_CC63SRL Capture/Compare Shadow Register for Channel CC63 Low | Reset: 00 _H | Bit Field | CC63SL | | | | | | | |
| | | | Type | rw | | | | | | | |
| 9B _H | CCU6_CC63SRH Capture/Compare Shadow Register for Channel CC63 High | Reset: 00 _H | Bit Field | CC63SH | | | | | | | |
| | | | Type | rw | | | | | | | |
| 9C _H | CCU6_TCTR4L Timer Control Register 4 Low | Reset: 00 _H | Bit Field | T12 STD | T12 STR | 0 | | DTRES | T12 RES | T12RS | T12RR |
| | | | Type | w | w | r | | w | w | w | w |
| 9D _H | CCU6_TCTR4H Timer Control Register 4 High | Reset: 00 _H | Bit Field | T13 STD | T13 STR | 0 | | T13 RES | T13RS | T13RR | |
| | | | Type | w | w | r | | w | w | w | |
| 9E _H | CCU6_MCMOUTSL Multi-Channel Mode Output Shadow Register Low | Reset: 00 _H | Bit Field | STRM CM | 0 | MCMPS | | | | | |
| | | | Type | w | r | rw | | | | | |
| 9F _H | CCU6_MCMOUTSH Multi-Channel Mode Output Shadow Register High | Reset: 00 _H | Bit Field | STRHP | 0 | CURHS | | | EXPHS | | |
| | | | Type | w | r | rw | | | rw | | |
| A4 _H | CCU6_ISRL Capture/Compare Interrupt Status Reset Register Low | Reset: 00 _H | Bit Field | RT12P M | RT12O M | RCC62 F | RCC62 R | RCC61 F | RCC61 R | RCC60 F | RCC60 R |
| | | | Type | w | w | w | w | w | w | w | w |
| A5 _H | CCU6_ISRH Capture/Compare Interrupt Status Reset Register High | Reset: 00 _H | Bit Field | RSTR | RIDLE | RWHE | RCHE | 0 | RTRPF | RT13 PM | RT13 CM |
| | | | Type | w | w | w | w | r | w | w | w |
| A6 _H | CCU6_CMPMODIFL Compare State Modification Register Low | Reset: 00 _H | Bit Field | 0 | MCC63 S | 0 | | MCC62 S | MCC61 S | MCC60 S | |
| | | | Type | r | w | r | | w | w | w | |
| A7 _H | CCU6_CMPMODIFH Compare State Modification Register High | Reset: 00 _H | Bit Field | 0 | MCC63 R | 0 | | MCC62 R | MCC61 R | MCC60 R | |
| | | | Type | r | w | r | | w | w | w | |
| FA _H | CCU6_CC60SRL Capture/Compare Shadow Register for Channel CC60 Low | Reset: 00 _H | Bit Field | CC60SL | | | | | | | |
| | | | Type | rwh | | | | | | | |

Functional Description
Table 11 CCU6 Register Overview (cont'd)

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|------------------|---|-----------|--------|------|-------|------|--------|--------|------|------|
| FB _H | CCU6_CC60SRH Reset: 00 _H Capture/Compare Shadow Register for Channel CC60 High | Bit Field | CC60SH | | | | | | | |
| | | Type | rwh | | | | | | | |
| FC _H | CCU6_CC61SRL Reset: 00 _H Capture/Compare Shadow Register for Channel CC61 Low | Bit Field | CC61SL | | | | | | | |
| | | Type | rwh | | | | | | | |
| FD _H | CCU6_CC61SRH Reset: 00 _H Capture/Compare Shadow Register for Channel CC61 High | Bit Field | CC61SH | | | | | | | |
| | | Type | rwh | | | | | | | |
| FE _H | CCU6_CC62SRL Reset: 00 _H Capture/Compare Shadow Register for Channel CC62 Low | Bit Field | CC62SL | | | | | | | |
| | | Type | rwh | | | | | | | |
| FF _H | CCU6_CC62SRH Reset: 00 _H Capture/Compare Shadow Register for Channel CC62 High | Bit Field | CC62SH | | | | | | | |
| | | Type | rwh | | | | | | | |
| RMAP = 0, Page 1 | | | | | | | | | | |
| 9A _H | CCU6_CC63RL Reset: 00 _H Capture/Compare Register for Channel CC63 Low | Bit Field | CC63VL | | | | | | | |
| | | Type | rh | | | | | | | |
| 9B _H | CCU6_CC63RH Reset: 00 _H Capture/Compare Register for Channel CC63 High | Bit Field | CC63VH | | | | | | | |
| | | Type | rh | | | | | | | |
| 9C _H | CCU6_T12PRL Reset: 00 _H Timer T12 Period Register Low | Bit Field | T12PVL | | | | | | | |
| | | Type | rwh | | | | | | | |
| 9D _H | CCU6_T12PRH Reset: 00 _H Timer T12 Period Register High | Bit Field | T12PVH | | | | | | | |
| | | Type | rwh | | | | | | | |
| 9E _H | CCU6_T13PRL Reset: 00 _H Timer T13 Period Register Low | Bit Field | T13PVL | | | | | | | |
| | | Type | rwh | | | | | | | |
| 9F _H | CCU6_T13PRH Reset: 00 _H Timer T13 Period Register High | Bit Field | T13PVH | | | | | | | |
| | | Type | rwh | | | | | | | |
| A4 _H | CCU6_T12DTCL Reset: 00 _H Dead-Time Control Register for Timer T12 Low | Bit Field | DTM | | | | | | | |
| | | Type | rw | | | | | | | |
| A5 _H | CCU6_T12DTCH Reset: 00 _H Dead-Time Control Register for Timer T12 High | Bit Field | 0 | DTR2 | DTR1 | DTR0 | 0 | DTE2 | DTE1 | DTE0 |
| | | Type | r | rh | rh | rh | r | rw | rw | rw |
| A6 _H | CCU6_TCTR0L Reset: 00 _H Timer Control Register 0 Low | Bit Field | CTM | CDIR | STE12 | T12R | T12PRE | T12CLK | | |
| | | Type | rw | rh | rh | rh | rw | rw | | |
| A7 _H | CCU6_TCTR0H Reset: 00 _H Timer Control Register 0 High | Bit Field | 0 | | STE13 | T13R | T13PRE | T13CLK | | |
| | | Type | r | | rh | rh | rw | rw | | |
| FA _H | CCU6_CC60RL Reset: 00 _H Capture/Compare Register for Channel CC60 Low | Bit Field | CC60VL | | | | | | | |
| | | Type | rh | | | | | | | |
| FB _H | CCU6_CC60RH Reset: 00 _H Capture/Compare Register for Channel CC60 High | Bit Field | CC60VH | | | | | | | |
| | | Type | rh | | | | | | | |
| FC _H | CCU6_CC61RL Reset: 00 _H Capture/Compare Register for Channel CC61 Low | Bit Field | CC61VL | | | | | | | |
| | | Type | rh | | | | | | | |

Functional Description
Table 11 CCU6 Register Overview (cont'd)

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 | |
|------------------|---|-----------|----------|----------|----------|----------|----------|----------|----------|----------|--|
| FD _H | CCU6_CC61RH Reset: 00_H Capture/Compare Register for Channel CC61 High | Bit Field | CC61VH | | | | | | | | |
| | | Type | rh | | | | | | | | |
| FE _H | CCU6_CC62RL Reset: 00_H Capture/Compare Register for Channel CC62 Low | Bit Field | CC62VL | | | | | | | | |
| | | Type | rh | | | | | | | | |
| FF _H | CCU6_CC62RH Reset: 00_H Capture/Compare Register for Channel CC62 High | Bit Field | CC62VH | | | | | | | | |
| | | Type | rh | | | | | | | | |
| RMAP = 0, Page 2 | | | | | | | | | | | |
| 9A _H | CCU6_T12MSELL Reset: 00_H T12 Capture/Compare Mode Select Register Low | Bit Field | MSEL61 | | | | MSEL60 | | | | |
| | | Type | rw | | | | rw | | | | |
| 9B _H | CCU6_T12MSELH Reset: 00_H T12 Capture/Compare Mode Select Register High | Bit Field | DBYP | HSYNC | | | MSEL62 | | | | |
| | | Type | rw | rw | | | rw | | | | |
| 9C _H | CCU6_IENL Reset: 00_H Capture/Compare Interrupt Enable Register Low | Bit Field | ENT12 PM | ENT12 OM | ENCC 62F | ENCC 62R | ENCC 61F | ENCC 61R | ENCC 60F | ENCC 60R | |
| | | Type | rw | rw | rw | rw | rw | rw | rw | rw | |
| 9D _H | CCU6_IENH Reset: 00_H Capture/Compare Interrupt Enable Register High | Bit Field | ENSTR | EN IDLE | EN WHE | EN CHE | 0 | EN TRPF | ENT13 PM | ENT13 CM | |
| | | Type | rw | rw | rw | rw | r | rw | rw | rw | |
| 9E _H | CCU6_INPL Reset: 40_H Capture/Compare Interrupt Node Pointer Register Low | Bit Field | INPCHE | | INPCC62 | | INPCC61 | | INPCC60 | | |
| | | Type | rw | | rw | | rw | | rw | | |
| 9F _H | CCU6_INPH Reset: 39_H Capture/Compare Interrupt Node Pointer Register High | Bit Field | 0 | | INPT13 | | INPT12 | | INPERR | | |
| | | Type | r | | rw | | rw | | rw | | |
| A4 _H | CCU6_ISSL Reset: 00_H Capture/Compare Interrupt Status Set Register Low | Bit Field | ST12P M | ST12O M | SCC62 F | SCC62 R | SCC61 F | SCC61 R | SCC60 F | SCC60 R | |
| | | Type | w | w | w | w | w | w | w | w | |
| A5 _H | CCU6_ISSH Reset: 00_H Capture/Compare Interrupt Status Set Register High | Bit Field | SSTR | SIDLE | SWHE | SCHE | SWHC | STRPF | ST13 PM | ST13 CM | |
| | | Type | w | w | w | w | w | w | w | w | |
| A6 _H | CCU6_PSLR Reset: 00_H Passive State Level Register | Bit Field | PSL63 | 0 | PSL | | | | | | |
| | | Type | rwh | r | rwh | | | | | | |
| A7 _H | CCU6_MCMCTR Reset: 00_H Multi-Channel Mode Control Register | Bit Field | 0 | | SWSYN | | 0 | SWSEL | | | |
| | | Type | r | | rw | | r | rw | | | |
| FA _H | CCU6_TCTR2L Reset: 00_H Timer Control Register 2 Low | Bit Field | 0 | T13TED | | T13TEC | | T13 SSC | T12 SSC | | |
| | | Type | r | rw | | rw | | rw | rw | | |
| FB _H | CCU6_TCTR2H Reset: 00_H Timer Control Register 2 High | Bit Field | 0 | | | | T13RSEL | | T12RSEL | | |
| | | Type | r | | | | rw | | rw | | |
| FC _H | CCU6_MODCTRL Reset: 00_H Modulation Control Register Low | Bit Field | MC MEN | 0 | T12MODEN | | | | | | |
| | | Type | rw | r | rw | | | | | | |
| FD _H | CCU6_MODCTRH Reset: 00_H Modulation Control Register High | Bit Field | ECT13 O | 0 | T13MODEN | | | | | | |
| | | Type | rw | r | rw | | | | | | |
| FE _H | CCU6_TRPCTRL Reset: 00_H Trap Control Register Low | Bit Field | 0 | | | | TRPM2 | TRPM1 | TRPM0 | | |
| | | Type | r | | | | rw | rw | rw | | |

Functional Description
Table 11 CCU6 Register Overview (cont'd)

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
|------------------|--|-----------|------------|--------------|--------------|-------------|--------------|-------------|--------------|------------|
| FF _H | CCU6_TRPCTRH Reset: 00_H Trap Control Register High | Bit Field | TRPPE N | TRPEN 13 | TRPEN | | | | | |
| | | Type | rw | rw | rw | | | | | |
| RMAP = 0, Page 3 | | | | | | | | | | |
| 9A _H | CCU6_MCMOUTL Reset: 00_H Multi-Channel Mode Output Register Low | Bit Field | 0 | R | MCMCP | | | | | |
| | | Type | r | rh | rh | | | | | |
| 9B _H | CCU6_MCMOUTH Reset: 00_H Multi-Channel Mode Output Register High | Bit Field | 0 | | CURH | | | EXPH | | |
| | | Type | r | | rh | | | rh | | |
| 9C _H | CCU6_ISL Reset: 00_H Capture/Compare Interrupt Status Register Low | Bit Field | T12PM | T12OM | ICC62F R | ICC61F R | ICC61 R | ICC60F R | ICC60 R | |
| | | Type | rh | rh | rh | rh | rh | rh | rh | |
| 9D _H | CCU6_ISH Reset: 00_H Capture/Compare Interrupt Status Register High | Bit Field | STR | IDLE | WHE | CHE | TRPS | TRPF | T13PM | T13CM |
| | | Type | rh | rh | rh | rh | rh | rh | rh | rh |
| 9E _H | CCU6_PISEL0L Reset: 00_H Port Input Select Register 0 Low | Bit Field | ISTRP | | ISCC62 | | ISCC61 | | ISCC60 | |
| | | Type | rw | | rw | | rw | | rw | |
| 9F _H | CCU6_PISEL0H Reset: 00_H Port Input Select Register 0 High | Bit Field | IST12HR | | ISPOS2 | | ISPOS1 | | ISPOS0 | |
| | | Type | rw | | rw | | rw | | rw | |
| A4 _H | CCU6_PISEL2 Reset: 00_H Port Input Select Register 2 | Bit Field | 0 | | | | | | IST13HR | |
| | | Type | r | | | | | | rw | |
| FA _H | CCU6_T12L Reset: 00_H Timer T12 Counter Register Low | Bit Field | T12CVL | | | | | | | |
| | | Type | rwh | | | | | | | |
| FB _H | CCU6_T12H Reset: 00_H Timer T12 Counter Register High | Bit Field | T12CVH | | | | | | | |
| | | Type | rwh | | | | | | | |
| FC _H | CCU6_T13L Reset: 00_H Timer T13 Counter Register Low | Bit Field | T13CVL | | | | | | | |
| | | Type | rwh | | | | | | | |
| FD _H | CCU6_T13H Reset: 00_H Timer T13 Counter Register High | Bit Field | T13CVH | | | | | | | |
| | | Type | rwh | | | | | | | |
| FE _H | CCU6_CMPSTATL Reset: 00_H Compare State Register Low | Bit Field | 0 | CC63 ST | CCPO S2 | CCPO S1 | CCPO S0 | CC62 ST | CC61 ST | CC60 ST |
| | | Type | r | rh | rh | rh | rh | rh | rh | rh |
| FF _H | CCU6_CMPSTATH Reset: 00_H Compare State Register High | Bit Field | T13IM | COUT 63PS | COUT 62PS | CC62 PS | COUT 61PS | CC61 PS | COUT 60PS | CC60 PS |
| | | Type | rwh | rwh | rwh | rwh | rwh | rwh | rwh | rwh |

The SSC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 12 SSC Register Overview

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 | |
|-----------------|---|-----------|----|----|----|----|----|---|-----|-----|-----|
| RMAP = 0 | | | | | | | | | | | |
| A9 _H | SSC_PISEL Reset: 00_H Port Input Select Register | Bit Field | 0 | | | | | | CIS | SIS | MIS |
| | | Type | r | | | | | | rw | rw | rw |
| AA _H | SSC_CONL Reset: 00_H Control Register Low <i>Programming Mode</i> | Bit Field | LB | PO | PH | HB | BM | | | | |
| | | Type | rw | rw | rw | rw | rw | | | | |
| | <i>Operating Mode</i> | Bit Field | 0 | | | | | | BC | | |
| | | Type | r | | | | | | rh | | |

Functional Description
Table 12 SSC Register Overview

| | | | | | | | | | | | |
|-----------------|---|------------------------------|-----------|----------------|----|---|------|-----|-----|-----|-----|
| AB _H | SSC_CONH Control Register High <i>Programming Mode</i> | Reset: 00_H | Bit Field | EN | MS | 0 | AREN | BEN | PEN | REN | TEN |
| | | | Type | rw | rw | r | rw | rw | rw | rw | rw |
| | <i>Operating Mode</i> | | Bit Field | EN | MS | 0 | BSY | BE | PE | RE | TE |
| | | | Type | rw | rw | r | rh | rwh | rwh | rwh | rwh |
| AC _H | SSC_TBL Transmitter Buffer Register Low | Reset: 00_H | Bit Field | TB_VALUE | | | | | | | |
| | | | Type | rw | | | | | | | |
| AD _H | SSC_RBL Receiver Buffer Register Low | Reset: 00_H | Bit Field | RB_VALUE | | | | | | | |
| | | | Type | rh | | | | | | | |
| AE _H | SSC_BRL Baudrate Timer Reload Register Low | Reset: 00_H | Bit Field | BR_VALUE[7:0] | | | | | | | |
| | | | Type | rw | | | | | | | |
| AF _H | SSC_BRH Baudrate Timer Reload Register High | Reset: 00_H | Bit Field | BR_VALUE[15:8] | | | | | | | |
| | | | Type | rw | | | | | | | |

The OCDS SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 13 OCDS Register Overview

| Addr | Register Name | Bit | 7 | 6 | 5 | 4 | 3 | 2 | 1 | 0 | |
|-----------------|---|------------------------------|-----------|---------|-------|----------|---------|----------|--------|--------|--------|
| RMAP = 1 | | | | | | | | | | | |
| E9 _H | MMCR2 Monitor Mode Control Register 2 | Reset: 00_H | Bit Field | EXBC_P | EXBC | MBCO_N_P | MBCO_N | MMEP_P | MMEP | MMOD_E | JENA |
| | | | Type | w | rw | w | rwh | w | rwh | rh | rh |
| F1 _H | MMCR Monitor Mode Control Register | Reset: 00_H | Bit Field | MEXIT_P | MEXIT | MSTEP_P | MSTEP | MRAM_S_P | MRAM_S | TRF | RRF |
| | | | Type | w | rwh | w | rw | w | rwh | rh | rh |
| F2 _H | MMSR Monitor Mode Status Register | Reset: 00_H | Bit Field | MBCA_M | MBCIN | EXBF | SWBF | HWB3_F | HWB2_F | HWB1_F | HWB0_F |
| | | | Type | rw | rh | rwh | rwh | rwh | rwh | rwh | rwh |
| F3 _H | MMBPCR BreakPoints Control Register | Reset: 00_H | Bit Field | SWBC | HWB3C | | HWB2C | | HWB1_C | HWB0C | |
| | | | Type | rw | rw | | rw | | rw | rw | |
| F4 _H | MMICR Monitor Mode Interrupt Control Register | Reset: 00_H | Bit Field | DVECT | DRETR | 0 | | MMUIE_P | MMUIE | RRIE_P | RRIE |
| | | | Type | rwh | rwh | r | | w | rw | w | rw |
| F5 _H | MMDR Monitor Mode Data Register | Reset: 00_H | Bit Field | MMRR | | | | | | | |
| | | | Type | rh | | | | | | | |
| | | | Bit Field | MMTR | | | | | | | |
| | | | Type | w | | | | | | | |
| F6 _H | HWBPSR Hardware Breakpoints Select Register | Reset: 00_H | Bit Field | 0 | | | BPSEL_P | BPSEL | | | |
| | | | Type | r | | | w | rw | | | |
| F7 _H | HWBPDR Hardware Breakpoints Data Register | Reset: 00_H | Bit Field | HWBPxx | | | | | | | |
| | | | Type | rw | | | | | | | |

3.3 Flash Memory

The Flash memory provides an embedded user-programmable non-volatile memory, allowing fast and reliable storage of user code and data. It is operated from a single 2.5 V supply from the Embedded Voltage Regulator (EVR) and does not require additional programming or erasing voltage. The sectorization of the Flash memory allows each sector to be erased independently.

Features

- In-System Programming (ISP) via UART
- In-Application Programming (IAP)
- Error Correction Code (ECC) for dynamic correction of single-bit errors
- Background program and erase operations for CPU load minimization
- Support for aborting erase operation
- Minimum program width¹⁾ of 32-byte for D-Flash and 32-byte for P-Flash
- 1-sector minimum erase width
- 1-byte read access
- Flash is delivered in erased state (read all zeros)
- Operating supply voltage: $2.5\text{ V} \pm 7.5\%$
- Read access time: $3 \times t_{\text{CCLK}} = 120\text{ ns}^2)$
- Program time: $209440 / f_{\text{SYS}} = 2.8\text{ ms}^3)$
- Erase time: $8175360 / f_{\text{SYS}} = 109\text{ ms}^3)$

¹⁾ P-Flash: 32-byte wordline can only be programmed once, i.e., one gate disturb allowed.
D-Flash: 32-byte wordline can be programmed twice, i.e., two gate disturbs allowed.

²⁾ $f_{\text{SYS}} = 75\text{ MHz} \pm 7.5\%$ ($f_{\text{CCLK}} = 25\text{ MHz} \pm 7.5\%$) is the maximum frequency range for Flash read access.

³⁾ $f_{\text{SYS}} = 75\text{ MHz} \pm 7.5\%$ is the only frequency range for Flash programming and erasing. f_{SYSmin} is used for obtaining the worst case timing.

Functional Description

Table 14 shows the Flash data retention and endurance targets.

Table 14 Flash Data Retention and Endurance

| Retention | Endurance ¹⁾ | Size | | Remarks |
|----------------------|------------------------------|--------------------------------|--------------------------------|----------------------|
| | | T _A =- 40 to 125 °C | T _A = 125 to 150 °C | |
| Program Flash | | | | |
| 20 years | 1,000 cycles | up to 16 Kbytes ²⁾ | | for 16-Kbyte Variant |
| 20 years | 1,000 cycles | up to 8 Kbytes ²⁾ | | for 8-Kbyte Variant |
| Data Flash | | | | |
| 20 years | 1,000 cycles ³⁾ | 4 Kbytes | 1 Kbytes | |
| 5 years | 10,000 cycles ³⁾ | 1 Kbyte | 256 bytes | |
| 2 years | 70,000 cycles ³⁾ | 512 bytes | 128 bytes | |
| 2 years | 100,000 cycles ³⁾ | 128 bytes | 32 bytes | |

¹⁾ One cycle refers to the programming of all wordlines in a sector and erasing of sector. The Flash endurance data specified in Table 14 is valid only if the following conditions are fulfilled:

- the maximum number of erase cycles per Flash sector must not exceed 100,000 cycles.
- the maximum number of erase cycles per Flash bank must not exceed 300,000 cycles.
- the maximum number of program cycles per Flash bank must not exceed 2,500,000 cycles.

²⁾ If no Flash is used for data, the Program Flash size can be up to the maximum Flash size available in the device variant. Having more Data Flash will mean less Flash is available for Program Flash.

³⁾ For T_A=125 to 150°C, refers to programming of second 8 bytes (bytes 8 to 15) per WL

3.3.1 Flash Bank Sectorization

The SAL-XC866 product family offers four Flash devices with either 8 Kbytes or 16 Kbytes of embedded Flash memory. These Flash memory sizes are made up of two or four 4-Kbyte Flash banks, respectively. Each Flash device consists of Program Flash (P-Flash) bank(s) and a single Data Flash (D-Flash) bank with different sectorization shown in **Figure 10**. Both types can be used for code and data storage. The label “Data” neither implies that the D-Flash is mapped to the data memory region, nor that it can only be used for data storage. It is used to distinguish the different Flash bank sectorizations.

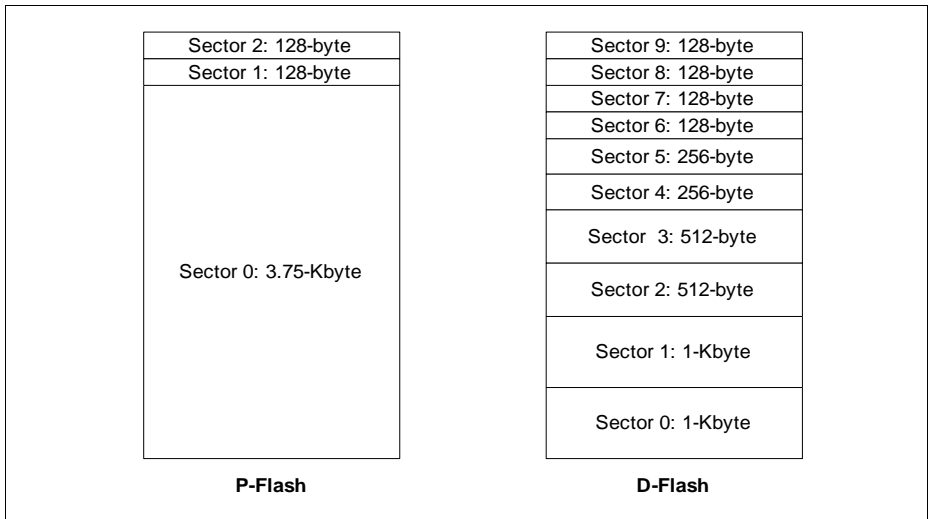


Figure 10 Flash Bank Sectorization

The internal structure of each Flash bank represents a sector architecture for flexible erase capability. The minimum erase width is always a complete sector, and sectors can be erased separately or in parallel. Contrary to standard EPROMs, erased Flash memory cells contain 0s.

The D-Flash bank is divided into more physical sectors for extended erasing and reprogramming capability; even numbers for each sector size are provided to allow greater flexibility and the ability to adapt to a wide range of application requirements.

3.3.2 Flash Programming Width

For the P-Flash banks, a programmed wordline (WL) must be erased before it can be reprogrammed as the Flash cells can only withstand one gate disturb. This means that the entire sector containing the WL must be erased since it is impossible to erase a single WL.

For the D-Flash bank, the same WL can be programmed twice before erasing is required as the Flash cells are able to withstand two gate disturbs. Hence, it is possible to program the same WL, for example, with 16 bytes of data in two times (see [Figure 11](#)).

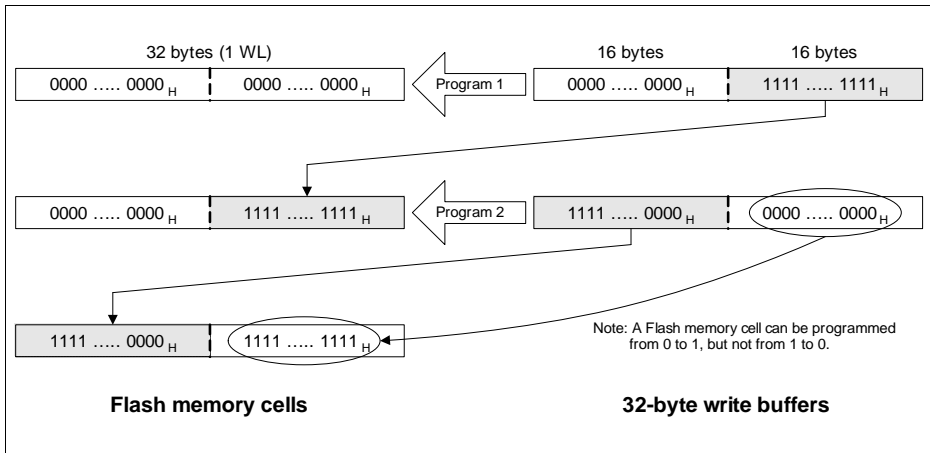


Figure 11 D-Flash Programming

Note: When programming a D-Flash WL the second time, the previously programmed Flash memory cells (whether 0s or 1s) should be reprogrammed with 0s to retain its original contents and to prevent “over-programming”.

3.4 Interrupt System

The XC800 Core supports one non-maskable interrupt (NMI) and 14 maskable interrupt requests. In addition to the standard interrupt functions supported by the core, e.g., configurable interrupt priority and interrupt masking, the XC866 interrupt system provides extended interrupt support capabilities such as the mapping of each interrupt vector to several interrupt sources to increase the number of interrupt sources supported, and additional status registers for detecting and determining the interrupt source.

3.4.1 Interrupt Source

Figure 12 to Figure 16 give a general overview of the interrupt sources and illustrates the request and control flags.

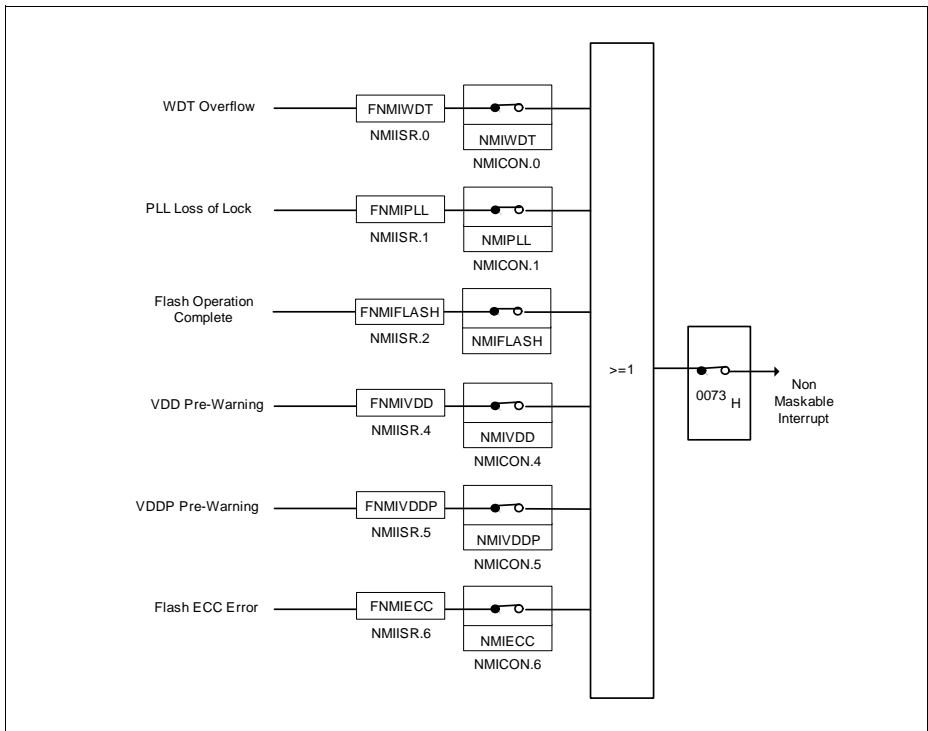


Figure 12 Non-Maskable Interrupt Request Sources

Functional Description

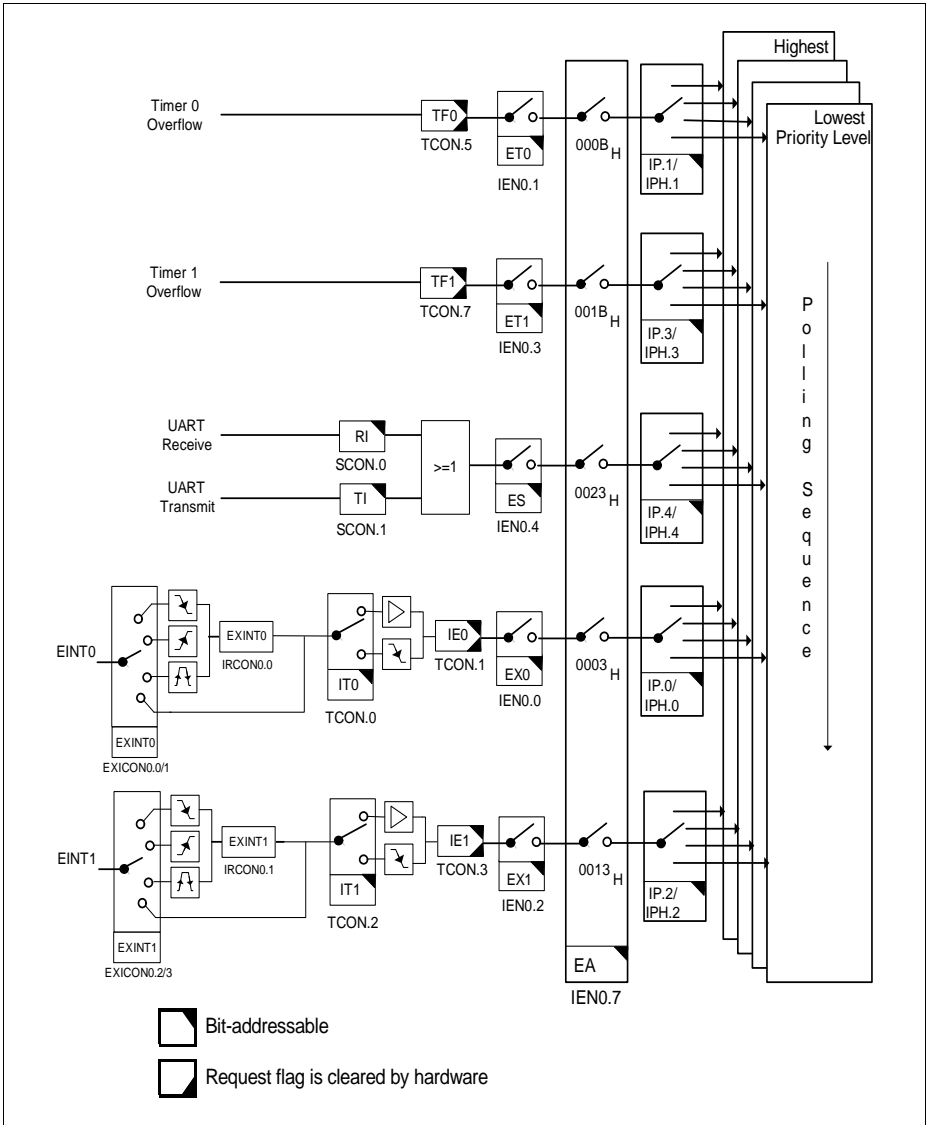


Figure 13 Interrupt Request Sources (Part 1)

Functional Description

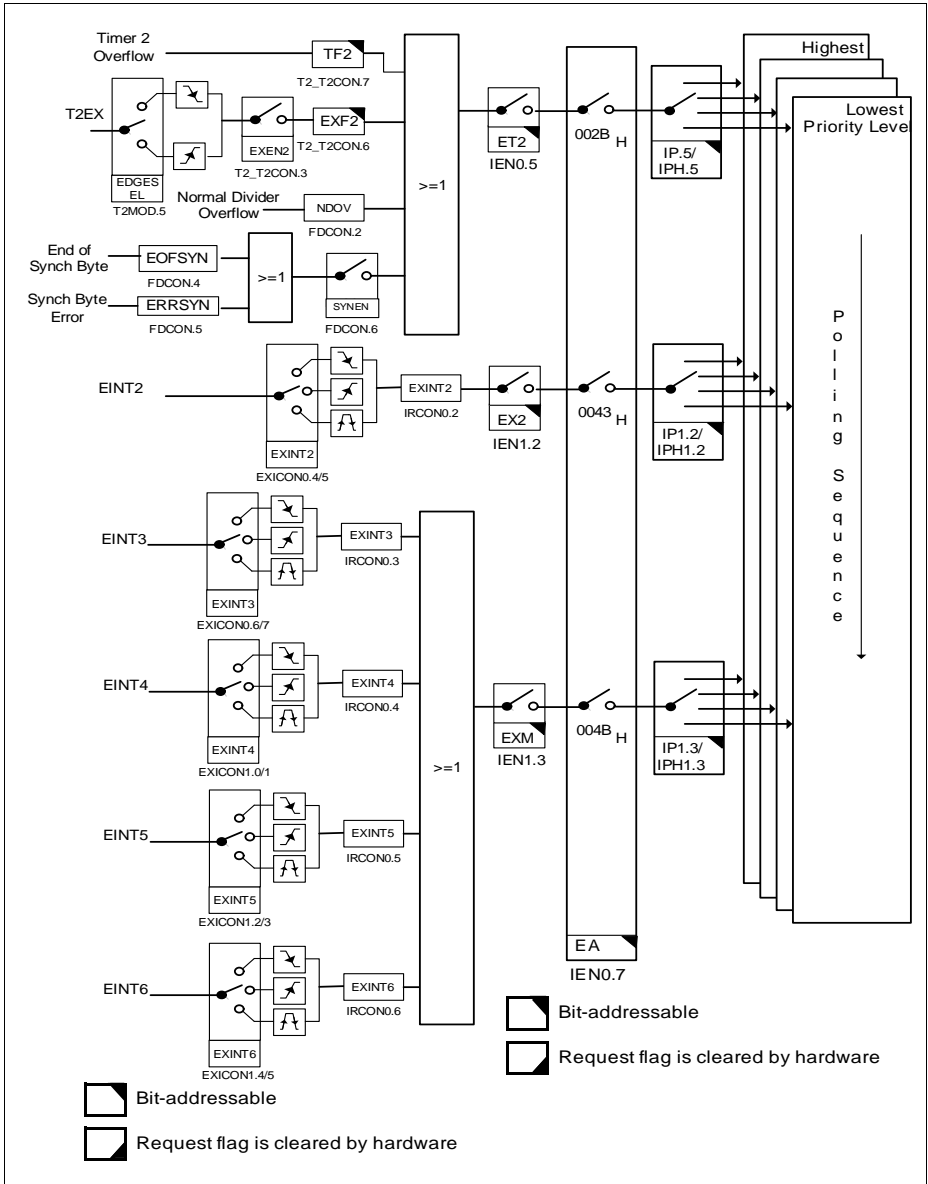


Figure 14 Interrupt Request Sources (Part 2)

Functional Description

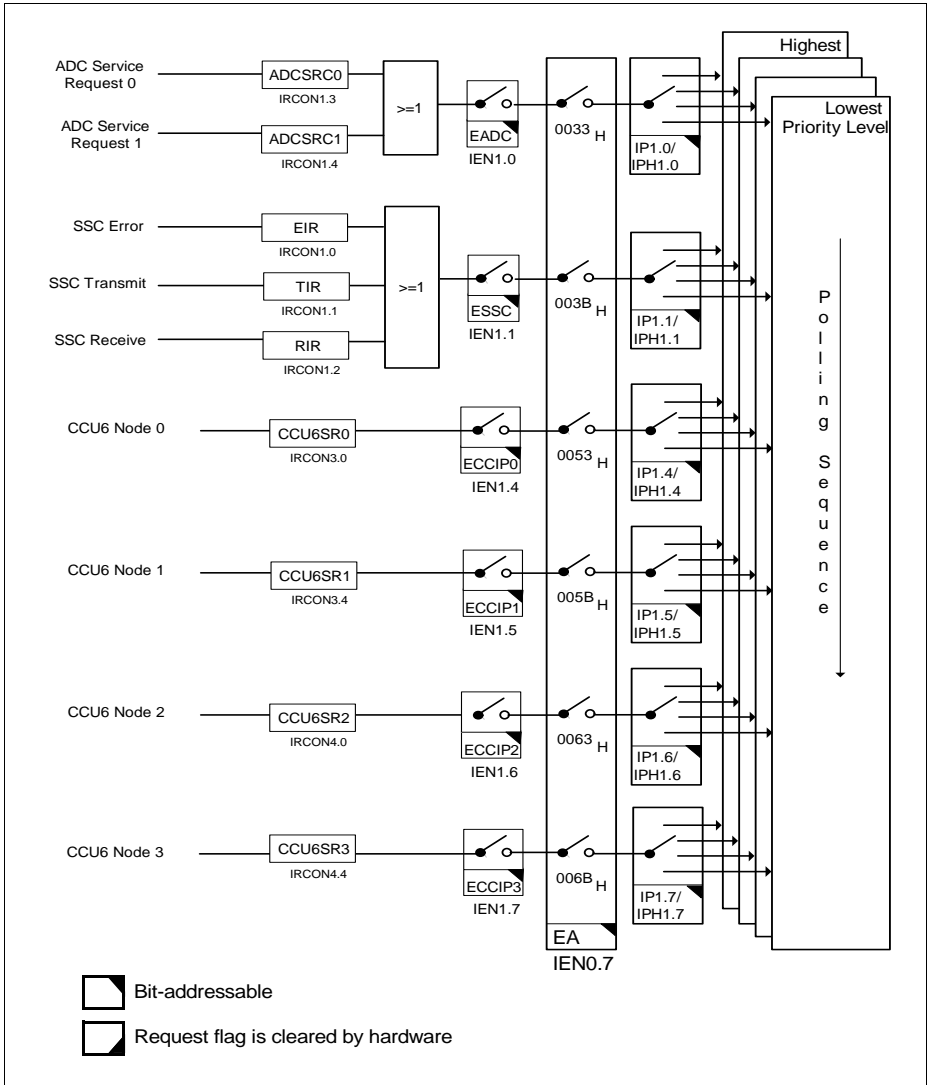


Figure 15 Interrupt Request Sources (Part 3)

Functional Description

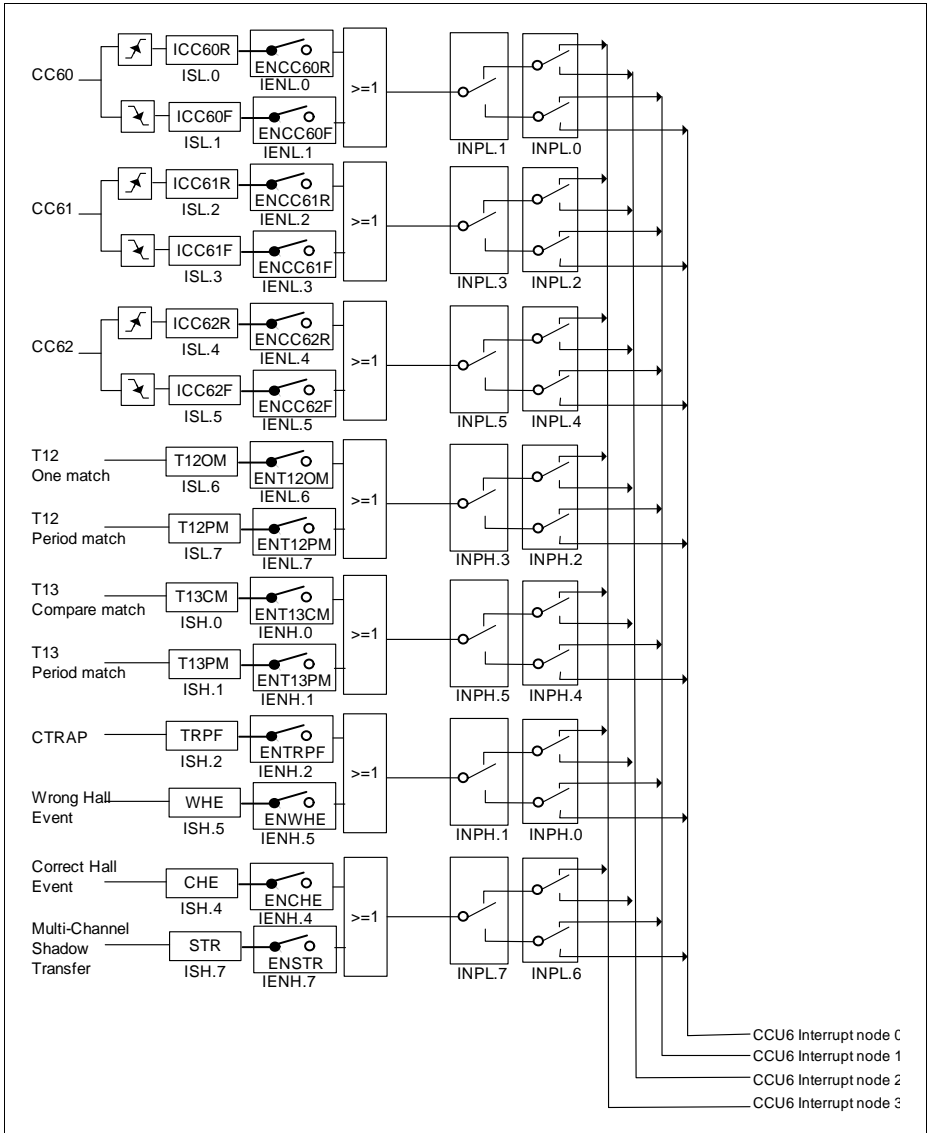


Figure 16 Interrupt Request Sources (Part 4)

3.4.2 Interrupt Source and Vector

Each interrupt source has an associated interrupt vector address. This vector is accessed to service the corresponding interrupt source request. The interrupt service of each interrupt source can be individually enabled or disabled via an enable bit. The assignment of the SAL-XC866 interrupt sources to the interrupt vector addresses and the corresponding interrupt source enable bits are summarized in [Table 15](#).

Table 15 Interrupt Vector Addresses

| Interrupt Source | Vector Address | Assignment for SAL-XC866 | Enable Bit | SFR |
|------------------|-------------------|--|------------|--------|
| NMI | 0073 _H | Watchdog Timer NMI | NMIWDT | NMICON |
| | | PLL NMI | NMIPLL | |
| | | Flash NMI | NMIFLASH | |
| | | VDDC Prewarning NMI | NMIVDD | |
| | | VDDP Prewarning NMI | NMIVDDP | |
| | | Flash ECC NMI | NMIECC | |
| XINTR0 | 0003 _H | External Interrupt 0 | EX0 | IEN0 |
| XINTR1 | 000B _H | Timer 0 | ET0 | |
| XINTR2 | 0013 _H | External Interrupt 1 | EX1 | |
| XINTR3 | 001B _H | Timer 1 | ET1 | |
| XINTR4 | 0023 _H | UART | ES | |
| XINTR5 | 002B _H | T2 | ET2 | |
| | | Fractional Divider (Normal Divider Overflow) | | |
| | | LIN | | |

Functional Description

Table 15 Interrupt Vector Addresses (cont'd)

| | | | | |
|---------|-------------------|----------------------|--------|------|
| XINTR6 | 0033 _H | ADC | EADC | IEN1 |
| XINTR7 | 003B _H | SSC | ESSC | |
| XINTR8 | 0043 _H | External Interrupt 2 | EX2 | |
| XINTR9 | 004B _H | External Interrupt 3 | EXM | |
| | | External Interrupt 4 | | |
| | | External Interrupt 5 | | |
| | | External Interrupt 6 | | |
| XINTR10 | 0053 _H | CCU6 INP0 | ECCIP0 | |
| XINTR11 | 005B _H | CCU6 INP1 | ECCIP1 | |
| XINTR12 | 0063 _H | CCU6 INP2 | ECCIP2 | |
| XINTR13 | 006B _H | CCU6 INP3 | ECCIP3 | |

3.4.3 Interrupt Priority

Each interrupt source, except for NMI, can be individually programmed to one of the four possible priority levels. The NMI has the highest priority and supersedes all other interrupts. Two pairs of interrupt priority registers (IP and IPH, IP1 and IPH1) are available to program the priority level of each non-NMI interrupt vector.

A low-priority interrupt can be interrupted by a high-priority interrupt, but not by another interrupt of the same or lower priority. Further, an interrupt of the highest priority cannot be interrupted by any other interrupt source.

If two or more requests of different priority levels are received simultaneously, the request of the highest priority is serviced first. If requests of the same priority are received simultaneously, then an internal polling sequence determines which request is serviced first. Thus, within each priority level, there is a second priority structure determined by the polling sequence shown in [Table 16](#).

Table 16 Priority Structure within Interrupt Level

| Source | Level |
|---|-----------|
| Non-Maskable Interrupt (NMI) | (highest) |
| External Interrupt 0 | 1 |
| Timer 0 Interrupt | 2 |
| External Interrupt 1 | 3 |
| Timer 1 Interrupt | 4 |
| UART Interrupt | 5 |
| Timer 2, Fractional Divider, LIN Interrupts | 6 |
| ADC Interrupt | 7 |
| SSC Interrupt | 8 |
| External Interrupt 2 | 9 |
| External Interrupt [6:3] | 10 |
| CCU6 Interrupt Node Pointer 0 | 11 |
| CCU6 Interrupt Node Pointer 1 | 12 |
| CCU6 Interrupt Node Pointer 2 | 13 |
| CCU6 Interrupt Node Pointer 3 | 14 |

3.5 Parallel Ports

The SAL-XC866 has 27 port pins organized into four parallel ports, Port 0 (P0) to Port 3 (P3). Each pin has a pair of internal pull-up and pull-down devices that can be individually enabled or disabled. Ports P0, P1 and P3 are bidirectional and can be used as general purpose input/output (GPIO) or to perform alternate input/output functions for the on-chip peripherals. When configured as an output, the open drain mode can be selected. Port P2 is an input-only port, providing general purpose input functions, alternate input functions for the on-chip peripherals, and also analog inputs for the Analog-to-Digital Converter (ADC).

Bidirectional Port Features:

- Configurable pin direction
- Configurable pull-up/pull-down devices
- Configurable open drain mode
- Transfer of data through digital inputs and outputs (general purpose I/O)
- Alternate input/output for on-chip peripherals

Input Port Features:

- Configurable input driver
- Configurable pull-up/pull-down devices
- Receive of data through digital input (general purpose input)
- Alternate input for on-chip peripherals
- Analog input for ADC module

Functional Description

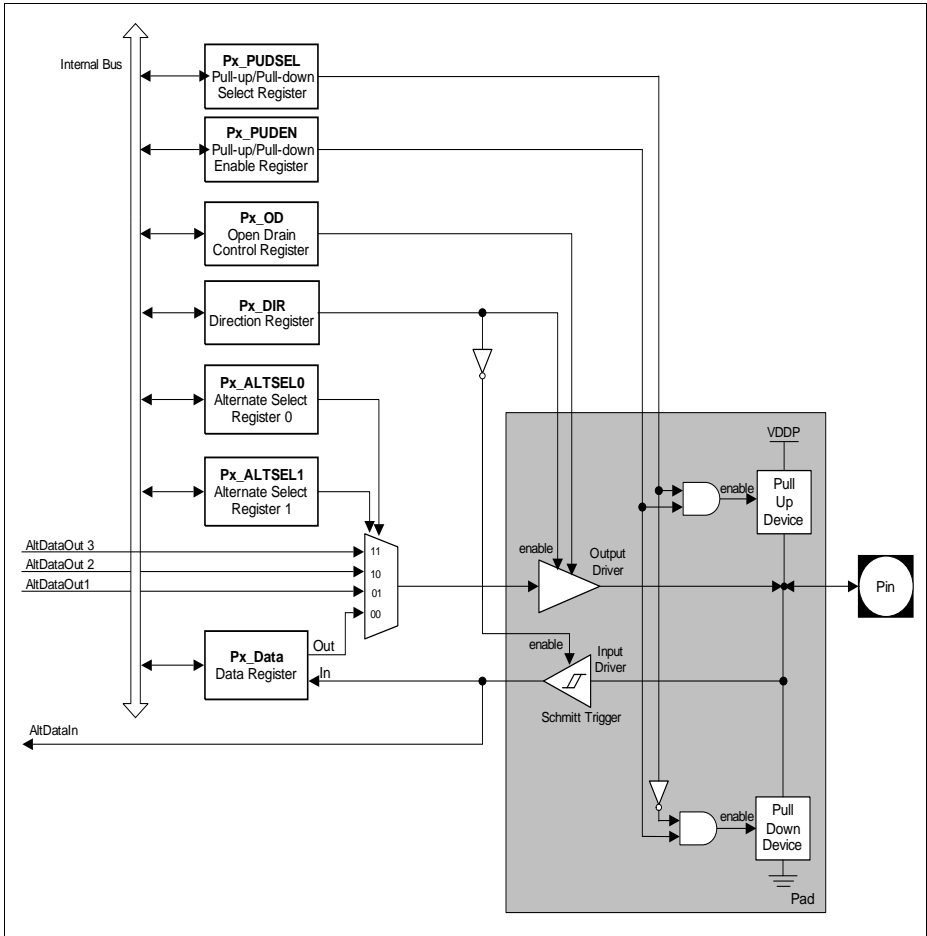


Figure 17 General Structure of Bidirectional Port

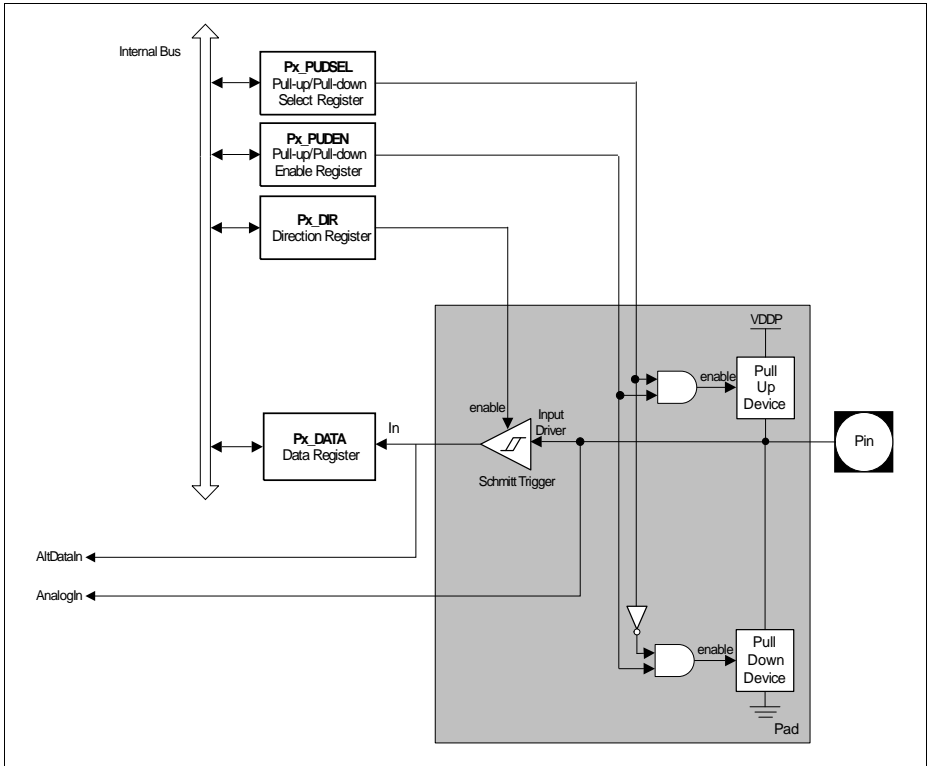


Figure 18 General Structure of Input Port

3.6 Power Supply System with Embedded Voltage Regulator

The SAL-XC866 microcontroller requires two different levels of power supply:

- 3.3 V or 5.0 V for the Embedded Voltage Regulator (EVR) and Ports
- 2.5 V for the core, memory, on-chip oscillator, and peripherals

Figure 19 shows the SAL-XC866 power supply system. A power supply of 3.3 V or 5.0 V must be provided from the external power supply pin. The 2.5 V power supply for the logic is generated by the EVR. The EVR helps to reduce the power consumption of the whole chip and the complexity of the application board design.

The EVR consists of a main voltage regulator and a low power voltage regulator. In active mode, both voltage regulators are enabled. In power-down mode, the main voltage regulator is switched off, while the low power voltage regulator continues to function and provide power supply to the system with low power consumption.

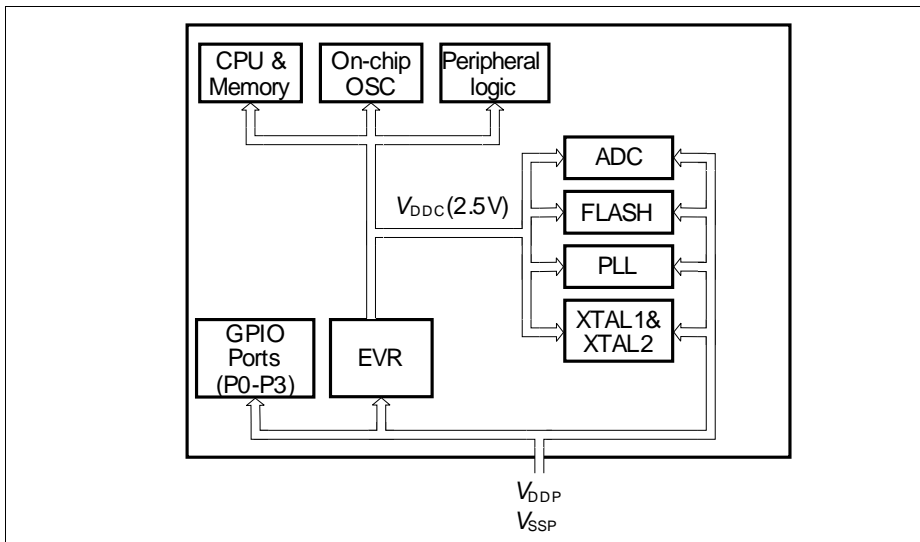


Figure 19 SAL-XC866 Power Supply System

EVR Features:

- Input voltage (V_{DDP}): 3.3 V/5.0 V
- Output voltage (V_{DDC}): 2.5 V \pm 7.5%
- Low power voltage regulator provided in power-down mode
- V_{DDC} and V_{DDP} prewarning detection
- V_{DDC} brownout detection

3.7 Reset Control

The SAL-XC866 has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the SAL-XC866 is first powered up, the status of certain pins (see [Table 18](#)) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

In order to power up the system properly, the external reset pin $\overline{\text{RESET}}$ must be asserted until V_{DDC} reaches $0.9 \cdot V_{\text{DDC}}$. The delay of external reset can be realized by an external capacitor at $\overline{\text{RESET}}$ pin. This capacitor value must be selected so that V_{RESET} reaches 0.4 V, but not before V_{DDC} reaches $0.9 \cdot V_{\text{DDC}}$.

A typical application example is shown in [Figure 20](#). V_{DDP} capacitor value is 300 nF. V_{DDC} capacitor value is 220 nF. The capacitor connected to $\overline{\text{RESET}}$ pin is 100 nF.

Typically, the time taken for V_{DDC} to reach $0.9 \cdot V_{\text{DDC}}$ is less than 50 μs once V_{DDP} reaches 2.3V. Hence, based on the condition that 10% to 90% V_{DDP} (slew rate) is less than 500 μs , the $\overline{\text{RESET}}$ pin should be held low for 500 μs typically. See [Figure 21](#).

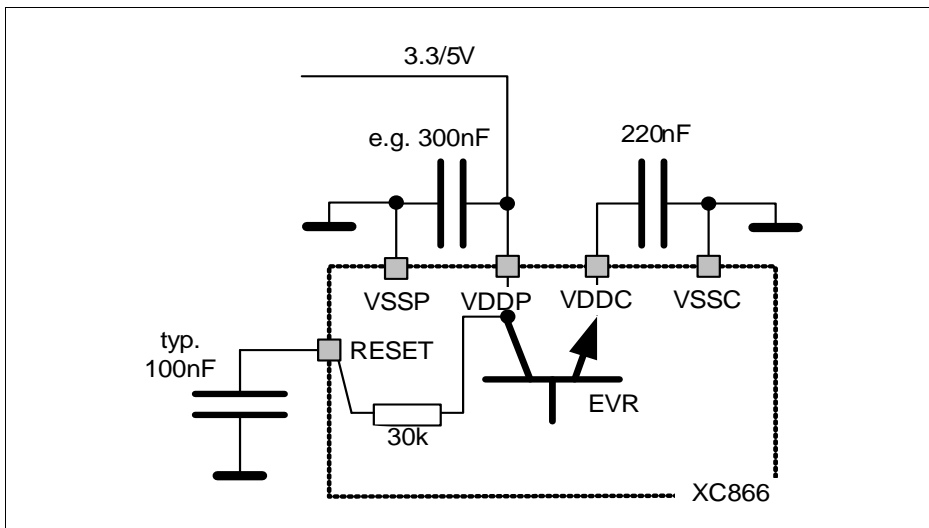


Figure 20 Reset Circuitry

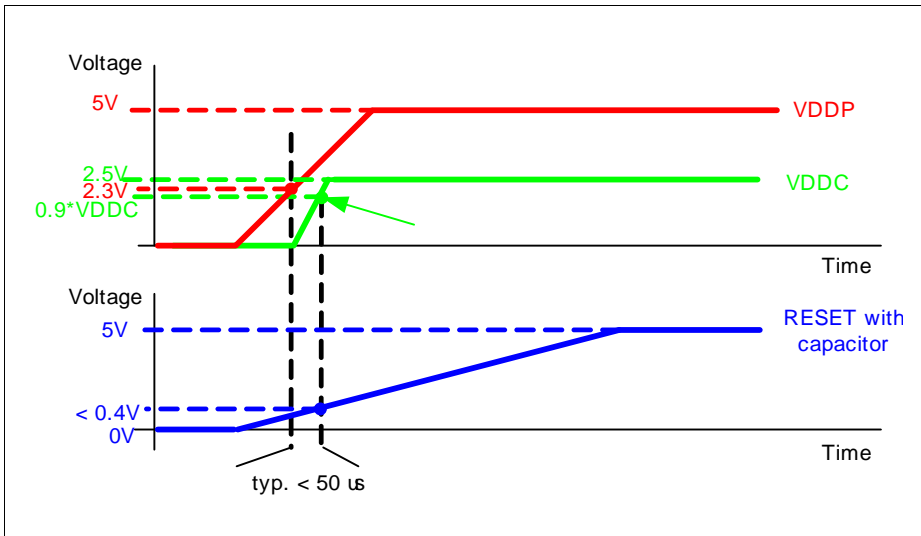


Figure 21 V_{DDP} , V_{DDC} and V_{RESET} during Power-on Reset

The second type of reset in SAL-XC866 is the hardware reset. This reset function can be used during normal operation or when the chip is in power-down mode. A reset input pin RESET is provided for the hardware reset. To ensure the recognition of the hardware reset, pin RESET must be held low for at least 100 ns.

The Watchdog Timer (WDT) module is also capable of resetting the device if it detects a malfunction in the system.

Another type of reset that needs to be detected is a reset while the device is in power-down mode (wake-up reset). While the contents of the static RAM are undefined after a power-on reset, they are well defined after a wake-up reset from power-down mode.

Functional Description
3.7.1 Module Reset Behavior

Table 17 shows how the functions of the SAL-XC866 are affected by the various reset types. A “■” means that this function is reset to its default state.

Table 17 Effect of Reset on Device Functions

| Module/ Function | Wake-Up Reset | Watchdog Reset | Hardware Reset | Power-On Reset | Brownout Reset |
|-------------------------------|--|---------------------------|---------------------------|---------------------------|---------------------------|
| CPU Core | ■ | ■ | ■ | ■ | ■ |
| Peripherals | ■ | ■ | ■ | ■ | ■ |
| On-Chip Static RAM | Not affected, reliable | Not affected, reliable | Not affected, reliable | Affected, un- reliable | Affected, un- reliable |
| Oscillator, PLL | ■ | Not affected | ■ | ■ | ■ |
| Port Pins | ■ | ■ | ■ | ■ | ■ |
| EVR | The voltage regulator is switched on | Not affected | ■ | ■ | ■ |
| FLASH | ■ | ■ | ■ | ■ | ■ |
| NMI | Disabled | Disabled | ■ | ■ | ■ |

3.7.2 Booting Scheme

When the SAL-XC866 is reset, it must identify the type of configuration with which to start the different modes once the reset sequence is complete. Thus, boot configuration information that is required for activation of special modes and conditions needs to be applied by the external world through input pins. After power-on reset or hardware reset, the pins MBC, TMS and P0.0 collectively select the different boot options. **Table 18** shows the available boot options in the SAL-XC866.

Table 18 SAL-XC866 Boot Selection

| MBC | TMS | P0.0 | Type of Mode | PC Start Value |
|-----|-----|------|---|-------------------|
| 1 | 0 | x | User Mode; on-chip OSC/PLL non-bypassed | 0000 _H |
| 0 | 0 | x | BSL Mode; on-chip OSC/PLL non-bypassed | 0000 _H |
| 0 | 1 | 0 | OCDS Mode ¹⁾ ; on-chip OSC/PLL non-bypassed | 0000 _H |
| 1 | 1 | 0 | Standalone User (JTAG) Mode ²⁾ ; on-chip OSC/PLL non-bypassed (normal) | 0000 _H |

¹⁾ The OCDS mode is not accessible if Flash is protected.

²⁾ Normal user mode with standard JTAG (TCK,TDI,TDO) pins for hot-attach purpose.

3.8 Clock Generation Unit

The Clock Generation Unit (CGU) allows great flexibility in the clock generation for the SAL-XC866. The power consumption is indirectly proportional to the frequency, whereas the performance of the microcontroller is directly proportional to the frequency. During user program execution, the frequency can be programmed for an optimal ratio between performance and power consumption. Therefore the power consumption can be adapted to the actual application state.

Features:

- Phase-Locked Loop (PLL) for multiplying clock source by different factors
- PLL Base Mode
- Prescaler Mode
- PLL Mode
- Power-down mode support

The CGU consists of an oscillator circuit and a PLL. In the SAL-XC866, the oscillator can be from either of these two sources: the on-chip oscillator (10 MHz) or the external oscillator (4 MHz to 12 MHz). The term “oscillator” is used to refer to both on-chip oscillator and external oscillator, unless otherwise stated. After the reset, the on-chip oscillator will be used by default. The external oscillator can be selected via software. In addition, the PLL provides a fail-safe logic to perform oscillator run and loss-of-lock detection. This allows emergency routines to be executed for system recovery or to perform system shut down.

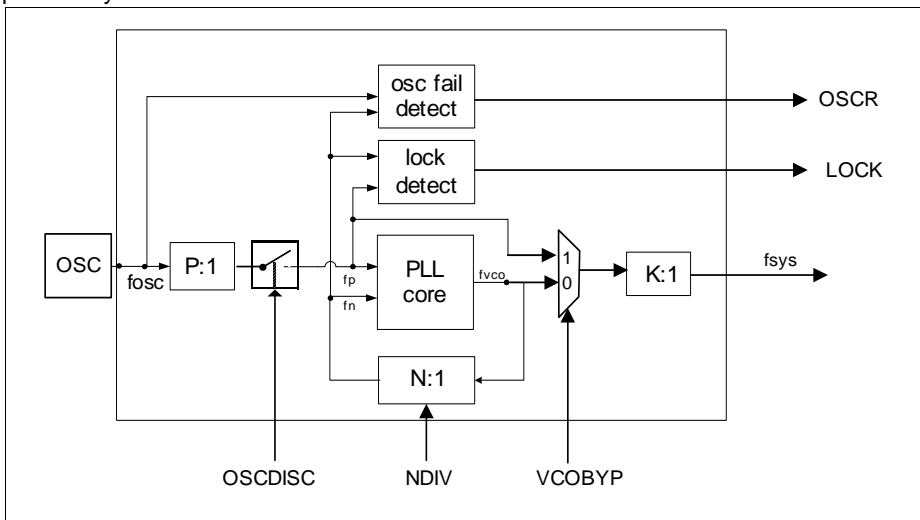


Figure 22 CGU Block Diagram

Functional Description

The clock system provides three ways to generate the system clock:

PLL Base Mode

The system clock is derived from the VCO base (free running) frequency clock divided by the K factor.

$$f_{SYS} = f_{VCObase} \times \frac{1}{K}$$

Prescaler Mode (VCO Bypass Operation)

In VCO bypass operation, the system clock is derived from the oscillator clock, divided by the P and K factors.

$$f_{SYS} = f_{OSC} \times \frac{1}{P \times K}$$

PLL Mode

The system clock is derived from the oscillator clock, multiplied by the N factor, and divided by the P and K factors. Both VCO bypass and PLL bypass must be inactive for this PLL mode. The PLL mode is used during normal system operation.

$$f_{SYS} = f_{OSC} \times \frac{N}{P \times K}$$

Table 19 shows the settings of bits OSCDISC and VCOBYP for different clock mode selection.

Table 19 Clock Mode Selection

| OSCDISC | VCOBYP | Clock Working Modes |
|---------|--------|---------------------|
| 0 | 0 | PLL Mode |
| 0 | 1 | Prescaler Mode |
| 1 | 0 | PLL Base Mode |
| 1 | 1 | PLL Base Mode |

Note: When oscillator clock is disconnected from PLL, the clock mode is PLL Base mode regardless of the setting of VCOBYP bit.

System Frequency Selection

For the SAL-XC866, the values of P and K are fixed to “1” and “2”, respectively. In order to obtain the required system frequency, f_{SYS} , the value of N can be selected by bit NDIV for different oscillator inputs. **Table 20** provides examples on how $f_{SYS} = 75$ MHz can be obtained for the different oscillator sources.

Table 20 System frequency ($f_{\text{sys}} = 75 \text{ MHz}$)

| Oscillator | f_{osc} | N | P | K | f_{sys} |
|------------|------------------|----|---|---|------------------|
| On-chip | 10 MHz | 15 | 1 | 2 | 75 MHz |
| External | 10 MHz | 15 | 1 | 2 | 75 MHz |
| | 5 MHz | 30 | 1 | 2 | 75 MHz |

Table 21 shows the VCO range for the SAL-XC866.

Table 21 VCO Range

| f_{VCOmin} | f_{VCOmax} | $f_{\text{VCOFREEmin}}$ | $f_{\text{VCOFREEmax}}$ | Unit |
|---------------------|---------------------|-------------------------|-------------------------|------|
| 150 | 200 | 20 | 80 | MHz |
| 100 | 150 | 10 | 80 | MHz |

3.8.1 Recommended External Oscillator Circuits

The oscillator circuit, a Pierce oscillator, is designed to work with both, an external crystal oscillator or an external stable clock source. It basically consists of an inverting amplifier and a feedback element with XTAL1 as input, and XTAL2 as output.

When using a crystal, a proper external oscillator circuitry must be connected to both pins, XTAL1 and XTAL2. The crystal frequency can be within the range of 4 MHz to 12 MHz. Additionally, it is necessary to have two load capacitances C_{X1} and C_{X2} , and depending on the crystal type, a series resistor R_{X2} , to limit the current. A test resistor R_Q may be temporarily inserted to measure the oscillation allowance (negative resistance) of the oscillator circuitry. R_Q values are typically specified by the crystal vendor. The C_{X1} and C_{X2} values shown in **Figure 23** can be used as starting points for the negative resistance evaluation and for non-productive systems. The exact values and related operating range are dependent on the crystal frequency and have to be determined and optimized together with the crystal vendor using the negative resistance method. Oscillation measurement with the final target system is strongly recommended to verify the input amplitude at XTAL1 and to determine the actual oscillation allowance (margin negative resistance) for the oscillator-crystal system.

When using an external clock signal, the signal must be connected to XTAL1. XTAL2 is left open (unconnected).

The oscillator can also be used in combination with a ceramic resonator. The final circuitry must also be verified by the resonator vendor.

Figure 23 shows the recommended external oscillator circuitries for both operating modes, external crystal mode and external input clock mode.

Functional Description

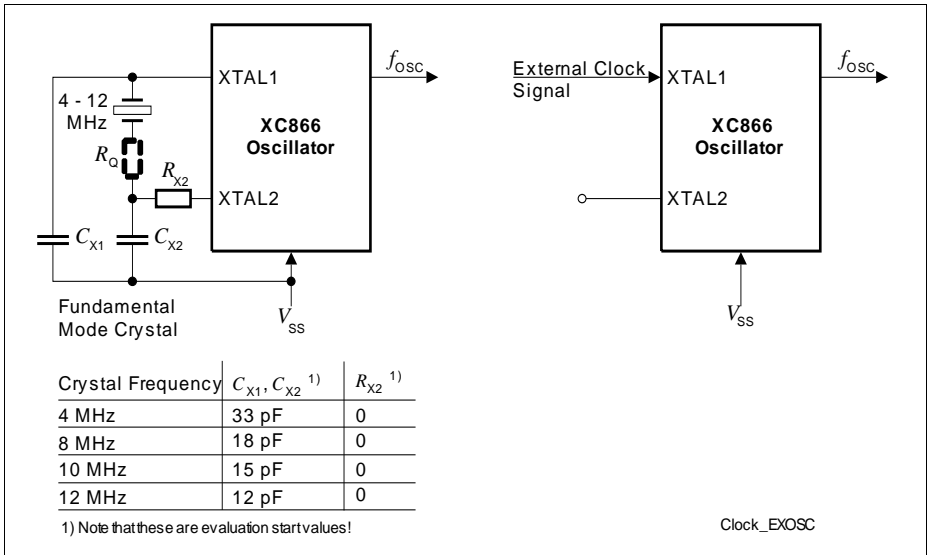


Figure 23 External Oscillator Circuitries

Note: For crystal operation, it is strongly recommended to measure the negative resistance in the final target system (layout) to determine the optimum parameters for the oscillator operation. Please refer to the minimum and maximum values of the negative resistance specified by the crystal supplier.

3.8.2 Clock Management

The CGU generates all clock signals required within the microcontroller from a single clock, f_{sys} . During normal system operation, the typical frequencies of the different modules are as follow:

- CPU clock: CCLK, SCLK = 25 MHz
- CCU6 clock: FCLK = 25 MHz
- Other peripherals: PCLK = 25 MHz
- Flash Interface clock: CCLK3 = 75 MHz and CCLK = 25 MHz

In addition, different clock frequency can output to pin CLKOUT(P0.0). The clock output frequency can further be divided by 2 using toggle latch (bit TLEN is set to 1), the resulting output frequency has 50% duty cycle. **Figure 24** shows the clock distribution of the SAL-XC866.

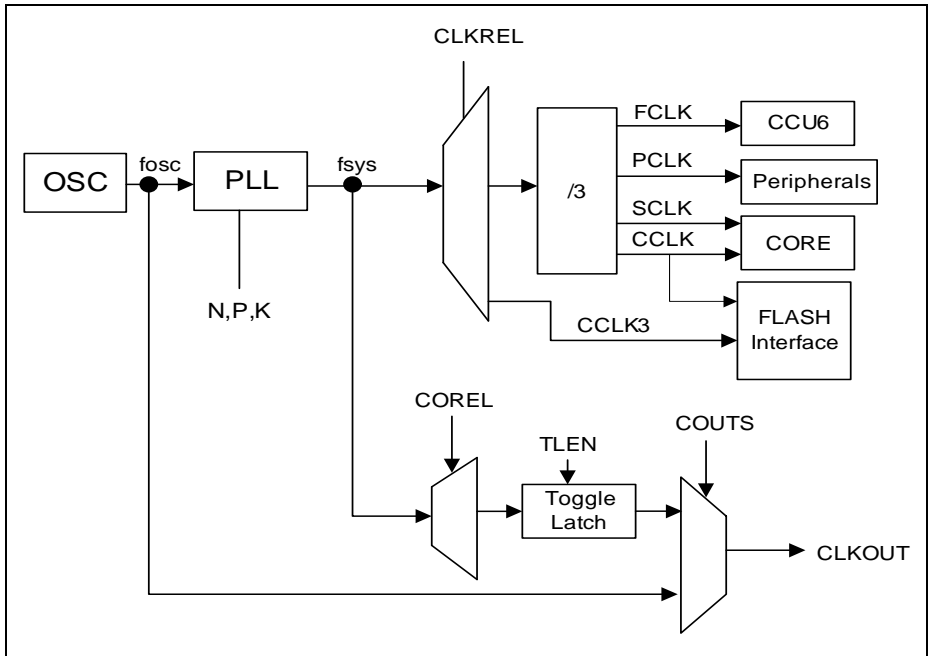


Figure 24 Clock Generation from f_{sys}

Functional Description

For power saving purposes, the clocks may be disabled or slowed down according to [Table 22](#).

Table 22 System frequency ($f_{\text{sys}} = 75 \text{ MHz}$)

| Power Saving Mode | Action |
|--------------------------|---|
| Idle | Clock to the CPU is disabled. |
| Slow-down | Clocks to the CPU and all the peripherals, including CCU6, are divided by a common programmable factor defined by bit field CMCON.CLKREL. |
| Power-down | Oscillator and PLL are switched off. |

3.9 Power Saving Modes

The power saving modes of the SAL-XC866 provide flexible power consumption through a combination of techniques, including:

- Stopping the CPU clock
- Stopping the clocks of individual system components
- Reducing clock speed of some peripheral components
- Power-down of the entire system with fast restart capability

After a reset, the active mode (normal operating mode) is selected by default (see [Figure 25](#)) and the system runs in the main system clock frequency. From active mode, different power saving modes can be selected by software. They are:

- Idle mode
- Slow-down mode
- Power-down mode

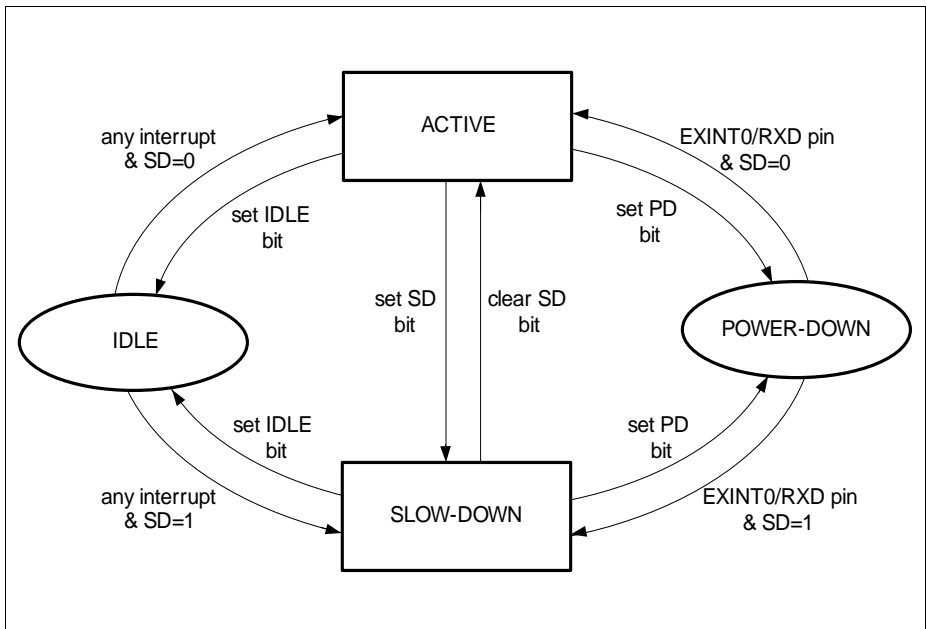


Figure 25 Transition between Power Saving Modes

3.10 Watchdog Timer

The Watchdog Timer (WDT) provides a highly reliable and secure way to detect and recover from software or hardware failures. The WDT is reset at a regular interval that is predefined by the user. The CPU must service the WDT within this interval to prevent the WDT from causing an SAL-XC866 system reset. Hence, routine service of the WDT confirms that the system is functioning properly. This ensures that an accidental malfunction of the SAL-XC866 will be aborted in a user-specified time period. In debug mode, the WDT is suspended and stops counting. Therefore, there is no need to refresh the WDT during debugging.

Features:

- 16-bit Watchdog Timer
- Programmable reload value for upper 8 bits of timer
- Programmable window boundary
- Selectable input frequency of $f_{PCLK}/2$ or $f_{PCLK}/128$
- Time-out detection with NMI generation and reset prewarning activation (after which a system reset will be performed)

The WDT is a 16-bit timer incremented by a count rate of $f_{PCLK}/2$ or $f_{PCLK}/128$. This 16-bit timer is realized as two concatenated 8-bit timers. The upper 8 bits of the WDT can be preset to a user-programmable value via a watchdog service access in order to modify the watchdog expire time period. The lower 8 bits are reset on each service access. **Figure 26** shows the block diagram of the WDT unit.

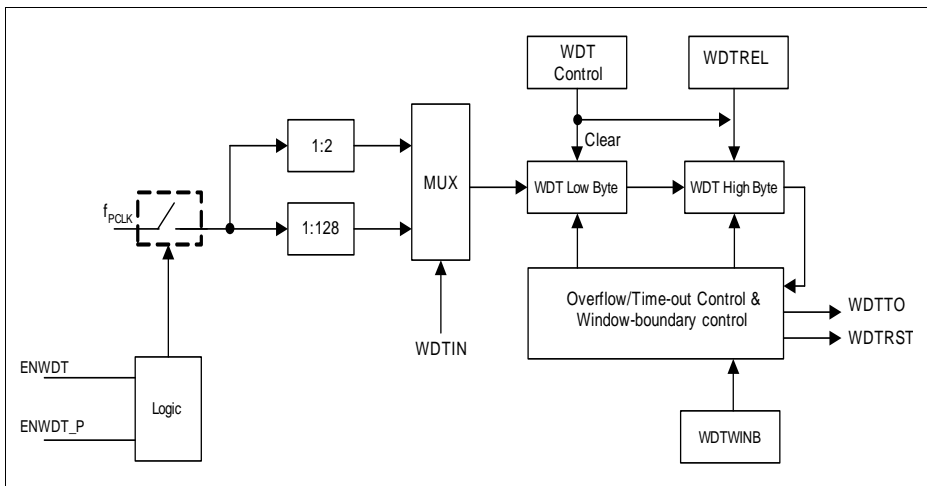


Figure 26 WDT Block Diagram

Functional Description

If the WDT is not serviced before the timer overflow, a system malfunction is assumed. As a result, the WDT NMI is triggered (assert WDTTO) and the reset prewarning is entered. The prewarning period lasts for 30_H count, after which the system is reset (assert WDRST).

The WDT has a “programmable window boundary” which disallows any refresh during the WDT’s count-up. A refresh during this window boundary constitutes an invalid access to the WDT, causing the reset prewarning to be entered but without triggering the WDT NMI. The system will still be reset after the prewarning period is over. The window boundary is from 0000_H to the value obtained from the concatenation of WDTWINB and 00_H.

After being serviced, the WDT continues counting up from the value (<WDTREL> * 2⁸). The time period for an overflow of the WDT is programmable in two ways:

- the input frequency to the WDT can be selected to be either f_{PCLK}/2 or f_{PCLK}/128
- the reload value WDTREL for the high byte of WDT can be programmed in register WDTREL

The period, P_{WDT}, between servicing the WDT and the next overflow can be determined by the following formula:

$$P_{WDT} = \frac{2^{(1 + WDTIN \times 6)} \times (2^{16} - WDTREL \times 2^8)}{f_{PCLK}}$$

If the Window-Boundary Refresh feature of the WDT is enabled, the period P_{WDT} between servicing the WDT and the next overflow is shortened if WDTWINB is greater than WDTREL, see [Figure 27](#). This period can be calculated using the same formula by replacing WDTREL with WDTWINB. For this feature to be useful, WDTWINB should not be smaller than WDTREL.

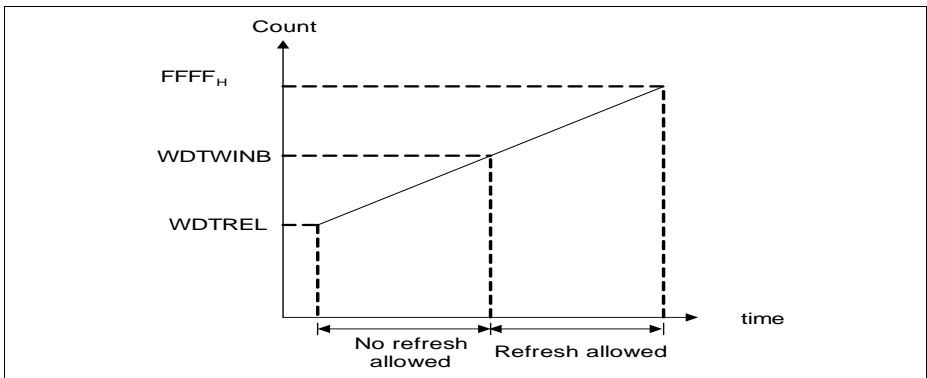


Figure 27 WDT Timing Diagram

Functional Description

Table 23 lists the possible watchdog time range that can be achieved for different module clock frequencies. Some numbers are rounded to 3 significant digits.

Table 23 Watchdog Time Ranges

| Reload value in WDTREL | Prescaler for f_{PCLK} | |
|---------------------------|--------------------------|-----------------|
| | 2 (WDTIN = 0) | 128 (WDTIN = 1) |
| | 25 MHz | 25 MHz |
| FF _H | 20.5 μ s | 1.31 ms |
| 7F _H | 2.64 ms | 169 ms |
| 00 _H | 5.24 ms | 336 ms |

3.11 Universal Asynchronous Receiver/Transmitter

The Universal Asynchronous Receiver/Transmitter (UART) provides a full-duplex asynchronous receiver/transmitter, i.e., it can transmit and receive simultaneously. It is also receive-buffered, i.e., it can commence reception of a second byte before a previously received byte has been read from the receive register. However, if the first byte still has not been read by the time reception of the second byte is complete, one of the bytes will be lost.

Features:

- Full-duplex asynchronous modes
 - 8-bit or 9-bit data frames, LSB first
 - fixed or variable baud rate
- Receive buffered
- Multiprocessor communication
- Interrupt generation on the completion of a data transmission or reception

The UART can operate in four asynchronous modes as shown in [Table 24](#). Data is transmitted on TXD and received on RXD.

Table 24 **UART Modes**

| Operating Mode | Baud Rate |
|------------------------------|--------------------------------|
| Mode 0: 8-bit shift register | $f_{PCLK}/2$ |
| Mode 1: 8-bit shift UART | Variable |
| Mode 2: 9-bit shift UART | $f_{PCLK}/32$ or $f_{PCLK}/64$ |
| Mode 3: 9-bit shift UART | Variable |

There are several ways to generate the baud rate clock for the serial port, depending on the mode in which it is operating. In mode 0, the baud rate for the transfer is fixed at $f_{PCLK}/2$. In mode 2, the baud rate is generated internally based on the UART input clock and can be configured to either $f_{PCLK}/32$ or $f_{PCLK}/64$. The variable baud rate is set by either the underflow rate on the dedicated baud-rate generator, or by the overflow rate on Timer 1.

3.11.1 Baud-Rate Generator

The baud-rate generator is based on a programmable 8-bit reload value, and includes divider stages (i.e., prescaler and fractional divider) for generating a wide range of baud rates based on its input clock f_{PCLK} , see [Figure 28](#).

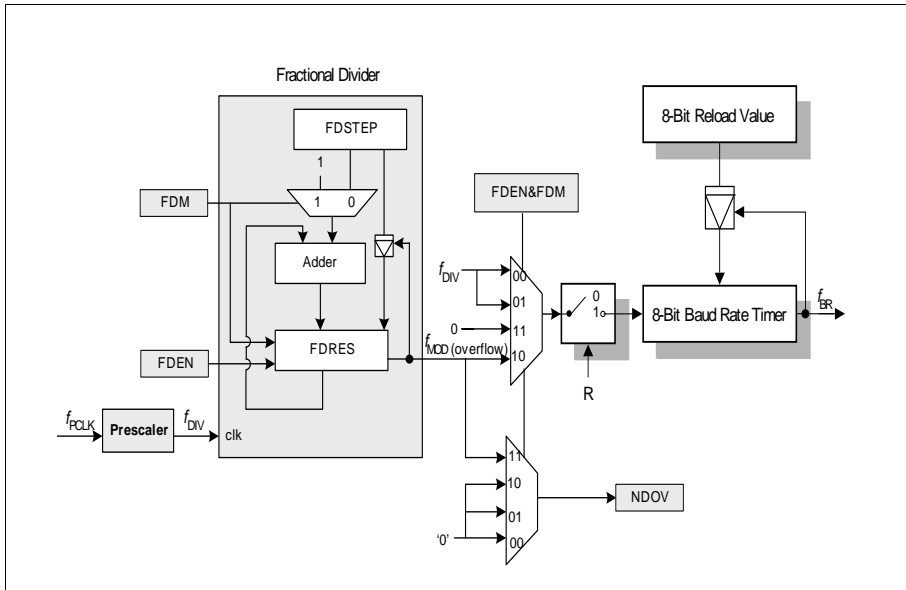


Figure 28 Baud-rate Generator Circuitry

The baud rate timer is a count-down timer and is clocked by either the output of the fractional divider (f_{MOD}) if the fractional divider is enabled ($FDCON.FDEN = 1$), or the output of the prescaler (f_{DIV}) if the fractional divider is disabled ($FDEN = 0$). For baud rate generation, the fractional divider must be configured to fractional divider mode ($FDCON.FDM = 0$). This allows the baud rate control run bit $BCON.R$ to be used to start or stop the baud rate timer. At each timer underflow, the timer is reloaded with the 8-bit reload value in register BG and one clock pulse is generated for the serial channel.

Enabling the fractional divider in normal divider mode ($FDEN = 1$ and $FDM = 1$) stops the baud rate timer and nullifies the effect of bit $BCON.R$. See [Section 3.12](#).

The baud rate (f_{BR}) value is dependent on the following parameters:

- Input clock f_{PCLK}
- Prescaling factor (2^{BRPRE}) defined by bit field $BRPRE$ in register $BCON$
- Fractional divider ($STEP/256$) defined by register $FDSTEP$
(to be considered only if fractional divider is enabled and operating in fractional divider mode)

Functional Description

- 8-bit reload value (BR_VALUE) for the baud rate timer defined by register BG

The following formulas calculate the final baud rate without and with the fractional divider respectively:

$$\text{baud rate} = \frac{f_{\text{PCLK}}}{16 \times 2^{\text{BRPRE}} \times (\text{BR_VALUE} + 1)} \quad \text{where } 2^{\text{BRPRE}} \times (\text{BR_VALUE} + 1) > 1$$

$$\text{baud rate} = \frac{f_{\text{PCLK}}}{16 \times 2^{\text{BRPRE}} \times (\text{BR_VALUE} + 1)} \times \frac{\text{STEP}}{256}$$

The maximum baud rate that can be generated is limited to $f_{\text{PCLK}}/32$. Hence, for a module clock of 25 MHz, the maximum achievable baud rate is 0.78 MBaud.

Standard LIN protocol can support a maximum baud rate of 20kHz, the baud rate accuracy is not critical and the fractional divider can be disabled. Only the prescaler is used for auto baud rate calculation. For LIN fast mode, which supports the baud rate of 20kHz to 115.2kHz, the higher baud rates require the use of the fractional divider for greater accuracy.

Table 25 lists the various commonly used baud rates with their corresponding parameter settings and deviation errors. The fractional divider is disabled and a module clock of 25 MHz is used.

Table 25 Typical Baud rates for UART with Fractional Divider disabled

| Baud rate | Prescaling Factor (2^{BRPRE}) | Reload Value (BR_VALUE + 1) | Deviation Error |
|------------|---|--------------------------------|-----------------|
| 19.2 kBaud | 1 (BRPRE=000 _B) | 81 (51 _H) | -0.47 % |
| 9600 Baud | 1 (BRPRE=000 _B) | 162 (A2 _H) | -0.47 % |
| 4800 Baud | 2 (BRPRE=001 _B) | 162 (A2 _H) | -0.47 % |
| 2400 Baud | 4 (BRPRE=010 _B) | 162 (A2 _H) | -0.47 % |

The fractional divider allows baud rates of higher accuracy (lower deviation error) to be generated. **Table 26** lists the resulting deviation errors from generating a baud rate of 115.2 kHz, using different module clock frequencies. The fractional divider is enabled (fractional divider mode) and the corresponding parameter settings are shown.

Table 26 Deviation Error for UART with Fractional Divider enabled

| f_{PCLK} | Prescaling Factor (2^{BRPRE}) | Reload Value (BR_VALUE + 1) | STEP | Deviation Error |
|------------|--------------------------------------|--------------------------------|------------------------|-----------------|
| 25 MHz | 1 | 10 (A _H) | 189 (BD _H) | +0.14 % |
| 12.5 MHz | 1 | 6 (6 _H) | 226 (E2 _H) | -0.22 % |
| 6.25 MHz | 1 | 3 (3 _H) | 226 (E2 _H) | -0.22 % |

3.11.2 Baud Rate Generation using Timer 1

In UART modes 1 and 3, Timer 1 can be used for generating the variable baud rates. In theory, this timer could be used in any of its modes. But in practice, it should be set into auto-reload mode (Timer 1 mode 2), with its high byte set to the appropriate value for the required baud rate. The baud rate is determined by the Timer 1 overflow rate and the value of SMOD as follows:

$$\text{Mode 1, 3 baud rate} = \frac{2^{\text{SMOD}} \times f_{\text{PCLK}}}{32 \times 2 \times (256 - \text{TH1})} \quad [3.1]$$

3.12 Normal Divider Mode (8-bit Auto-reload Timer)

Setting bit FDM in register FDCON to 1 configures the fractional divider to normal divider mode, while at the same time disables baud rate generation (see [Figure 28](#)). Once the fractional divider is enabled (FDEN = 1), it functions as an 8-bit auto-reload timer (with no relation to baud rate generation) and counts up from the reload value with each input clock pulse. Bit field RESULT in register FDRES represents the timer value, while bit field STEP in register FDSTEP defines the reload value. At each timer overflow, an overflow flag (FDCON.NDOV) will be set and an interrupt request generated. This gives an output clock f_{MOD} that is 1/n of the input clock f_{DIV} , where n is defined by 256 - STEP.

The output frequency in normal divider mode is derived as follows:

$$f_{\text{MOD}} = f_{\text{DIV}} \times \frac{1}{256 - \text{STEP}} \quad [3.2]$$

3.13 LIN Protocol

The UART can be used to support the Local Interconnect Network (LIN) protocol for both master and slave operations. The LIN baud rate detection feature provides the capability to detect the baud rate within LIN protocol using Timer 2. This allows the UART to be synchronized to the LIN baud rate for data transmission and reception.

LIN is a holistic communication concept for local interconnected networks in vehicles. The communication is based on the SCI (UART) data format, a single-master/multiple-slave concept, a clock synchronization for nodes without stabilized time base. An attractive feature of LIN is self-synchronization of the slave nodes without a crystal or ceramic resonator, which significantly reduces the cost of hardware platform. Hence, the baud rate must be calculated and returned with every message frame.

The structure of a LIN frame is shown in **Figure 29**. The frame consists of the:

- header, which comprises a Break (13-bit time low), Synch Byte (55_H), and ID field
- response time
- data bytes (according to UART protocol)
- checksum

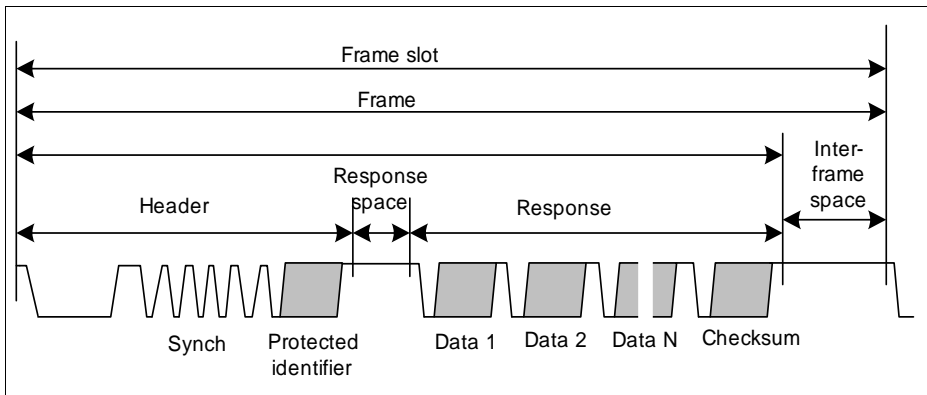


Figure 29 Structure of LIN Frame

3.13.1 LIN Header Transmission

LIN header transmission is only applicable in master mode. In the LIN communication, a master task decides when and which frame is to be transferred on the bus. It also identifies a slave task to provide the data transported by each frame. The information needed for the handshaking between the master and slave tasks is provided by the master task through the header portion of the frame.

The header consists of a break and synch pattern followed by an identifier. Among these three fields, only the break pattern cannot be transmitted as a normal 8-bit UART data.

Functional Description

The break must contain a dominant value of 13 bits or more to ensure proper synchronization of slave nodes.

In the LIN communication, a slave task is required to be synchronized at the beginning of the protected identifier field of frame. For this purpose, every frame starts with a sequence consisting of a break field followed by a synch byte field. This sequence is unique and provides enough information for any slave task to detect the beginning of a new frame and be synchronized at the start of the identifier field.

Upon entering LIN communication, a connection is established and the transfer speed (baud rate) of the serial communication partner (host) is automatically synchronized in the following steps:

STEP 1: Initialize interface for reception and timer for baud rate measurement

STEP 2: Wait for an incoming LIN frame from host

STEP 3: Synchronize the baud rate to the host

STEP 4: Enter for Master Request Frame or for Slave Response Frame

*Note: Re-synchronization and setup of baud rate are always done for **every** Master Request Header or Slave Response Header LIN frame.*

3.14 High-Speed Synchronous Serial Interface

The High-Speed Synchronous Serial Interface (SSC) supports full-duplex and half-duplex synchronous communication. The serial clock signal can be generated by the SSC internally (master mode), using its own 16-bit baud-rate generator, or can be received from an external master (slave mode). Data width, shift direction, clock polarity and phase are programmable. This allows communication with SPI-compatible devices or devices using other synchronous serial interfaces.

Features:

- Master and slave mode operation
 - Full-duplex or half-duplex operation
- Transmit and receive buffered
- Flexible data format
 - Programmable number of data bits: 2 to 8 bits
 - Programmable shift direction: LSB or MSB shift first
 - Programmable clock polarity: idle low or high state for the shift clock
 - Programmable clock/data phase: data shift with leading or trailing edge of the shift clock
- Variable baud rate
- Compatible with Serial Peripheral Interface (SPI)
- Interrupt generation
 - On a transmitter empty condition
 - On a receiver full condition
 - On an error condition (receive, phase, baud rate, transmit error)

Functional Description

Data is transmitted or received on lines TXD and RXD, which are normally connected to the pins MTSR (Master Transmit/Slave Receive) and MRST (Master Receive/Slave Transmit). The clock signal is output via line MS_CLK (Master Serial Shift Clock) or input via line SS_CLK (Slave Serial Shift Clock). Both lines are normally connected to the pin SCLK. Transmission and reception of data are double-buffered.

Figure 30 shows the block diagram of the SSC.

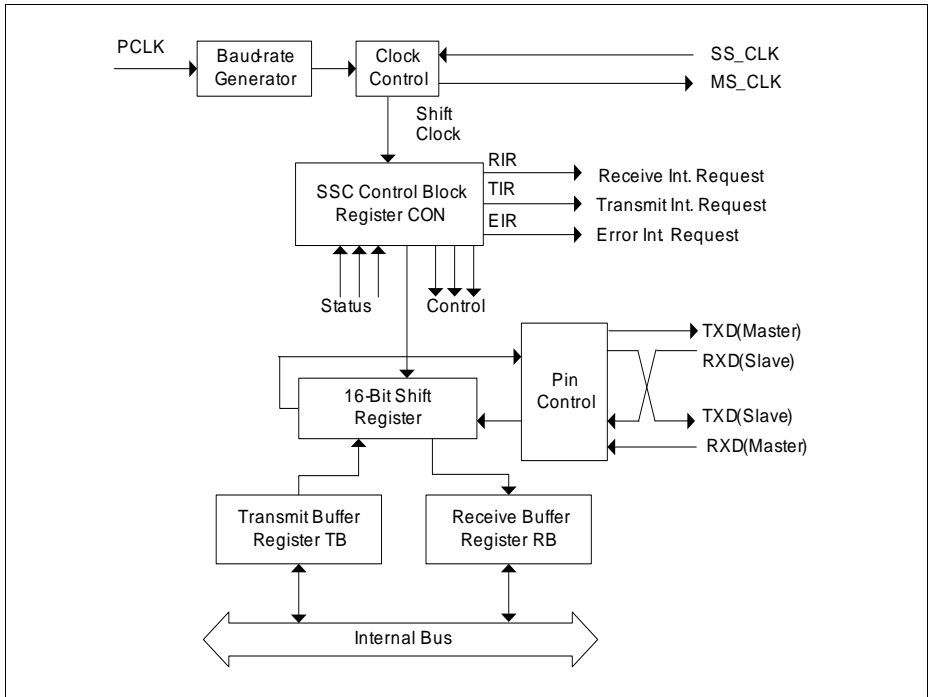


Figure 30 SSC Block Diagram

3.15 Timer 0 and Timer 1

Timers 0 and 1 are count-up timers which are incremented every machine cycle, or in terms of the input clock, every 2 PCLK cycles. They are fully compatible and can be configured in four different operating modes for use in a variety of applications, see [Table 27](#). In modes 0, 1 and 2, the two timers operate independently, but in mode 3, their functions are specialized.

Table 27 Timer 0 and Timer 1 Modes

| Mode | Operation |
|----------|---|
| 0 | 13-bit timer The timer is essentially an 8-bit counter with a divide-by-32 prescaler. This mode is included solely for compatibility with Intel 8048 devices. |
| 1 | 16-bit timer The timer registers, TLx and THx, are concatenated to form a 16-bit counter. |
| 2 | 8-bit timer with auto-reload The timer register TLx is reloaded with a user-defined 8-bit value in THx upon overflow. |
| 3 | Timer 0 operates as two 8-bit timers The timer registers, TL0 and TH0, operate as two separate 8-bit counters. Timer 1 is halted and retains its count even if enabled. |

3.16 Timer 2

Timer 2 is a 16-bit general purpose timer (THL2) that has two modes of operation, a 16-bit auto-reload mode and a 16-bit one channel capture mode. If the prescaler is disabled, Timer 2 counts with an input clock of PCLK/12. Timer 2 continues counting as long as it is enabled.

Table 28 Timer 2 Modes

| Mode | Description |
|------------------------|---|
| Auto-reload | Up/Down Count Disabled <ul style="list-style-type: none"> • Count up only • Start counting from 16-bit reload value, overflow at $FFFF_H$ • Reload event configurable for trigger by overflow condition only, or by negative/positive edge at input pin T2EX as well • Programmable reload value in register RC2 • Interrupt is generated with reload event |
| | Up/Down Count Enabled <ul style="list-style-type: none"> • Count up or down, direction determined by level at input pin T2EX • No interrupt is generated • Count up <ul style="list-style-type: none"> – Start counting from 16-bit reload value, overflow at $FFFF_H$ – Reload event triggered by overflow condition – Programmable reload value in register RC2 • Count down <ul style="list-style-type: none"> – Start counting from $FFFF_H$, underflow at value defined in register RC2 – Reload event triggered by underflow condition – Reload value fixed at $FFFF_H$ |
| Channel capture | <ul style="list-style-type: none"> • Count up only • Start counting from 0000_H, overflow at $FFFF_H$ • Reload event triggered by overflow condition • Reload value fixed at 0000_H • Capture event triggered by falling/rising edge at pin T2EX • Captured timer value stored in register RC2 • Interrupt is generated with reload or capture event |

3.17 Capture/Compare Unit 6

The Capture/Compare Unit 6 (CCU6) provides two independent timers (T12, T13), which can be used for Pulse Width Modulation (PWM) generation, especially for AC-motor control. The CCU6 also supports special control modes for block commutation and multi-phase machines.

The timer T12 can function in capture and/or compare mode for its three channels. The timer T13 can work in compare mode only.

The multi-channel control unit generates output patterns, which can be modulated by T12 and/or T13. The modulation sources can be selected and combined for the signal modulation.

Timer T12 Features:

- Three capture/compare channels, each channel can be used either as a capture or as a compare channel
- Supports generation of a three-phase PWM (six outputs, individual signals for highside and lowside switches)
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Dead-time control for each channel to avoid short-circuits in the power stage
- Concurrent update of the required T12/13 registers
- Generation of center-aligned and edge-aligned PWM
- Supports single-shot mode
- Supports many interrupt request sources
- Hysteresis-like control mode

Timer T13 Features:

- One independent compare channel with one output
- 16-bit resolution, maximum count frequency = peripheral clock frequency
- Can be synchronized to T12
- Interrupt generation at period-match and compare-match
- Supports single-shot mode

Additional Features:

- Implements block commutation for Brushless DC-drives
- Position detection via Hall-sensor pattern
- Automatic rotational speed measurement for block commutation
- Integrated error handling
- Fast emergency stop without CPU load via external signal ($\overline{\text{CTRAP}}$)
- Control modes for multi-channel AC-drives
- Output levels can be selected and adapted to the power stage

Functional Description

The block diagram of the CCU6 module is shown in **Figure 31**.

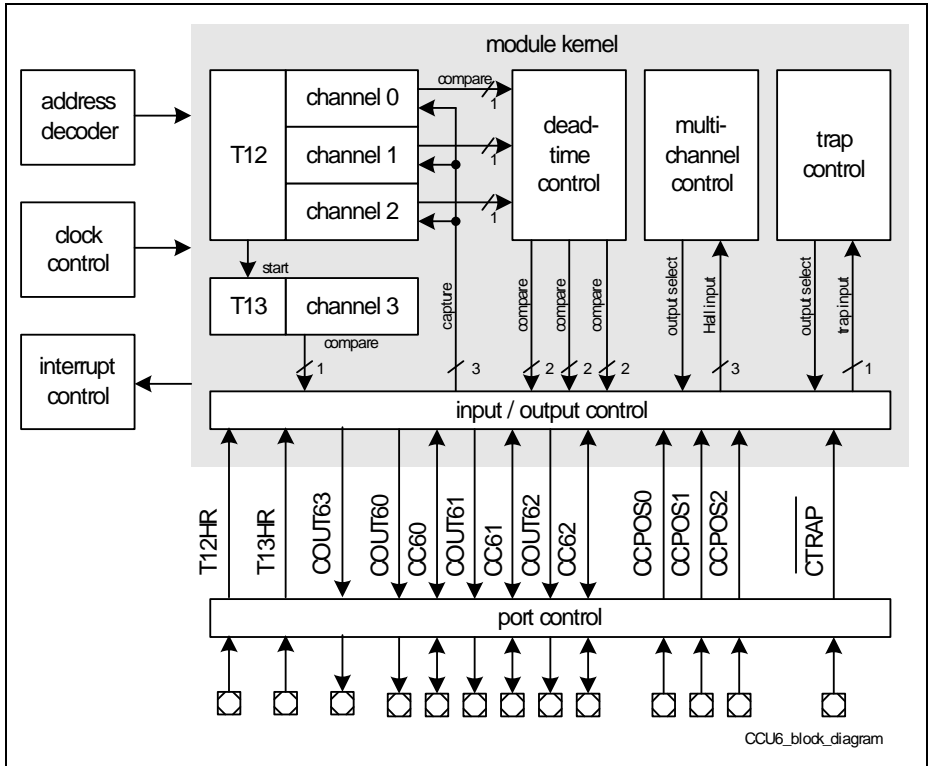


Figure 31 CCU6 Block Diagram

3.18 Analog-to-Digital Converter

The SAL-XC866 includes a high-performance 10-bit Analog-to-Digital Converter (ADC) with eight multiplexed analog input channels. The ADC uses a successive approximation technique to convert the analog voltage levels from up to eight different sources. The analog input channels of the ADC are available at Port 2.

Features:

- Successive approximation
- 8-bit or 10-bit resolution
- Eight analog channels
- Four independent result registers
- Result data protection for slow CPU access (wait-for-read mode)
- Single conversion mode
- Autoscan functionality
- Limit checking for conversion results
- Data reduction filter (accumulation of up to 2 conversion results)
- Two independent conversion request sources with programmable priority
- Selectable conversion request trigger
- Flexible interrupt generation with configurable service nodes
- Programmable sample time
- Programmable clock divider
- Cancel/restart feature for running conversions
- Integrated sample and hold circuitry
- Compensation of offset errors
- Low power modes

3.18.1 ADC Clocking Scheme

A common module clock f_{ADC} generates the various clock signals used by the analog and digital parts of the ADC module:

- f_{ADCA} is input clock for the analog part.
- f_{ADCI} is internal clock for the analog part (defines the time base for conversion length and the sample time). This clock is generated internally in the analog part, based on the input clock f_{ADCA} to generate a correct duty cycle for the analog components.
- f_{ADCD} is input clock for the digital part.

The internal clock for the analog part f_{ADCI} is limited to a maximum frequency of 10 MHz. Therefore, the ADC clock prescaler must be programmed to a value that ensures f_{ADCI} does not exceed 10 MHz. The prescaler ratio is selected by bit field CTC in register GLOBCTR. A prescaling ratio of 32 can be selected when the maximum performance of the ADC is not required.

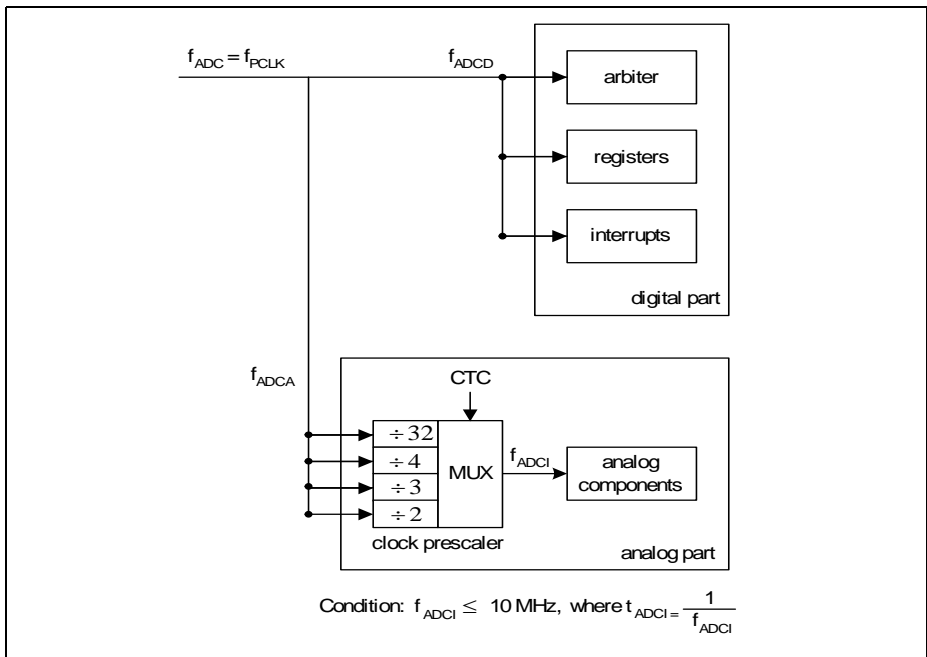


Figure 32 ADC Clocking Scheme

Functional Description

For module clock $f_{ADC} = 25$ MHz, the analog clock f_{ADCI} frequency can be selected as shown in **Table 29**.

Table 29 f_{ADCI} Frequency Selection

| Module Clock f_{ADC} | CTC | Prescaling Ratio | Analog Clock f_{ADCI} |
|------------------------|---------------------------|------------------|-------------------------|
| 25 MHz | 00 _B | ÷ 2 | 12.5 MHz (N.A) |
| | 01 _B | ÷ 3 | 8.3 MHz |
| | 10 _B | ÷ 4 | 6.3 MHz |
| | 11 _B (default) | ÷ 32 | 781.3 kHz |

As f_{ADCI} cannot exceed 10 MHz, bit field CTC should not be set to 00_B when f_{ADC} is 25 MHz. During slow-down mode where f_{ADC} may be reduced to 12.5 MHz, 6.25 MHz etc., CTC can be set to 00_B as long as the divided analog clock f_{ADCI} does not exceed 10 MHz. However, it is important to note that the conversion error could increase due to loss of charges on the capacitors, if f_{ADC} becomes too low during slow-down mode.

3.18.2 ADC Conversion Sequence

The analog-to-digital conversion procedure consists of the following phases:

- Synchronization phase (t_{SYN})
- Sample phase (t_S)
- Conversion phase
- Write result phase (t_{WR})

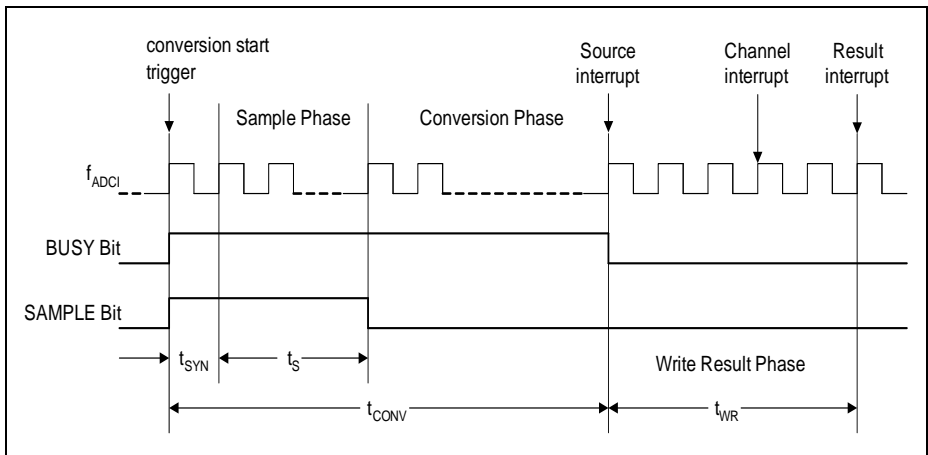


Figure 33 ADC Conversion Timing

3.19 On-Chip Debug Support

The On-Chip Debug Support (OCDS) provides the basic functionality required for the software development and debugging of XC800-based systems.

The OCDS design is based on these principles:

- use the built-in debug functionality of the XC800 Core
- add a minimum of hardware overhead
- provide support for most of the operations by a Monitor Program
- use standard interfaces to communicate with the Host (a Debugger)

Features:

- Set breakpoints on instruction address and within a specified address range
- Set breakpoints on internal RAM address
- Support unlimited software breakpoints in Flash/RAM code region
- Process external breaks
- Step through the program code

The OCDS functional blocks are shown in [Figure 34](#). The Monitor Mode Control (MMC) block at the center of OCDS system brings together control signals and supports the overall functionality. The MMC communicates with the XC800 Core, primarily via the Debug Interface, and also receives reset and clock signals. After processing memory address and control signals from the core, the MMC provides proper access to the dedicated extra-memories: a Monitor ROM (holding the code) and a Monitor RAM (for work-data and Monitor-stack). The OCDS system is accessed through the JTAG¹⁾, which is an interface dedicated exclusively for testing and debugging activities and is not normally used in an application. The dedicated MBC pin is used for external configuration and debugging control.

Note: All the debug functionality described here can normally be used only after SAL-XC866 has been started in OCDS mode.

¹⁾ The pins of the JTAG port can be assigned to either Port 0 (primary) or Ports 1 and 2 (secondary). User must set the JTAG pins (TCK and TDI) as input during connection with the OCDS system.

Functional Description

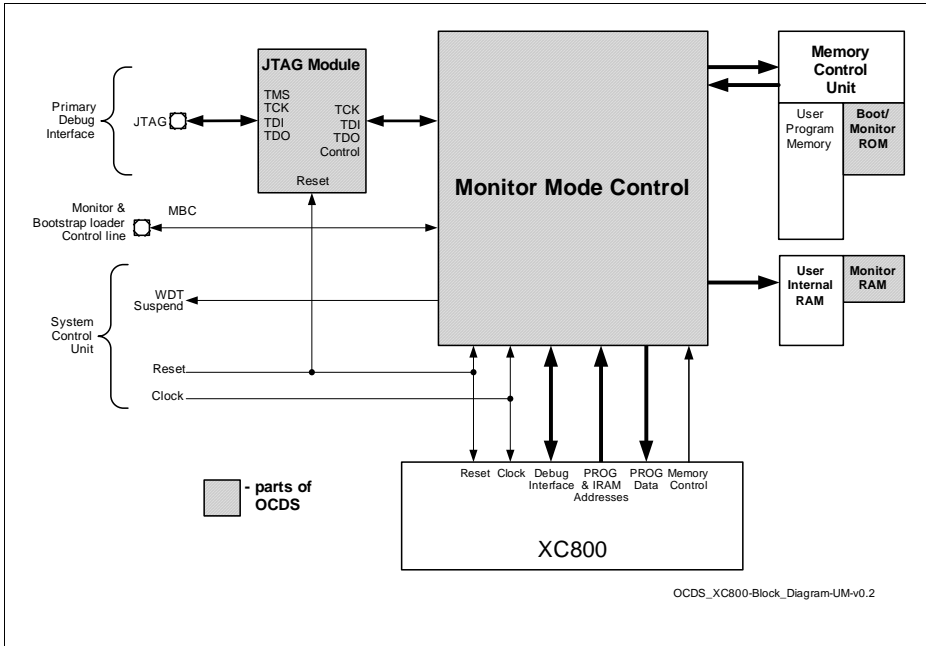


Figure 34 OCDS Block Diagram

3.19.1 JTAG ID Register

This is a read-only register located inside the JTAG module, and is used to recognize the device(s) connected to the JTAG interface. Its content is shifted out when INSTRUCTION register contains the IDCODE command (opcode 04_H), and the same is also true immediately after reset.

The JTAG ID register contents for the SAL-XC866 devices are given in [Table 30](#).

Table 30 JTAG ID Summary

| Device Type | Device Name | JTAG ID |
|-------------|-----------------|------------------------|
| Flash | SAL-XC866L-4FRA | 1010 0083 _H |
| | SAL-XC866L-2FRA | 1010 2083 _H |

Functional Description

3.20 Identification Register

The SAL-XC866 identity register is located at Page 1 of address B3_H.

ID

Identity Register

Reset Value: 0000 0010_B



| Field | Bits | Type | Description |
|--------|-------|------|----------------------------------|
| VERID | [2:0] | r | Version ID 010 _B |
| PRODID | [7:3] | r | Product ID 00000 _B |

4 Electrical Parameters

Chapter 4 provides the characteristics of the electrical parameters which are implementation-specific for the SAL-XC866.

4.1 General Parameters

The general parameters are described here to aid the users in interpreting the parameters mainly in [Section 4.2](#) and [Section 4.3](#).

4.1.1 Parameter Interpretation

The parameters listed in this section represent partly the characteristics of the SAL-XC866 and partly its requirements on the system. To aid interpreting the parameters easily when evaluating them for a design, they are indicated by the abbreviations in the "Symbol" column:

- **CC**
These parameters indicate **C**ontroller **C**haracteristics, which are distinctive features of the SAL-XC866 and must be regarded for a system design.
- **SR**
These parameters indicate **S**ystem **R**equirements, which must be provided by the microcontroller system in which the SAL-XC866 is designed in.

4.1.2 Absolute Maximum Rating

Maximum ratings are the extreme limits to which the SAL-XC866 can be subjected to without permanent damage.

Table 31 Absolute Maximum Rating Parameters

| Parameter | Symbol | Limit Values | | Unit | Notes |
|--|------------------|--------------|---------------------------|------|----------------------------------|
| | | min. | max. | | |
| Ambient temperature | T_A | -40 | 150 | °C | under bias |
| Storage temperature | T_{ST} | -65 | 150 | °C | ¹⁾ |
| Junction temperature | T_J | -40 | 160 | °C | under bias ¹⁾ |
| Voltage on power supply pin with respect to V_{SS} | V_{DDP} | -0.5 | 6 | V | ¹⁾ |
| Voltage on any pin with respect to V_{SS} | V_{IN} | -0.5 | $V_{DDP} + 0.5$ or max. 6 | V | Whichever is lower ¹⁾ |
| Input current on any pin during overload condition | I_{IN} | -10 | 10 | mA | ¹⁾ |
| Absolute sum of all input currents during overload condition | $\Sigma I_{IN} $ | – | 50 | mA | ¹⁾ |

¹⁾ Not subjected to production test, verified by design/characterization.

Note: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. During absolute maximum rating overload conditions ($V_{IN} > V_{DDP}$ or $V_{IN} < V_{SS}$) the voltage on V_{DDP} pin with respect to ground (V_{SS}) must not exceed the values defined by the absolute maximum ratings.

4.1.3 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation of the SAL-XC866. All parameters mentioned in the following table refer to these operating conditions, unless otherwise noted.

Table 32 Operating Condition Parameters

| Parameter | Symbol | Limit Values | | Unit | Notes/ Conditions |
|--------------------------------------|-----------|--------------|------|------|----------------------|
| | | min. | max. | | |
| Digital power supply voltage | V_{DDP} | 4.5 | 5.5 | V | 5V Device |
| Digital power supply voltage | V_{DDP} | 3.0 | 3.6 | V | 3.3V Device |
| Digital ground voltage | V_{SS} | 0 | | V | |
| Digital core supply voltage | V_{DDC} | 2.3 | 2.7 | V | |
| System Clock Frequency ¹⁾ | f_{SYS} | 69 | 81 | MHz | |
| Ambient temperature | T_A | -40 | 150 | °C | SAL-XC866... |

¹⁾ f_{SYS} is the PLL output clock. During normal operating mode, CPU clock is $f_{SYS} / 3$. Please refer to [Figure 24](#) for detailed description.

4.2 DC Parameters
4.2.1 Input/Output Characteristics
Table 33 Input/Output Characteristics (Operating Conditions apply)

| Parameter | Symbol | Limit Values | | Unit | Test Conditions |
|--|---------------|-----------------------|----------------------|------|-------------------|
| | | min. | max. | | |
| $V_{DDP} = 5V$ Range | | | | | |
| Output low voltage | V_{OL} CC | – | 1.0 | V | $I_{OL} = 15$ mA |
| | | – | 0.4 | V | $I_{OL} = 5$ mA |
| Output high voltage | V_{OH} CC | $V_{DDP} - 1.0$ | – | V | $I_{OH} = -15$ mA |
| | | $V_{DDP} - 0.4$ | – | V | $I_{OH} = -5$ mA |
| Input low voltage on port pins (all except P0.0 & P0.1) | V_{ILP} SR | – | $0.3 \times V_{DDP}$ | V | CMOS Mode |
| Input low voltage on P0.0 & P0.1 | V_{ILP0} SR | -0.2 | $0.3 \times V_{DDP}$ | V | CMOS Mode |
| Input low voltage on RESET pin | V_{ILR} SR | – | $0.3 \times V_{DDP}$ | V | CMOS Mode |
| Input low voltage on TMS pin | V_{ILT} SR | – | $0.3 \times V_{DDP}$ | V | CMOS Mode |
| Input high voltage on port pins (all except P0.0 & P0.1) | V_{IHP} SR | $0.7 \times V_{DDP}$ | – | V | CMOS Mode |
| Input high voltage on P0.0 & P0.1 | V_{IHP0} SR | $0.7 \times V_{DDP}$ | V_{DDP} | V | CMOS Mode |
| Input high voltage on RESET pin | V_{IHR} SR | $0.7 \times V_{DDP}$ | – | V | CMOS Mode |
| Input high voltage on TMS pin | V_{IHT} SR | $0.75 \times V_{DDP}$ | – | V | CMOS Mode |
| Input Hysteresis ¹⁾ on Port Pins | HYS CC | $0.08 \times V_{DDP}$ | – | V | CMOS Mode |
| Input Hysteresis ¹⁾ on XTAL1 | $HYSXCC$ | $0.07 \times V_{DDC}$ | – | V | |

Electrical Parameters
Table 33 Input/Output Characteristics (Operating Conditions apply)

| Parameter | Symbol | | Limit Values | | Unit | Test Conditions |
|--|-------------------|----|----------------------|----------------------|---------|--|
| | | | min. | max. | | |
| Input low voltage at XTAL1 | V_{ILX} | SR | $V_{SS} - 0.5$ | $0.3 \times V_{DDC}$ | V | |
| Input high voltage at XTAL1 | V_{IHx} | SR | $0.7 \times V_{DDC}$ | $V_{DDC} + 0.5$ | V | |
| Pull-up current | I_{PU} | SR | - | -10 | μA | $V_{IH,min}$ |
| | | | -150 | - | μA | $V_{IL,max}$ |
| Pull-down current | I_{PD} | SR | - | 10 | μA | $V_{IL,max}$ |
| | | | 150 | - | μA | $V_{IH,min}$ |
| Input leakage current ²⁾ | I_{OZ1} | CC | -2 | 2 | μA | $0 < V_{IN} < V_{DDP}$, $T_A \leq 150^\circ C$ |
| Input current at XTAL1 | I_{ILX} | CC | -10 | 10 | μA | |
| Overload current on any pin | I_{OV} | SR | -5 | 5 | mA | ³⁾ |
| Absolute sum of overload currents | $\Sigma I_{OV} $ | SR | - | 25 | mA | ³⁾ |
| Voltage on any pin during V_{DDP} power off | V_{PO} | SR | - | 0.3 | V | ⁴⁾ |
| Maximum current per pin (excluding V_{DDP} and V_{SS}) | I_M | SR | - | 15 | mA | |
| Maximum current for all pins (excluding V_{DDP} and V_{SS}) | $\Sigma I_M $ | SR | - | 60 | mA | |
| Maximum current into V_{DDP} | I_{MVDDP} | SR | - | 80 | mA | ³⁾ |
| Maximum current out of V_{SS} | I_{MVSS} | SR | - | 80 | mA | ³⁾ |

Electrical Parameters
Table 33 Input/Output Characteristics (Operating Conditions apply)

| Parameter | Symbol | Limit Values | | Unit | Test Conditions |
|--|---------------|-----------------------|----------------------|------|---------------------------|
| | | min. | max. | | |
| $V_{DDP} = 3.3V$ Range | | | | | |
| Output low voltage | V_{OL} CC | – | 1.0 | V | $I_{OL} = 8\text{ mA}$ |
| | | – | 0.4 | V | $I_{OL} = 2.5\text{ mA}$ |
| Output high voltage | V_{OH} CC | $V_{DDP} - 1.0$ | – | V | $I_{OH} = -8\text{ mA}$ |
| | | $V_{DDP} - 0.4$ | – | V | $I_{OH} = -2.5\text{ mA}$ |
| Input low voltage on port pins (all except P0.0 & P0.1) | V_{ILP} SR | – | $0.3 \times V_{DDP}$ | V | CMOS Mode |
| Input low voltage on P0.0 & P0.1 | V_{ILP0} SR | -0.2 | $0.3 \times V_{DDP}$ | V | CMOS Mode |
| Input low voltage on RESET pin | V_{ILR} SR | – | $0.3 \times V_{DDP}$ | V | CMOS Mode |
| Input low voltage on TMS pin | V_{ILT} SR | – | $0.3 \times V_{DDP}$ | V | CMOS Mode |
| Input high voltage on port pins (all except P0.0 & P0.1) | V_{IHP} SR | $0.7 \times V_{DDP}$ | – | V | CMOS Mode |
| Input high voltage on P0.0 & P0.1 | V_{IHP0} SR | $0.7 \times V_{DDP}$ | V_{DDP} | V | CMOS Mode |
| Input high voltage on RESET pin | V_{IHR} SR | $0.7 \times V_{DDP}$ | – | V | CMOS Mode |
| Input high voltage on TMS pin | V_{IHT} SR | $0.75 \times V_{DDP}$ | – | V | CMOS Mode |
| Input Hysteresis ¹⁾ on Port Pins | <i>HYS</i> CC | $0.03 \times V_{DDP}$ | – | V | CMOS Mode |
| Input Hysteresis ¹⁾ on XTAL1 | <i>HYSXCC</i> | $0.07 \times V_{DDC}$ | – | V | |
| Input low voltage at XTAL1 | V_{ILX} SR | $V_{SS} - 0.5$ | $0.3 \times V_{DDC}$ | V | |
| Input high voltage at XTAL1 | V_{IHx} SR | $0.7 \times V_{DDC}$ | $V_{DDC} + 0.5$ | V | |

Electrical Parameters
Table 33 Input/Output Characteristics (Operating Conditions apply)

| Parameter | Symbol | Limit Values | | Unit | Test Conditions |
|--|---------------------|--------------|------|---------------|--|
| | | min. | max. | | |
| Pull-up current | I_{PU} SR | - | -5 | μA | $V_{IH,min}$ |
| | | -50 | - | μA | $V_{IL,max}$ |
| Pull-down current | I_{PD} SR | - | 5 | μA | $V_{IL,max}$ |
| | | 50 | - | μA | $V_{IH,min}$ |
| Input leakage current ²⁾ | I_{OZ1} CC | -2 | 2 | μA | $0 < V_{IN} < V_{DDP}$, $T_A \leq 150^\circ\text{C}$ |
| Input current at XTAL1 | I_{ILX} CC | - 10 | 10 | μA | |
| Overload current on any pin | I_{OV} SR | -5 | 5 | mA | ³⁾ |
| Absolute sum of overload currents | $\Sigma I_{OV} $ SR | - | 25 | mA | ³⁾ |
| Voltage on any pin during V_{DDP} power off | V_{PO} SR | - | 0.3 | V | ⁴⁾ |
| Maximum current per pin (excluding V_{DDP} and V_{SS}) | I_M SR | - | 15 | mA | |
| Maximum current for all pins (excluding V_{DDP} and V_{SS}) | $\Sigma I_M $ SR | - | 60 | mA | |
| Maximum current into V_{DDP} | I_{MVDDP} SR | - | 80 | mA | |
| Maximum current out of V_{SS} | I_{MVSS} SR | - | 80 | mA | |

¹⁾ Not subjected to production test, verified by design/characterization. Hysteresis is implemented to avoid meta stable states and switching due to internal ground bounce. It cannot be guaranteed that it suppresses switching due to external system noise.

²⁾ An additional error current (I_{INJ}) will flow if an overload current flows through an adjacent pin. TMS pin and RESET pin have internal pull devices and are not included in the input leakage current characteristic.

³⁾ Not subjected to production test, verified by design/characterization.

⁴⁾ Not subjected to production test, verified by design/characterization. However, for applications with strict low power-down current requirements, it is mandatory that no active voltage source is supplied at any GPIO pin when V_{DDP} is powered off.

4.2.2 Supply Threshold Characteristics

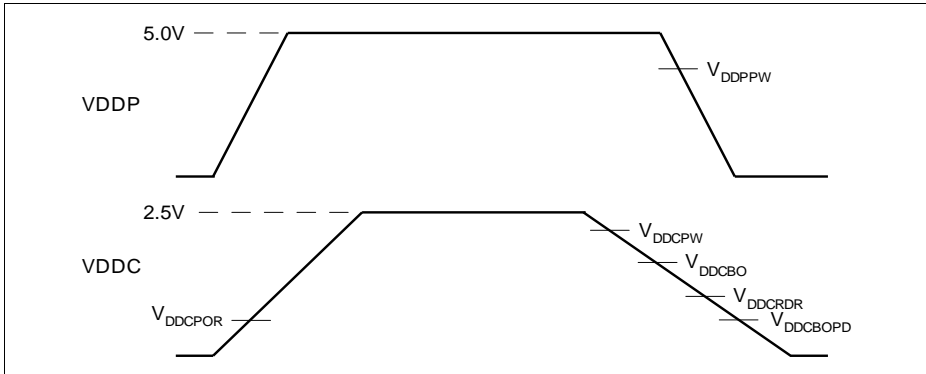


Figure 35 Supply Threshold Parameters

Table 34 Supply Threshold Parameters (Operating Conditions apply)

| Parameters | Symbol | | Limit Values | | | Unit |
|---|---------------|----|--------------|------|------|------|
| | | | min. | typ. | max. | |
| V_{DDC} prewarning voltage ¹⁾ | V_{DDCPW} | CC | 2.2 | 2.3 | 2.4 | V |
| V_{DDC} brownout voltage in active mode ¹⁾ | V_{DDCBO} | CC | 2.0 | 2.1 | 2.2 | V |
| RAM data retention voltage | V_{DDCRDR} | CC | 0.9 | 1.0 | 1.1 | V |
| V_{DDC} brownout voltage in power-down mode ²⁾ | $V_{DDCBOPD}$ | CC | 1.3 | 1.5 | 1.7 | V |
| V_{DDP} prewarning voltage ³⁾ | V_{DDPPW} | CC | 3.3 | 4.0 | 4.65 | V |
| Power-on reset voltage ²⁾⁴⁾ | V_{DDCPOR} | CC | 1.3 | 1.5 | 1.7 | V |

1) Detection is disabled in power-down mode.

2) Detection is enabled in both active and power-down mode.

3) Detection is enabled for external power supply of 5.0V
Detection must be disabled for external power supply of 3.3V.

4) The reset of EVR is extended by 300 μ s typically after the VDDC reaches the power-on reset voltage.

4.2.3 ADC Characteristics

The values in the table below are given for an analog power supply between 4.5 V to 5.5 V. The ADC can be used with an analog power supply down to 3 V. But in this case, the analog parameters may show a reduced performance. All ground pins (V_{SS}) must be externally connected to one single star point in the system. The voltage difference between the ground pins must not exceed 200mV.

Table 35 ADC Characteristics (Operating Conditions apply; $V_{DDP} = 5V$ Range)

| Parameter | Symbol | Limit Values | | | Unit | Test Conditions/ Remarks |
|--|---------------------|-------------------------------------|-----------|----------------------|---------|--|
| | | min. | typ . | max. | | |
| Analog reference voltage | V_{AREF} SR | $V_{AGND} + 1$ | V_{DDP} | $V_{DDP} + 0.05$ | V | 1) |
| Analog reference ground | V_{AGND} SR | $V_{SS} - 0.05$ | V_{SS} | $V_{AREF} - 1$ | V | 1) |
| Analog input voltage range | V_{AIN} SR | V_{AGND} | – | V_{AREF} | V | |
| ADC clocks | f_{ADC} | – | 20 | 40 | MHz | module clock ¹⁾ |
| | f_{ADCI} | – | – | 10 | MHz | internal analog clock ¹⁾ See Figure 32 |
| Sample time | t_S CC | $(2 + INPCR0.STC) \times t_{ADCI}$ | | | μs | 1) |
| Conversion time | t_C CC | See Section 4.2.3.1 | | | μs | 1) |
| Total unadjusted error | TUE CC | – | – | 1 | LSB | 8-bit conversion. ²⁾ |
| | | – | – | 2 | LSB | 10-bit conversion. ²⁾ |
| Differential Nonlinearity | $ EA_{DNL} $ CC | – | 1 | – | LSB | 10-bit conversion ¹⁾ |
| Integral Nonlinearity | $ EA_{INL} $ CC | – | 1 | – | LSB | 10-bit conversion ¹⁾ |
| Offset | $ EA_{OFF} $ CC | – | 1 | – | LSB | 10-bit conversion ¹⁾ |
| Gain | $ EA_{GAIN} $ CC | – | 1 | – | LSB | 10-bit conversion ¹⁾ |
| Overload current coupling factor for analog inputs | K_{OVA} CC | – | – | 1.0×10^{-4} | – | $I_{OV} > 0^{1)3)}$ |
| | | – | – | 1.5×10^{-3} | – | $I_{OV} < 0^{1)3)}$ |

Electrical Parameters
Table 35 ADC Characteristics (Operating Conditions apply; $V_{DDP} = 5V$ Range)

| Parameter | Symbol | Limit Values | | | Unit | Test Conditions/ Remarks |
|---|--------------------|--------------|-------|----------------------|------------|-----------------------------|
| | | min. | typ . | max. | | |
| Overload current coupling factor for digital I/O pins | K_{OVD} CC | – | – | 5.0×10^{-3} | – | $I_{OV} > 0^{1)3)}$ |
| | | – | – | 1.0×10^{-2} | – | $I_{OV} < 0^{1)3)}$ |
| Switched capacitance at the reference voltage input | C_{AREFSW} CC | – | 10 | 20 | pF | 1)4) |
| Switched capacitance at the analog voltage inputs | C_{AINSW} CC | – | 5 | 7 | pF | 1)5) |
| Input resistance of the reference input | R_{AREF} CC | – | 1 | 2 | k Ω | 1) |
| Input resistance of the selected analog channel | R_{AIN} CC | – | 1 | 1.5 | k Ω | 1) |

1) Not subject to production test, verified by design/characterization.

2) TUE is tested at $V_{AREF} = 5.0$ V, $V_{AGND} = 0$ V, $V_{DDP} = 5.0$ V.

3) An overload current (I_{OV}) through a pin injects a certain error current (I_{INJ}) into the adjacent pins. This error current adds to the respective pin's leakage current (I_{OZ}). The amount of error current depends on the overload current and is defined by the overload coupling factor K_{OV} . The polarity of the injected error current is inverse compared to the polarity of the overload current that produces it. The total current through a pin is $|I_{TOT}| = |I_{OZ}| + (|I_{OV}| \times K_{OV})$. The additional error current may distort the input voltage on analog inputs.

4) This represents an equivalent switched capacitance. This capacitance is not switched to the reference voltage at once. Instead of this, smaller capacitances are successively switched to the reference voltage.

5) The sampling capacity of the conversion C-Network is pre-charged to $V_{AREF}/2$ before connecting the input to the C-Network. Because of the parasitic elements, the voltage measured at ANx is lower than $V_{AREF}/2$.

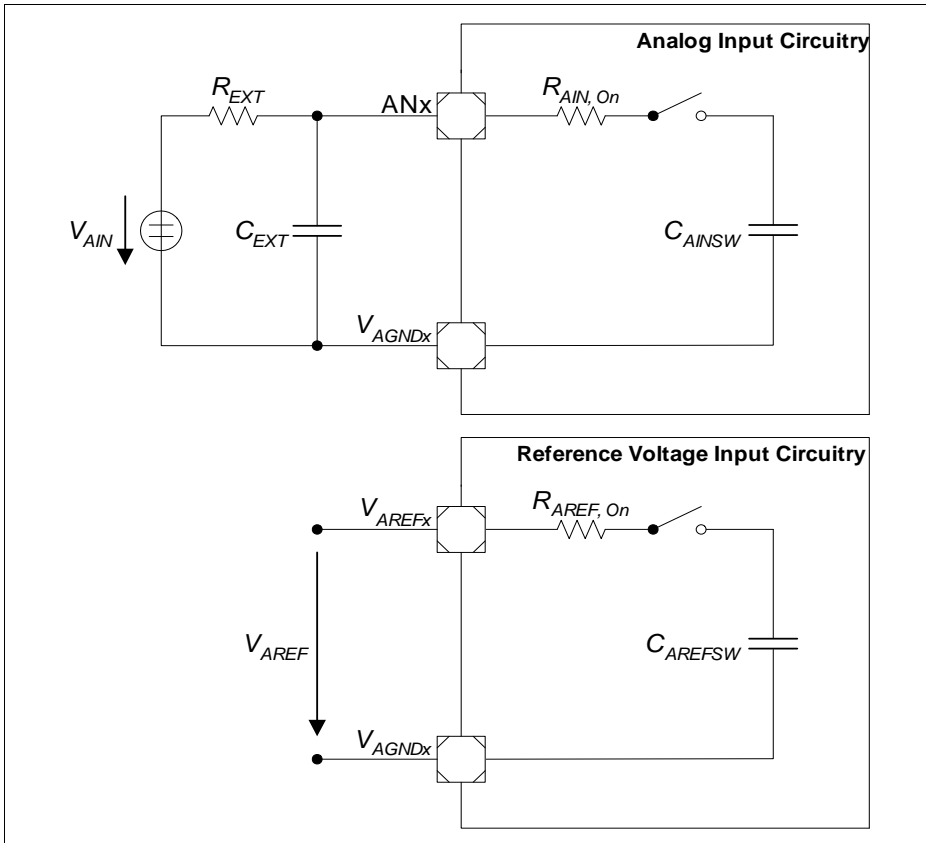


Figure 36 ADC Input Circuits

4.2.3.1 ADC Conversion Timing

Conversion time, $t_C = t_{ADC} \times (1 + r \times (3 + n + STC))$, where

$r = CTC + 2$ for $CTC = 00_B, 01_B$ or 10_B ,

$r = 32$ for $CTC = 11_B$,

$CTC =$ Conversion Time Control (GLOBCTR.CTC),

$STC =$ Sample Time Control (INPCR0.STC),

$n = 8$ or 10 (for 8-bit and 10-bit conversion respectively),

$t_{ADC} = 1 / f_{ADC}$

4.2.4 Power Supply Current

Table 36 Power Supply Current Parameters (Operating Conditions apply)

| Parameter | Symbol | Limit Values | | Unit | Test Condition |
|------------------------------------|-----------|--------------------|--------------------|------|----------------|
| | | typ. ¹⁾ | max. ²⁾ | | |
| Active Mode | I_{DDP} | 22.6 | 25.1 | mA | ³⁾ |
| Idle Mode | I_{DDP} | 17.2 | 19.7 | mA | ⁴⁾ |
| Active Mode with slow-down enabled | I_{DDP} | 7.2 | 9.3 | mA | ⁵⁾ |
| Idle Mode with slow-down enabled | I_{DDP} | 7.1 | 8 | mA | ⁶⁾ |

¹⁾ The typical I_{DDP} values are periodically measured at $T_A = +25\text{ °C}$ and $V_{DDP} = 5.0\text{ V}$.

²⁾ The maximum I_{DDP} values are measured under worst case conditions ($T_A = +150\text{ °C}$ and $V_{DDP} = 5.5\text{ V}$).

³⁾ I_{DDP} (active mode) is measured with: CPU clock and input clock to all peripherals running at 25 MHz (set by on-chip oscillator of 10 MHz and NDIV in PLL_CON to 0001_B), $\overline{\text{RESET}} = V_{DDP}$.

⁴⁾ I_{DDP} (idle mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 25 MHz, $\overline{\text{RESET}} = V_{DDP}$.

⁵⁾ I_{DDP} (active mode with slow-down mode) is measured with: CPU clock and input clock to all peripherals running at 781 KHz by setting CLKREL in CMCON to 0101_B, $\overline{\text{RESET}} = V_{DDP}$.

⁶⁾ I_{DDP} (idle mode with slow-down mode) is measured with: CPU clock disabled, watchdog timer disabled, input clock to all peripherals enabled and running at 781 MHz by setting CLKREL in CMCON to 0101_B, $\overline{\text{RESET}} = V_{DDP}$.

Electrical Parameters
Table 37 Power Down Current (Operating Conditions apply)

| Parameter | Symbol | Limit Values | | Unit | Test Condition |
|-------------------------------|-----------|--------------------|--------------------|---------------|---|
| | | typ. ¹⁾ | max. ²⁾ | | |
| Power-Down Mode ³⁾ | I_{PDP} | 1 | 10 | μA | $T_A = + 25\text{ }^\circ\text{C}.$ ⁴⁾ |
| | | - | 30 | μA | $T_A = + 85\text{ }^\circ\text{C}.$ ⁴⁾⁵⁾ |

1) The typical I_{PDP} values are measured at $V_{DDP} = 5.0\text{ V}$.

2) The maximum I_{PDP} values are measured at $V_{DDP} = 5.5\text{ V}$.

3) I_{PDP} (power-down mode) has a maximum value of $500\text{ }\mu\text{A}$ at $T_A = + 150\text{ }^\circ\text{C}$.

4) I_{PDP} (power-down mode) is measured with: $\overline{\text{RESET}} = V_{DDP}$, $V_{AGND} = V_{SS}$, $\text{RXD}/\text{INT0} = V_{DDP}$; rest of the ports are programmed to be input with either internal pull devices enabled or driven externally to ensure no floating inputs.

5) Not subject to production test, verified by design/characterization.

4.3 AC Parameters

4.3.1 Testing Waveforms

The testing waveforms for rise/fall time, output delay and output high impedance are shown in **Figure 37**, **Figure 38** and **Figure 39**.

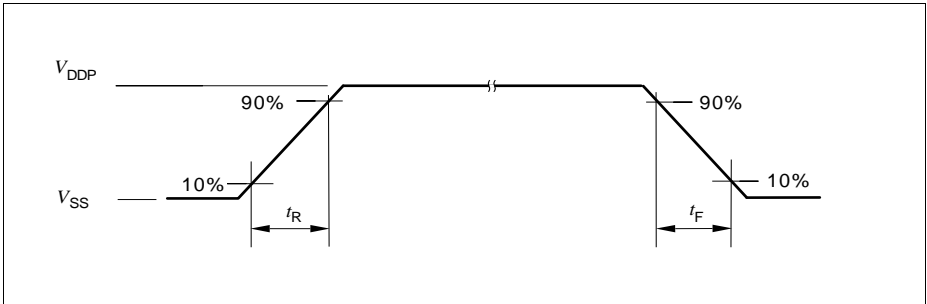


Figure 37 Rise/Fall Time Parameters

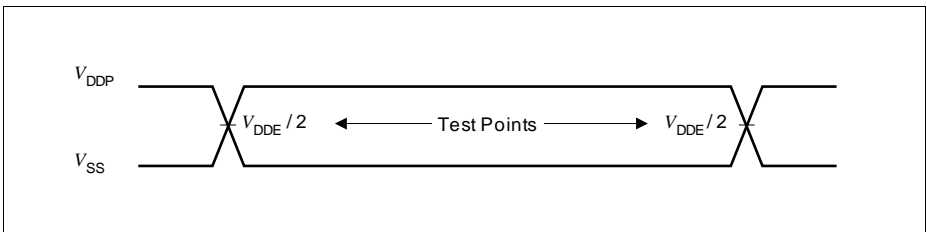


Figure 38 Testing Waveform, Output Delay

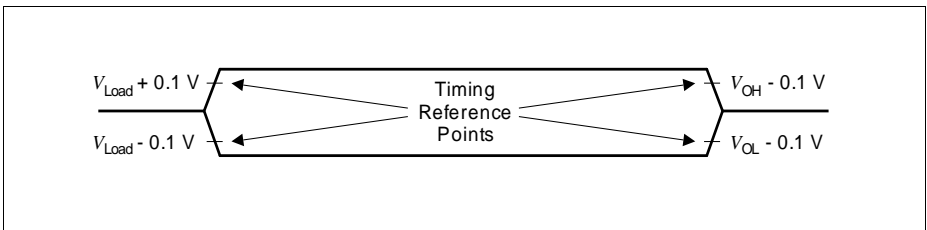


Figure 39 Testing Waveform, Output High Impedance

4.3.2 Output Rise/Fall Times

Table 38 Output Rise/Fall Times Parameters (Operating Conditions apply)

| Parameter | Symbol | Limit Values | | Unit | Test Conditions |
|--|------------|--------------|------|------|----------------------|
| | | min. | max. | | |
| $V_{DDP} = 5V$ Range | | | | | |
| Rise/fall times ^{1) 2)} | t_R, t_F | – | 10 | ns | 20 pF. ³⁾ |
| $V_{DDP} = 3.3V$ Range | | | | | |
| Rise/fall times ^{1) 2)} | t_R, t_F | – | 10 | ns | 20 pF. ⁴⁾ |

- 1) Rise/Fall time measurements are taken with 10% - 90% of the pad supply.
- 2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.
- 3) Additional rise/fall time valid for $C_L = 20pF - 100pF @ 0.125 ns/pF$.
- 4) Additional rise/fall time valid for $C_L = 20pF - 100pF @ 0.225 ns/pF$.

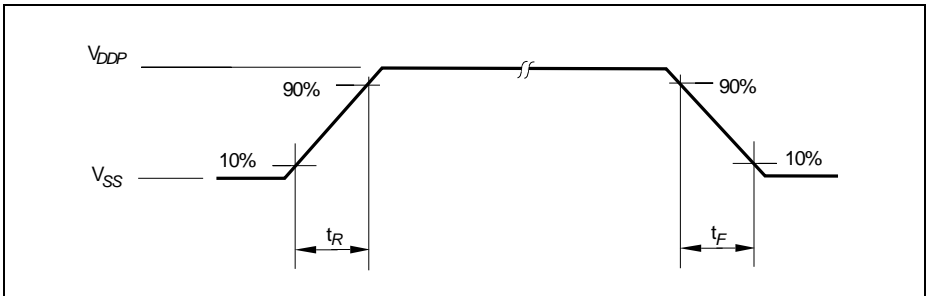


Figure 40 Rise/Fall Times Parameters

4.3.3 Power-on Reset and PLL Timing

Table 39 Power-On Reset and PLL Timing (Operating Conditions apply)

| Parameter | Symbol | Limit Values | | | Unit | Test Conditions |
|----------------------------------|----------------|--------------|------|------|---------|---|
| | | min. | typ. | max. | | |
| Pad operating voltage | V_{PAD} CC | 2.3 | – | – | V | 1) |
| On-Chip Oscillator start-up time | t_{OSCST} CC | – | – | 500 | ns | 1) |
| Flash initialization time | t_{FINIT} CC | – | 160 | – | μ s | 1) |
| RESET hold time | t_{RST} SR | – | 500 | – | μ s | V_{DDP} rise time (10% – 90%) $\leq 500\mu$ s ¹⁾²⁾ |
| PLL lock-in in time | t_{LOCK} CC | – | – | 200 | μ s | 1) |
| PLL accumulated jitter | D_P | – | – | 0.7 | ns | 1) |

1) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

2) RESET signal has to be active (low) until V_{DDC} has reached 90% of its maximum value (typ. 2.5V).

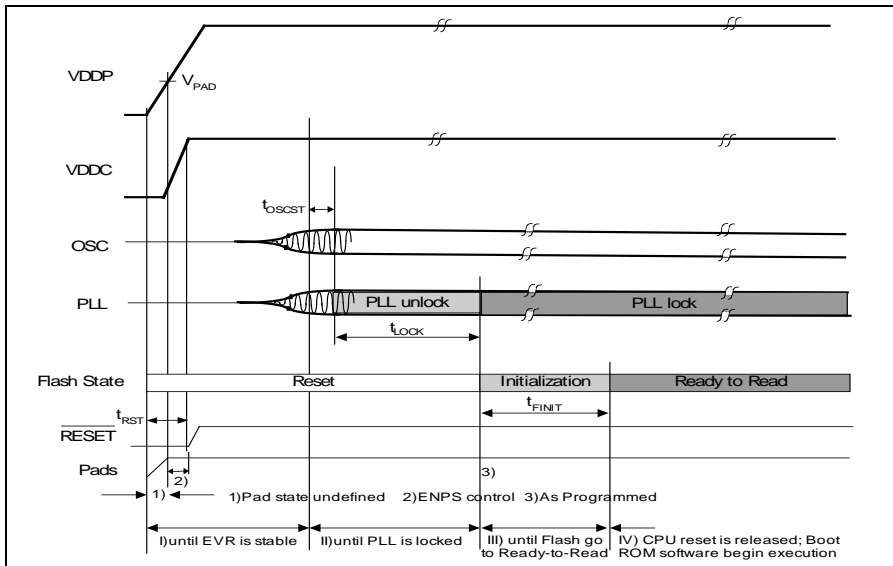


Figure 41 Power-on Reset Timing

4.3.4 On-Chip Oscillator Characteristics
Table 40 On-chip Oscillator Characteristics (Operating Conditions apply)

| Parameter | Symbol | Limit Values | | | Unit | Test Conditions |
|--------------------------------|--------------------|--------------|------|-------|------|---|
| | | min. | typ. | max. | | |
| Nominal frequency | f_{NOM} CC | 9.75 | 10 | 10.25 | MHz | under nominal conditions ¹⁾ |
| Long term frequency deviation | Δf_{LT} CC | 0 | – | 6.0 | % | with respect to f_{NOM} , over lifetime and temperature (125°C to 150°C), for one device after trimming |
| | | -5.0 | – | 5.0 | % | with respect to f_{NOM} , over lifetime and temperature (-10°C to 125°C), for one device after trimming |
| | | -6.0 | – | 0 | % | with respect to f_{NOM} , over lifetime and temperature (-40°C to -10°C), for one device after trimming |
| Short term frequency deviation | Δf_{ST} CC | -1.0 | – | 1.0 | % | within one LIN message (<10 ms 100 ms) |

¹⁾ Nominal condition: $V_{DDC} = 2.5$ V, $T_A = +25^\circ\text{C}$.

4.3.5 JTAG Timing

Table 41 TCK Clock Timing (Operating Conditions apply; $C_L = 50$ pF)

| Parameter | Symbol | Limits | | Unit |
|-----------------------------------|--------------|--------|-----|------|
| | | min | max | |
| TCK clock period ¹⁾ | t_{TCK} SR | 50 | – | ns |
| TCK high time ¹⁾ | t_1 SR | 20 | – | ns |
| TCK low time ¹⁾ | t_2 SR | 20 | – | ns |
| TCK clock rise time ¹⁾ | t_3 SR | – | 4 | ns |
| TCK clock fall time ¹⁾ | t_4 SR | – | 4 | ns |

¹⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

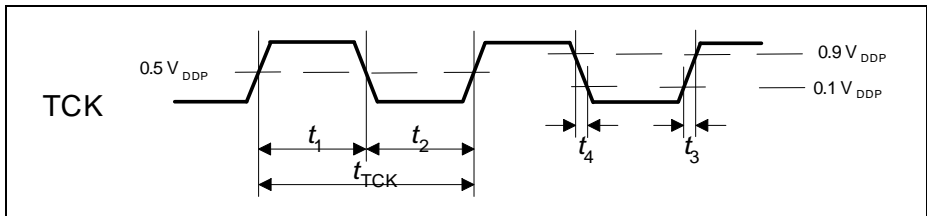









Figure 42 TCK Clock Timing

Table 42 JTAG Timing (Operating Conditions apply; $C_L = 50$ pF)

| Parameter | Symbol | | Limits | | Unit |
|---|--------|----|--------|-----|------|
| | | | min | max | |
| TMS setup to TCK ¹⁾  | t_1 | SR | 8.0 | – | ns |
| TMS hold to TCK ¹⁾  | t_2 | SR | 5.0 | – | ns |
| TDI setup to TCK ¹⁾  | t_1 | SR | 11.0 | – | ns |
| TDI hold to TCK ¹⁾  | t_2 | SR | 6.0 | – | ns |
| TDO valid output from TCK ¹⁾  | t_3 | CC | – | 23 | ns |
| TDO high impedance to valid output from TCK ¹⁾  | t_4 | CC | – | 26 | ns |
| TDO valid output to high impedance from TCK ¹⁾  | t_5 | CC | – | 18 | ns |

¹⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

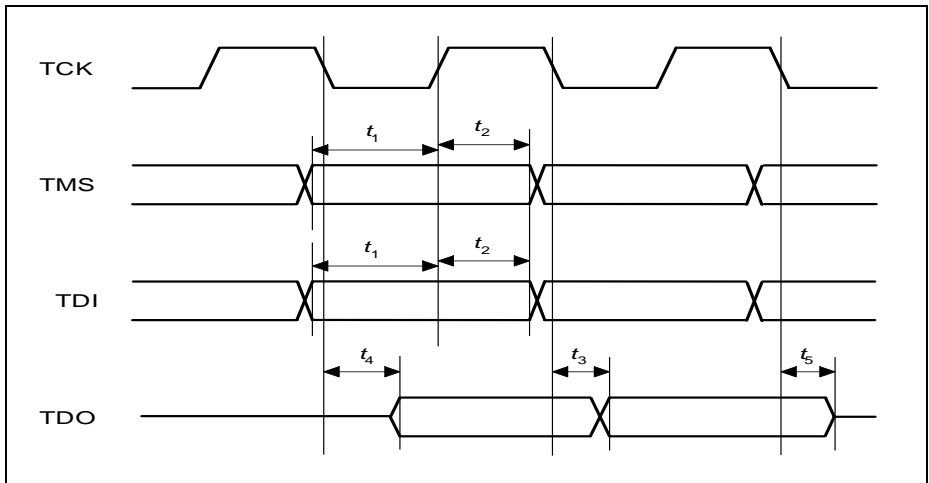


Figure 43 JTAG Timing

4.3.6 SSC Master Mode Timing

Table 43 SSC Master Mode Timing (Operating Conditions apply; $C_L = 50$ pF)

| Parameter | Symbol | | Limit Values | | Unit |
|------------------------------------|--------|----|---------------------------------|------|------|
| | | | min. | max. | |
| SCLK clock period ¹⁾ | t_0 | CC | $2 \cdot T_{SSC}$ ²⁾ | – | ns |
| MISR delay from SCLK ¹⁾ | t_1 | CC | 0 | 8 | ns |
| MRST setup to SCLK ¹⁾ | t_2 | SR | 22 | – | ns |
| MRST hold from SCLK ¹⁾ | t_3 | SR | 0 | – | ns |

¹⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

²⁾ $T_{SSCmin} = T_{CPU} = 1/f_{CPU}$. When $f_{CPU} = 25$ MHz, $t_0 = 80$ ns. T_{CPU} is the CPU clock period.

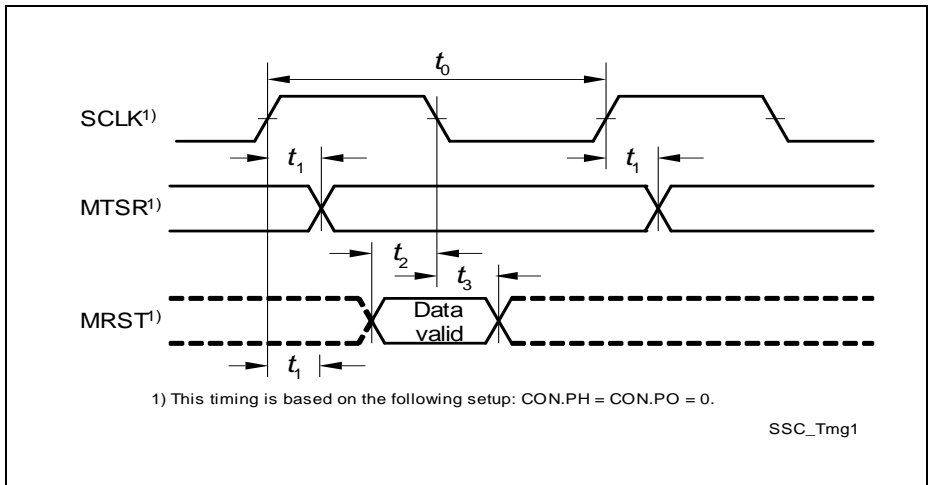


Figure 44 SSC Master Mode Timing

5 Package and Reliability

5.1 Package Parameters (PG-TSSOP-38)

Table 44 provides the thermal characteristics of the package.

Table 44 Thermal Characteristics of the Package

| Parameter | Symbol | Limit Values | | Unit | Notes |
|--|--------------|--------------|------|------|-------|
| | | Min. | Max. | | |
| Thermal resistance junction case ¹⁾²⁾ | R_{TJC} CC | – | 15.7 | K/W | – |
| Thermal resistance junction lead ¹⁾²⁾ | R_{TJL} CC | – | 39.2 | K/W | – |

¹⁾ The thermal resistances between the case and the ambient (R_{TCA}), the lead and the ambient (R_{TLA}) are to be combined with the thermal resistances between the junction and the case (R_{TJC}), the junction and the lead (R_{TJL}) given above, in order to calculate the total thermal resistance between the junction and the ambient (R_{TJA}). The thermal resistances between the case and the ambient (R_{TCA}), the lead and the ambient (R_{TLA}) depend on the external system (PCB, case) characteristics, and are under user responsibility.

The junction temperature can be calculated using the following equation: $T_J = T_A + R_{TJA} \times P_D$, where the R_{TJA} is the total thermal resistance between the junction and the ambient. This total junction ambient resistance R_{TJA} can be obtained from the upper four partial thermal resistances, by

- a) simply adding only the two thermal resistances (junction lead and lead ambient), or
- b) by taking all four resistances into account, depending on the precision needed.

²⁾ Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

5.2 Package Outline

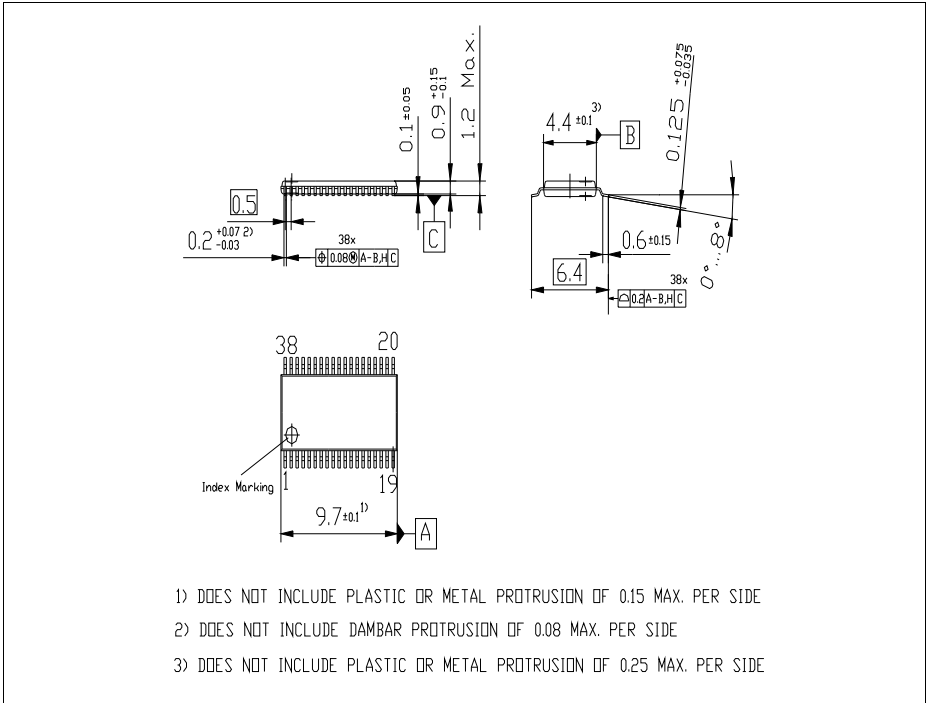


Figure 45 PG-TSSOP-38-4 Package Outline

5.3 Quality Declaration

Table 45 shows the characteristics of the quality parameters in the SAL-XC866.

Table 45 Quality Parameters

| Parameter | Symbol | Limit Values | | | Unit | Notes |
|---|------------|--------------|------|--------|------------------|---------------------------------|
| | | Min. | Typ. | Max. | | |
| Operation Lifetime when the device is used at the four stated T_A ¹⁾²⁾ | t_{OP} | – | – | 500 | hours | $T_A = 150^\circ\text{C}$ |
| | | – | – | 1000 | hours | $T_A = 140^\circ\text{C}$ |
| | | – | – | 2000 | hours | $T_A = 125^\circ\text{C}$ |
| | | – | – | 10000 | hours | $T_A = 85^\circ\text{C}$ |
| | | – | – | 1500 | hours | $T_A = -40^\circ\text{C}$ |
| Operation Lifetime when the device is used at the two stated T_A ¹⁾²⁾ | t_{OP2} | – | – | 18000 | hours | $T_A = 108^\circ\text{C}$ |
| | | – | – | 130000 | hours | $T_A = 27^\circ\text{C}$ |
| Weighted Average Temperature ²⁾³⁾ | T_{WA} | – | 107 | – | $^\circ\text{C}$ | for 15000 hours |
| ESD susceptibility according to Human Body Model (HBM) for all pins (except V_{DDC}) ²⁾ | V_{HBM} | – | – | 2000 | V | Conforming to EIA/JESD22-A114-B |
| ESD susceptibility according to Human Body Model (HBM) for V_{DDC} ²⁾ | V_{HBMC} | – | – | 600 | V | Conforming to EIA/JESD22-A114-B |
| ESD susceptibility according to Charged Device Model (CDM) pins ²⁾ | V_{CDM} | – | – | 750 | V | Conforming to JESD22-C101-C |

1) This lifetime refers only to the time when the device is powered-on.

2) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

3) This parameter is derived based on the Arrhenius model.

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